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RENESAS TECHNICAL UPDATE

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Product Category	MPU/MCU		Document No.	TN-RL*-A006A/E	Rev.	1.00
Title	Correction for Incorrect Description Notice RL78/G12 Descriptions in the Hardware User's Manual Rev. 1.10 Changed		Information Category	Technical Notification		
Applicable Product	RL78/G12 R5F102xxx, R5F103xxx	Lot No. All lots	Reference Document	RL78/G12 User's Manual: Hardware Rev.1.10 R01UH0200EJ0110 (Sep. 2012)		

This document describes misstatements found in the RL78/G12 User's Manual: Hardware Rev.1.10 (R01UH0200EJ0110).

Corrections

Applicable Item	Applicable Page	Contents
1.4 Pin Configuration (Top View) 1.4.3 30-pin products	Page 8	Incorrect descriptions revised
Internal data memory space / Control registers / General-purpose registers	Pages 38, 48 and 50	Incorrect descriptions revised
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6.7.3 Operation as frequency divider	Page 239	Incorrect descriptions revised
11. 6. 3 SNOOZE mode function	Pages 467	Specifications changed
17.2.2 STOP mode	Pages 663 and 664	Incorrect descriptions revised
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28.5.2 Serial interface IICA	Page 807	Specifications changed
28.6.1 A/D converter characteristics	Pages 808 to 810	Specifications extended
28.6.2 Temperature Sensor/Internal Reference Voltage Characteristics	Page 811	Specifications changed
28.6.3 POR circuit characteristics	Page 811	Specifications changed
Power supply voltage rising slope characteristics	-	Specifications added
28.7 Data Memory STOP Mode Low Supply Voltage Data Retention Characteristics	Page 814	Specifications extended
Chapter 29 ELECTRICAL SPECIFICATIONS (G: T_A = −40 to +105°C) (TARGET VALUES)	-	Specifications added

Document Improvement

The above corrections will be made for the next revision of the User's Manual: Hardware.

Corrections in the User's Manual: Hardware

No.	Corrections and Applicable Items			Pages in this document for corrections
		Document No. English	R01UH0200EJ0110	
1	1.4 Pin Configuration (Top View) 1.4.3 30-pin products		Page 8	Page 3
2	Internal data memory space / Control registers / General-purpose registers		Pages 38, 48 and 50	Page 4
3	4.3 Registers Controlling Port Function Figure 4-40. Format of Peripheral I/O Redirection Register (PIOR)		Page 134	Pages 5 and 6
4	6.7.3 Operation as frequency divider		Page 239	Page 7
5	11. 6. 3 SNOOZE mode function		Pages 467	Pages 8 and 9
6	17.2.2 STOP mode		Pages 663 and 664	Page 10
7	17.2.3 SNOOZE mode		Page 666	Page 11
8	Figure 23-3 Format of Option Byte (000C2H)		Page 721	Page 12
9	28.3.1 Pin characteristics		Pages 775 and 776	Page 13
10	28.3.2 Supply current characteristics		Pages 779 to 783	Page 13
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17	Power supply voltage rising slope characteristics		-	Page 14
18	28.7 Data Memory STOP Mode Low Supply Voltage Data Retention Characteristics		Page 814	Page 14
19	Chapter 29 ELECTRICAL SPECIFICATIONS (G: T_A = −40 to +105°C) (TARGET VALUES)		-	Page 14

Incorrect: Bold with underline; Correct: Gray hatched

Revision History

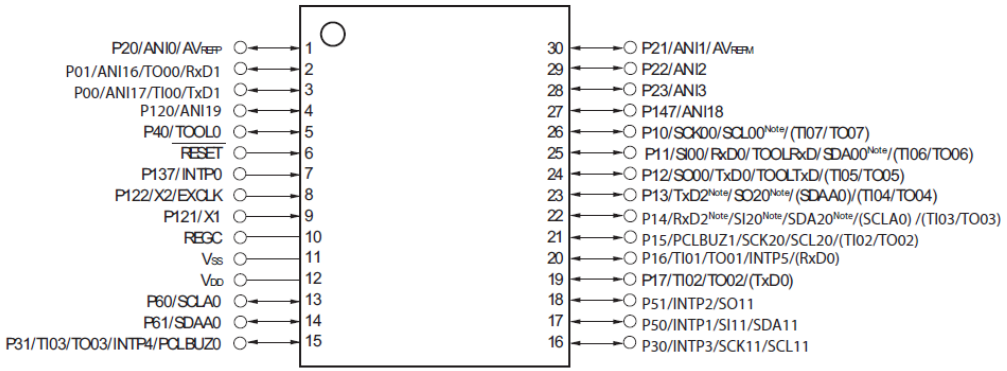
RL78/G12 User's Manual: Hardware Rev.1.10 Correction for Incorrect Description Notice

Document Number	Date	Description
TN-RL*-A006A/E	Aug. 1, 2013	First edition issued No.1 to 19 in corrections (This notice)

1. **1.4 Pin Configuration (Top View)**
   1.4.3 30-pin products

Incorrect:

- 30-pin plastic SSOP (7.62 mm (300))



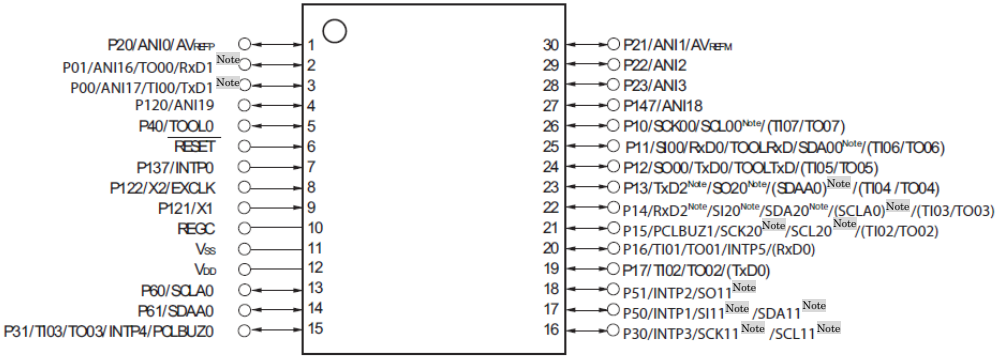
Note Provided in the R5F102 products.

Caution Connect the REGC pin to Vss via capacitor (0.47 to 1 μF).

Remarks 1. For pin identification, see **1.5 Pin Identification**.
2. Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR).

Correct:

- 30-pin plastic SSOP (7.62 mm (300))



Note Provided only in R5F102 products

Caution Connect the REGC pin to Vss via capacitor (0.47 to 1 μF).

Remarks 1. For pin identification, see **1.5 Pin Identification**.
2. Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR).

2. Internal data memory space / Control registers / General-purpose registers

Incorrect:

Cautions 1. It is prohibited to use the general-purpose register space (FFEE0H to FFEFFH) for fetching instructions or as a stack area.

2. When self-programming is performed or the data flash memory is rewritten, the stack used for each library and the RAM address used for the data buffer and DMA transfer should not be set to the RAM area of the following products. For details, refer to **RL78 Family sh Library Type04** User's Manual.

R5F10266 : FFE20H-FFEA1H, FFEE0H-FFEFFH

(The stack used for the data flash library should be set to FFEA2H to FFEDFH and the RAM address used for the data buffer and DMA transfer should be set to FFE00H to **FFE19H.**)

R5F102mn, R5F103mn :FFE20H-**FFEA1H**

Remark m: Pin count (m = 6, 7, A), n: ROM capacitance (n = 7, 8, 9, A)

3. Use of the RAM areas of the following products is prohibited, because these areas are used for self-programming library and data flash library. (Refer to figure 3-3 to figure 3-5, Memory Map)

R5F102m8, R5F103m8: FFC00H to **FFC80H**
R5F102m9, R5F103m9: FFB00H-**FFC80H**
R5F102mA, R5F103mA: FF900H-**FFC80H**

Remarks m: Pin count (m = 6, 7)

Correct:

Cautions 1. It is prohibited to use the general-purpose register space (FFEE0H to FFEFFH) for fetching instructions or as a stack area.

2. When self-programming is performed or the data flash memory is rewritten, the stack used for each library and the RAM address used for the data buffer and DMA transfer should not be set to the RAM area of the following products. For details, refer to RL78 Family Data Flash Library Type04 User's Manual.

R5F10266 : FFE20H to FFEA1H, FFEE0H to FFEFFH

(The stack used for the data flash library should be set to FFEA2H to FFEDFH and the RAM address used for the data buffer and DMA transfer should be set to FFE00H to FFE1FH.)

R5F102mn, R5F103mn :FFE20H to FFEFFH

Remark m: Pin count (m = 6, 7, A), n: ROM capacitance (n = 7, 8, 9, A)

3. Use of the RAM areas of the following products is prohibited, because these areas are used for self-programming library and data flash library. (Refer to figure 3-3 to figure 3-5, Memory Map)

R5F102m8, R5F103m8: FFC00H to FFC89H
R5F102m9, R5F103m9: FFB00H to FFC89H
R5F102mA, R5F103mA: FF900H to FFC89H

Remark m: Pin count (m = 6, 7)

3. **4.3 Registers Controlling Port Function**
Figure 4-40. Format of Peripheral I/O Redirection Register (PIOR)

Incorrect:

Figure 4-40. Format of Peripheral I/O Redirection Register (PIOR)

Address : F0077H After reset : 00H R/W

Symbol	7	6	5	4	3	2	1	0
PIOR	0	0	0	0	PIOR3	PIOR2	PIOR1	PIOR0

20-, 24-pin products

Bit	Function	Setting value	
		0	1
PIOR3 Note 1	SCK01	P42	P02 Note 2
	SI01	P125	P00 Note 2
	SO01	P41	P01 Note 2
	SCL01	P42	P02 Note 2
	SDA01	P41	P01 Note 2
PIOR2	TI02	P41	P122
	TI03	P42	P121
PIOR1	RxD0	P11	P61
	TxD0	P12	P60
PIOR0	INTP2	P13	P122
	INTP3	P14	P121

Notes 1. R5F102 products
2. Provided only in 24-pin products

Correct:

Figure 4-40. Format of Peripheral I/O Redirection Register (PIOR)

Address : F0077H After reset : 00H R/W

Symbol	7	6	5	4	3	2	1	0
PIOR	0	0	0	0	PIOR3 Notes 1, 2	PIOR2	PIOR1	PIOR0

20-, 24-pin products

Bit	Function	Setting value	
		0	1
PIOR3 Notes 1, 2	SCK01	P42	P02
	SI01	P125	P00
	SO01	P41	P01
	SCL01	P42	P02
	SDA01	P41	P01
PIOR2 Note 3	TI02	P41	P122
	TI03	P42	P121
PIOR1	RxD0	P11	P61
	TxD0	P12	P60
PIOR0	INTP2	P13	P122
	INTP3	P14	P121

Notes 1. Provided only in R5F102 products.
2. Provided only in 24-pin products.
3. If the PIOR2 bit is set to "1" in 20-, 24-pin products, using output of timer from the TO02 and TO03 is prohibited.

Figure 4-40. Format of Peripheral I/O Redirection Register (PIOR)

Address : F0077H After reset : 00H R/W

Symbol	7	6	5	4	3	2	1	0
PIOR	0	0	0	0	PIOR3	PIOR2	PIOR1	PIOR0

30-pin products

Bit	Function	Setting value	
		0	1
PIOR3	—	(fixed)	—
PIOR2	SCLA0	P60	P14
	SDAA0	P61	P13
PIOR1	TxD2 Note 1	P13	—
	RxD2 Note 1	P14	—
	SCL20 Note 1	P15	—
	SDA20 Note 1	P14	—
	SI20 Note 1	P14	—
	SO20 Note 1	P13	—
	SCK20 Note 1	P15	—
	TxD0	P12	P17
	RxD0	P11	P16
	SCL00	P10	—
	SDA00	P11	—
	SI00	P11	—
	SO00	P12	—
	SCK00	P10	—
PIOR0	TI02/TO02	P17	P15
	TI03/TO03	P31	P14
	TI04/TO04 Note 1	—	P13
	TI05/TO05 Note 1	—	P12
	TI06/TO06 Note 1	—	P11
	TI07/TO07 Note 1	—	P10

Notes 1. R5F102 products

2. Provided only in 24-pin products

Figure 4-40. Format of Peripheral I/O Redirection Register (PIOR)

Address : F0077H After reset : 00H R/W

Symbol	7	6	5	4	3	2	1	0
PIOR	0	0	0	0	PIOR3 Notes 1, 2	PIOR2	PIOR1	PIOR0

30-pin products

Bit	Function	Setting value	
		0	1
PIOR3	—	Fixed	Setting prohibited
PIOR2	SCLA0	P60	P14
	SDAA0	P61	P13
PIOR1	TxD2 Note 1	P13	—
	RxD2 Note 1	P14	—
	SCL20 Note 1	P15	—
	SDA20 Note 1	P14	—
	SI20 Note 1	P14	—
	SO20 Note 1	P13	—
	SCK20 Note 1	P15	—
	TxD0	P12	P17
	RxD0	P11	P16
	SCL00 Note 1	P10	—
	SDA00 Note 1	P11	—
	SI00	P11	—
	SO00	P12	—
	SCK00	P10	—
PIOR0	TI02/TO02	P17	P15
	TI03/TO03	P31	P14
	TI04/TO04	—	P13
	TI05/TO05	—	P12
	TI06/TO06	—	P11
	TI07/TO07	—	P10

Notes 1. Provided only in R5F102 products.

2. Provided only in 24-pin products.

4. 6.7.3 Operation as frequency divider

Incorrect:

6.7.3 Operation as frequency divider (channel 0 of unit 0 only)

The timer array unit can be used as a frequency divider that divides a clock input to the TI00 pin and outputs the result from the TO00 pin.

The divided clock frequency output from TO00 can be calculated by the following expression.

- When rising edge/falling edge is selected:
  Divided clock frequency = Input clock frequency/{(Set value of TDR00 + 1) × 2}
- When both edges are selected:
  Divided clock frequency ≅ Input clock frequency/(Set value of TDR00 + 1)

(omitted)

The period of the TO00 output clock includes a sampling error of one period of the operation clock.

Clock period of TO00 output = Ideal TO00 output clock period ± Operation clock period (error)

The TDR00 register can be rewritten at any time. The new value of the TDR00 register becomes valid during the next count period.

(omitted)

Correct:

6.7.3 Operation as frequency divider (channel 0 only in 30-pin products)

The timer array unit can be used as a frequency divider that divides a clock input to the TI00 pin and outputs the result from the TO00 pin.

The divided clock frequency output from TO00 can be calculated by the following expression.

- When rising edge/falling edge is selected:
  Divided clock frequency = Input clock frequency/{(Set value of TDR00 + 1) × 2}
- When both edges are selected:
  Divided clock frequency ≅ Input clock frequency/(Set value of TDR00 + 1)

(omitted)

The period of the TO00 output clock includes a sampling error of one period of the operation clock.

Clock period of TO00 output = Ideal TO00 output clock period ± Operation clock period (error)

The TDR00 register can be rewritten at any time. The new value of the TDR00 register becomes valid during the next count period.

(omitted)

5. 11.6.3 SNOOZE mode function (only UART0 reception)

Incorrect:
SNOOZE mode makes UART operate reception by RxD0 pin input detection while the STOP mode. Normally UART stops communication in the STOP mode. But, using the SNOOZE mode makes reception data unless the CPU operation.
Only UART0 can be set to the SNOOZE mode.
When using the SNOOZE mode function, set the SWC0 bit of serial standby control register 0 (SSC0) to 1 before switching to the STOP mode.

Cautions 1. The SNOOZE mode can only be specified when the high-speed on-chip oscillator clock is selected for fCLK.
2. The maximum transfer rate when using UART0 in the SNOOZE mode is 9600 bps.

Correct:
SNOOZE mode makes UART operate reception by RxD0 pin input detection while the STOP mode. Normally UART stops communication in the STOP mode. But, using the SNOOZE mode makes reception UART operate unless the CPU operation by detecting RxD0 pin input.
Only following channels can be set to the SNOOZE mode.

When using UART0 in SNOOZE mode, execute the following settings before entering STOP mode (Refer to Flowcharts of SNOOZE mode operation in Figure 11-93 and Figure 11-95).

- **In SNOOZE mode, UART reception baud rate must be set differently from normal operation. Refer to Table 11-3 to set registers SPS0 and SDR01 [15:9].**
- **Set bits EOC01 and SSEC0 to enable or disable the error interrupt (INTSRE0) when a communication error occurs.**
- **Set the SWC0 bit in the serial standby control register m (SSC0) to 1 just before entering STOP mode. After initialization, set the SS01 bit to 1 in the serial channel start register 0 (SS0).**

When the MCU detects the RxD0 pin edge input (input the start bit) after entering STOP mode, the UART reception is started.

Cautions: 1. The SNOOZE mode can only be specified when the high-speed on-chip oscillator clock (f_{IH}) is selected for f_{CLK}.
2. The transfer rate in SNOOZE mode is 4800 bps only.
3. When the SWC0 bit is 1, UART0 can be used only when the reception is started in STOP mode. If UART0 is used with other SNOOZE function or interrupts concurrently and the reception is started in state other than STOP mode as described below, the UART0 cannot receive data correctly and may cause a framing error or parity error.
• The case the UART0 reception is started from the moment the SWC0 bit is set to 1 before the MCU enters STOP mode
• The case the UART0 reception is started in SNOOZE mode
• The case the UART0 reception is started from the moment the MCU exits STOP mode and enters normal mode using interrupts before the SWC0 bit is set to 0

4. When the SSEC0 bit is 1, if a parity error, framing error, or overrun error occurs, flags PEF01, FEF01, or OVF01 is not set, nor an error interrupt (INTSRE0) is generated. To set the SSEC0 bit to 1, clear flags PEF01, FEF01, and OVF01 before setting the SWC0 bit to 1, and read bits 7 to 0 (RxD0) in the SDR01 register.

Table 11-3 UART Reception Baud Rate Setting in SNOOZE Mode

High-speed on-chip oscillator (f_{IH})	UART reception baud rate in SNOOZE mode			
	Baud rate: 4800 bps			
	Operating clock (f_{MCK})	SDR01 [15:9]	Maximum acceptable value	Minimum acceptable value
24 MHz ± 1.0% (note)	$f_{CLK}/2^5$	79	1.60%	−2.18%
16 MHz ± 1.0% (note)	$f_{CLK}/2^4$	105	2.27%	−1.53%
12 MHz ± 1.0% (note)	$f_{CLK}/2^4$	79	1.60%	−2.19%
8 MHz ± 1.0% (note)	$f_{CLK}/2^3$	105	2.27%	−1.53%
6 MHz ± 1.0% (note)	$f_{CLK}/2^3$	79	1.60%	−2.19%
4 MHz ± 1.0% (note)	$f_{CLK}/2^2$	105	2.27%	−1.53%
3 MHz ± 1.0% (note)	$f_{CLK}/2^2$	79	1.60%	−2.19%
2 MHz ± 1.0% (note)	$f_{CLK}/2$	105	2.27%	−1.54%
1 MHz ± 1.0% (note)	f_{CLK}	105	2.27%	−1.57%

Note: When the high-speed on-chip oscillator clock accuracy is at ± 1.5% or ± 2.0%, the acceptable range is limited as follows:
- f_{IH} ± 1.5%: Subtract 0.5% from the maximum acceptable value of f_{IH} ± 1.0%, and add 0.5% to the minimum acceptable value of f_{IH} ± 1.0%.
- f_{IH} ± 2.0%: Subtract 1.0% from the maximum acceptable value of f_{IH} ± 1.0%, and add 1.0% to the minimum acceptable value of f_{IH} ± 1.0%.

Remarks: Maximum and minimum acceptable values in the above table are the baud rate acceptable values in UART reception. Make sure to set the baud rate for transmission within this range.

6. 17.2.2 STOP mode

Incorrect:

Figure 17-5. STOP Mode Release by Interrupt Request Generation
(1) When high-speed system clock (X1 oscillation) is used as CPU clock
(omitted)

Notes 2. Time for STOP mode release
Supply of the clock is stopped: 18.96 μ s to "whichever is longer 28.95 μ s and the oscillation stabilization time (set by OSTS)"
Wait
- When vectored interrupt servicing is carried out: 10 to 11 clock
- When vectored interrupt servicing is not carried out: 4 to 5 clock

(2) When high-speed system clock (external clock input) is used as CPU clock
(3) When high-speed on-chip oscillator clock is used as CPU clock
(omitted)

Notes 2. STOP mode release time
Supply of the clock is stopped:19.08 to 32.99 μ s
Wait
- When vectored interrupt servicing is carried out: 7 clock
- When vectored interrupt servicing is not carried out: 1 clock

Correct:

Figure 17-5 STOP Mode Release by Interrupt Request Generation (1/2)
(1) When high-speed system clock (X1 oscillation) is used as CPU clock
(omitted)

Notes2. STOP mode release time
Supply of the clock is stopped: 18 μs to "whichever is longer 65 μs or the oscillation stabilization time (set by OSTS)"

Wait
- When vectored interrupt servicing is carried out: 10 to 11 clocks
- When vectored interrupt servicing is not carried out: 4 to 5 clocks

Remark: The time to stop clock supply varies depending on the temperature conditions and STOP mode time.

(2) When high-speed system clock (external clock input) is used as CPU clock
(3) When high-speed on-chip oscillator clock is used as CPU clock
(omitted)

Notes: 2. STOP mode release time
Supply of the clock is stopped: 18 to 65 μs

Wait
- When vectored interrupt servicing is carried out: 7 clocks
- When vectored interrupt servicing is not carried out: 1 clock

Remark: The time to stop clock supply varies depending on the temperature conditions and STOP mode time.

7. 17.2.3 SNOOZE Mode

Incorrect:
In SNOOZE mode rerease, wait status to be only following time.

From STOP to SNOOZE
HS (high-speed main) mode : 18.96 to 28.95 μ s
LS (low-speed main) mode : 20.24 to 28.95 μ s

From SNOOZE to normal operation
· When vectored interrupt servicing is carried out:
HS (high-speed main) mode : 6.79 to 12.4 μ s + 7 clock
LS (low-speed main) mode : 2.58 to 7.8 μ s + 7 clock
· When vectored interrupt servicing is not carried out:
HS (high-speed main) mode : 6.79 to 12.4 μ s + 1 clock
LS (low-speed main) mode : 2.58 to 7.8 μ s + 1 clock

Correct:
The MCU transits from STOP mode to SNOOZE mode or from SNOOZE mode to normal operation after time shown below elapses.

Transit time from STOP mode to SNOOZE mode: 18 to 65 μs

Remark: The transit time from STOP mode to SNOOZE mode varies depending on the temperature conditions and STOP mode time.

Transit time from SNOOZE mode to normal operation:
- **When vectored interrupt servicing is carried out:**
  HS (High-speed main) mode : "6.65 to 9.44 μs" + 7 clocks
  LS (Low-speed main) mode : "1.10 to 5.08 μs" + 7 clocks

- **When vectored interrupt servicing is not carried out:**
  HS (High-speed main) mode : "6.65 to 9.44 μs" + 1 clock
  LS (Low-speed main) mode : "1.10 to 5.08 μs" + 1 clock

8. Figure 23-3 Format of Option Byte (000C2H)

Old:

Figure 23-3 Format of Option Byte (000C2H)

Address: 000C2H

7	6	5	4	3	2	1	0
CMODE1	**C5MODE0**	1	0	FRQSEL3	FRQSEL2	FRQSEL1	FRQSEL0

CMODE1	CMODE0	Setting of flash operation mode		
			Operating Frequency Range	Operating Voltage Range
1	0	LS (low speed main) mode	1 to 8 MHz	1.8 to 5.5 V
1	1	HS (high speed main) mode	1 to 16 MHz	2.4 to 5.5 V
			1 to 24 MHz	2.7 to 5.5 V
Other than above		Setting prohibited		

FRQSEL3	FRQSEL2	FRQSEL1	FRQSEL0	Frequency of the high-speed on-chip oscillator
0	0	0	0	24 MHz
1	0	0	1	16 MHz
0	0	0	1	12 MHz
1	0	1	0	8 MHz
1	0	1	1	4 MHz
1	1	0	1	1 MHz
Other than above				Setting prohibited

Caution: Be sure to set bit 5 to “1" and bit 4 to “0”.

New:

Figure 23-3 Format of Option Byte (000C2H)

Address: 000C2H

7	6	5	4	3	2	1	0
CMODE1	CMODE0	1	0	FRQSEL3	FRQSEL2	FRQSEL1	FRQSEL0

CMODE1	CMODE0	Setting of flash operation mode		
			Operating Frequency Range	Operating Voltage Range
1	0	LS (Low-speed main) mode	1 to 8 MHz	1.8 to 5.5 V
1	1	HS (High-speed main) mode	1 to 16 MHz	2.4 to 5.5 V
			1 to 24 MHz	2.7 to 5.5 V
Other than above		Setting prohibited		

FRQSEL3	FRQSEL2	FRQSEL1	FRQSEL0	Frequency of the high-speed on-chip oscillator
0	0	0	0	24 MHz
1	0	0	1	16 MHz
0	0	0	1	12 MHz
1	0	1	0	8 MHz
0	**0**	**1**	**0**	**6 MHz**
1	0	1	1	4 MHz
0	**0**	**1**	**1**	**3 MHz**
1	**1**	**0**	**0**	**2 MHz**
1	1	0	1	1 MHz
Other than above				Setting prohibited

Cautions 1. Be sure to set bit 5 to “1" and bit 4 to “0”

2. The ranges of operation frequency and operation voltage vary depending on the flash operation mode. For details, see 28.4 or 29.4 AC Characteristics.

9. 28.3.1 Pin characteristics

Incorrect:
Fixed typo in Note 3 in pages 775 and 776

Correct:
Refer to pages 5 and 6 in Technical Update Exhibit “Chapter 28 ELECTRICAL SPECIFICATIONS (A, D: T_A = −40 to + 85°C)” (MCYG-AB-13-0155).

10. 28.3.2 Supply current characteristics

Incorrect:
Fixed typo in Notes and typical values of IDD2 and IDD3 in pages 779 to 783

Correct:
Refer to pages 9 to 14 in Technical Update Exhibit “Chapter 28 ELECTRICAL SPECIFICATIONS (A, D: T_A = −40 to + 85°C)” (MCYG-AB-13-0155).

11. 28.4 AC Characteristics

Old:
Specifications of the external system clock frequency and external system clock input high-level width, low-level width in page 784 extended

New:
Refer to page 15 in Technical Update Exhibit “Chapter 28 ELECTRICAL SPECIFICATIONS (A, D: T_A = −40 to + 85°C)” (MCYG-AB-13-0155).

12. 28.5.1 Serial array unit

Incorrect:
Fixed typo in 28.5.1 Serial array unit in pages 786 to 806

Correct:
Refer to pages 18 to 39 in Technical Update Exhibit “Chapter 28 ELECTRICAL SPECIFICATIONS (A, D: T_A = −40 to + 85°C)” (MCYG-AB-13-0155).

13. 28.5.2 Serial Interface IICA

Incorrect:
Fixed typo in 28.5.2 Serial interface IICA in page 807

Correct:
Refer to page 40 in Technical Update Exhibit “Chapter 28 ELECTRICAL SPECIFICATIONS (A, D: T_A = −40 to + 85°C)” (MCYG-AB-13-0155).

14. 28.6.1 A/D converter characteristics

Old:
Specifications of “28.6.1 A/D converter characteristics” in pages 808 to 810 extended

New:
Refer to pages 41 to 44 in Technical Update Exhibit “Chapter 28 ELECTRICAL SPECIFICATIONS (A, D: T_A = −40 to + 85°C)” (MCYG-AB-13-0155).

15. 28.6.2 Temperature Sensor/Internal Reference Voltage Characteristics

Incorrect:
Fixed typo in 28.6.2 Temperature Sensor/Internal Reference Voltage Characteristics in page 811

Correct:
Refer to page 45 in Technical Update Exhibit “Chapter 28 ELECTRICAL SPECIFICATIONS (A, D: T_A = −40 to + 85°C)” (MCYG-AB-13-0155).

16. 28.6.3 POR circuit characteristics

Incorrect:
Fixed typo in 28.6.3 POR circuit characteristics in page 811

Correct:
Refer to page 45 in Technical Update Exhibit “Chapter 28 ELECTRICAL SPECIFICATIONS (A, D: T_A = −40 to + 85°C)” (MCYG-AB-13-0155).

17. Power supply voltage rising slope characteristics

Old:
Specifications in Power supply voltage rising slope characteristics added

New:
Refer to page 47 in Technical Update Exhibit “Chapter 28 ELECTRICAL SPECIFICATIONS (A, D: T_A = −40 to + 85°C)” (MCYG-AB-13-0155).

18. 28.7 Data Memory STOP Mode Low Supply Voltage Data Retention Characteristics

Old:
Specifications in Data Memory STOP Mode Low Supply Voltage Data Retention Characteristics in page 814 extended

New:
Refer to page 48 in Technical Update Exhibit “Chapter 28 ELECTRICAL SPECIFICATIONS (A, D: T_A = −40 to + 85°C)” (MCYG-AB-13-0155).

19. Chapter 29 ELECTRICAL SPECIFICATIONS (G: T_A = −40 to +105°C) (TARGET VALUES)

Old:
Specifications in Chapter 29 ELECTRICAL SPECIFICATIONS (G: T_A = −40 to +105°C) (TARGET VALUES) added

New:
Refer to pages 2 to 44 in Technical Update Exhibit “Chapter 29 ELECTRICAL SPECIFICATIONS (G: T_A = −40 to +105°C) (TARGET VALUES)” (MCYG-AB-13-0156).

To our valued customers:	RL78/G12 Technical Update Exhibit Chapter 28 ELECTRICAL SPECIFICATIONS (A, D: T_A = −40 to +85°C)	M C Y G - A B - 1 3 - 0 1 5 5 - 1 July 24, 2013 Hiroshi Uchimura Manager 1st Solution Business Unit 3rd MCU Business Division Brand Strategy Department Renesas Electronics Corporation

(Rep. Takehiro Furukawa)

Thank you for your continued support for Renesas Electronics products.

Please be advised that the misstatements found in the following User's Manual have been fixed.

The second and following pages in this document include "Chapter 28 ELECTRICAL SPECIFICATIONS (A, D: T_A = −40 to +85°C)" which has been updated by the Correction for incorrect description notice RL78/G12 Descriptions in the User's Manual: Hardware Rev.1.10 changed (TN-RL*-A006A/E).

1. Applicable products:

RL78/G12

R5F102xxA, R5F103xxA
R5F102xxD, R5F103xxD

2. Reference documents:

Correction for incorrect description notice RL78/G12 Descriptions in the User's Manual: Hardware Rev.1.10 changed (TN-RL*-A006A/E)
RL78/G12 User's Manual: Hardware Rev.1.10 (R01UH0200EJ0110)

CHAPTER 28 ELECTRICAL SPECIFICATIONS (A, D: T_A = –40 to +85°C)

This chapter describes the electrical specifications for the products "A: Consumer applications (T_A = -40 to +85°C)" and "D: Industrial applications (T_A = -40 to +85°C)".

Cautions 1. The RL78 microcontrollers have an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. Renesas Electronics is not liable for problems occurring when the on-chip debug function is used.

2. The pins mounted depend on the product. Refer to 2.1 Port Function to 2.2.1 Functions Mounted According to Product.

28.1 Absolute Maximum Ratings

(T_A = 25°C)

Parameter	Symbols	Conditions		Ratings	Unit
Supply Voltage	V_{DD}			–0.5 to + 6.5	V
REGC terminal input voltage[Note1]	V_{IREGC}	REGC		–0.3 to +2.8 and –0.3 to V_{DD} + 0.3 [Note 2]	V
Input Voltage	V_{I1}	Other than P60, P61		–0.3 to V_{DD} + 0.3[Note 3]	V
	V_{I2}	P60, P61 (N-ch open drain)		–0.3 to 6.5	V
Output Voltage	V_O			–0.3 to V_{DD} + 0.3[Note 3]	V
Analog input voltage	V_{AI}	20-, 24-pin products: ANI0 to ANI3, ANI16 to ANI22 30-pin products: ANI0 to ANI3, ANI16 to ANI19		–0.3 to V_{DD} + 0.3 and –0.3 to AVREF(+)+0.3 [Notes 3, 4]	V
Output current, high	I_{OH1}	Per pin	Other than P20 to P23	–40	mA
		Total of all pins	All the terminals other than P20 to P23	–170	mA
			20-, 24-pin products: P40 to P42 30-pin products: P00, P01, P40, P120	–70	mA
			20-, 24-pin products: P00 to P03[Note 5], P10 to P14 30-pin products: P10 to P17, P30, P31, P50, P51, P147	–100	mA
	I_{OH2}	Per pin	P20 to P23	–0.5	mA
		Total of all pins		–2	mA
Output current, low	I_{OL1}	Per pin	Other than P20 to P23	40	mA
		Total of all pins	All the terminals other than P20 to P23	170	mA
			20-, 24-pin products: P40 to P42 30-pin products: P00, P01, P40, P120	70	mA
			20-, 24-pin products: P00 to P03[Note 5], P10 to P14, P60, P61 30-pin products: P10 to P17, P30, P31, P50, P51, P60, P61, P147	100	mA
	I_{OL2}	Per pin	P20 to P23	1	mA
		Total of all pins		5	mA
Operating ambient temperature	T_A			–40 to +85	°C
Storage temperature	T_{stg}			–65 to +150	°C

Notes 1. 30-pin products only.

2. Connect the REGC pin to V_{SS} via a capacitor (0.47 to 1 μF). This value determines the absolute maximum rating of the REGC pin. Do not use it with voltage applied.

3. Must be 6.5 V or lower.

4. Do not exceed $AV_{REF}(+)$ + 0.3 V in case of A/D conversion target pin.

5. 24-pin products only.

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Remarks 1. Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

2. $AV_{REF}(+)$: + side reference voltage of the A/D converter.

3. V_{SS} : Reference voltage

28.2 Oscillator Characteristics

28.2.1 X1 oscillator characteristics

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Resonator	Conditions	MIN.	TYP.	MAX.	Unit
X1 clock oscillation frequency (f_X)[Note]	Ceramic resonator / crystal oscillator	2.7 V ≤ V_{DD} ≤ 5.5 V	1.0		20.0	MHz
		1.8 V ≤ V_{DD} < 2.7 V	1.0		8.0	

Note Indicates only permissible oscillator frequency ranges. Refer to AC Characteristics for instruction execution time. Request evaluation by the manufacturer of the oscillator circuit mounted on a board to check the oscillator characteristics.

Caution Since the CPU is started by the high-speed on-chip oscillator clock after a reset release, check the X1 clock oscillation stabilization time using the oscillation stabilization time counter status register (OSTC) by the user. Determine the oscillation stabilization time of the OSTC register and the oscillation stabilization time select register (OSTS) after sufficiently evaluating the oscillation stabilization time with the resonator to be used.

Remark When using the X1 oscillator, refer to **5.4 System Clock Oscillator**.

28.2.2 On-chip oscillator characteristics

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Oscillators	Parameters	Conditions		MIN.	TYP.	MAX.	Unit
High-speed on-chip oscillator clock frequency [Notes 1, 2]	f_{IH}			1		24	MHz
High-speed on-chip oscillator clock frequency accuracy		R5F102 products	T_A = –20 to +85°C	-1.0		+1.0	%
			T_A = –40 to –20°C	-1.5		+1.5	%
		R5F103 products		-5.0		+5.0	%
Low-speed on-chip oscillator clock frequency	f_{IL}				15		kHz
Low-speed on-chip oscillator clock frequency accuracy				-15		+15	%

Notes 1. High-speed on-chip oscillator frequency is selected by bits 0 to 3 of option byte (000C2H/010C2H) and bits 0 to 2 of HOCODIV register.

2. This only indicates the oscillator characteristics. Refer to AC Characteristics for instruction execution time.

28.3 DC Characteristics

28.3.1 Pin characteristics

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (1/4)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, high[Note 1]	I_{OH1}	20-, 24-pin products: Per pin for P00 to P03[Note 4], P10 to P14, P40 to P42 30-pin products: Per pin for P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147				–10.0 [Note 2]	mA
		20-, 24-pin products: Total of P40 to P42 30-pin products: Total of P00, P01, P40, P120 (When duty ≤ 70% [Note 3])	4.0 V ≤ V_{DD} ≤ 5.5 V			–30.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			–6.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			–4.5	mA
		20-, 24-pin products: Total of P00 to P03[Note 4], P10 to P14 30-pin products: Total of P10 to P17, P30, P31, P50, P51, P147 (When duty ≤ 70% [Note 3])	4.0 V ≤ V_{DD} ≤ 5.5 V			–80.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			–18.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			–10.0	mA
		Total of all pins (When duty ≤ 70% [Note 3])				–100	mA
	I_{OH2}	Per pin for P20 to P23				–0.1	mA
		Total of all pins				–0.4	mA

Notes 1. value of current at which the device operation is guaranteed even if the current flows from the V_{DD} pin to an output pin.

2. However, do not exceed the total current value.

3. The output current value under conditions where the duty factor ≤ 70%.
If duty factor > 70%: The output current value can be calculated with the following expression (where n represents the duty factor as a percentage).

- Total output current of pins = (I_{OH} × 0.7)/(n × 0.01)

<Example> Where n = 80% and I_{OH} = –10.0 mA

Total output current of pins = (–10.0 × 0.7)/(80 × 0.01) ≅ –8.7 mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

4. 24-pin products only.

Caution P10 to P12, P41 for 20-pin products, P01, P10 to P12, P41 for 24-pin products, and P00, P10 to P15, P17, P50 for 30-pin products do not output high level in N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (2/4)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, low Note 1	I_{OL1}	20-, 24-pin products: Per pin for P00 to P03 Note 4, P10 to P14, P40 to P42 30-pin products: Per pin for P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147				20.0 Note 2	mA
		Per pin for P60, P61				15.0 Note 2	mA
		20-, 24-pin products: Total of P40 to P42 30-pin products: Total of P00, P01, P40, P120 (When duty ≤ 70% Note 3)	4.0 V ≤ V_{DD} ≤ 5.5 V			60.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			9.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			1.8	mA
		20-, 24-pin products: Total of P00 to P03 Note 4, P10 to P14, P60, P61 30-pin products: Total of P10 to P17, P30, P31, P50, P51, P60, P61, P147 (When duty ≤ 70% Note 3)	4.0 V ≤ V_{DD} ≤ 5.5 V			80.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			27.0	mA
			1.8 V ≤ V_{DD} < 2.7 V			5.4	mA
		Total of all pins (When duty ≤ 70% Note 3)				140	mA
	I_{OL2}	Per pin for P20 to P23				0.4	mA
		Total of all pins				1.6	mA

Notes 1. Value of current at which the device operation is guaranteed even if the current flows from an output pin to the V_{SS} pin.

2. However, do not exceed the total current value.

3. The output current value under conditions where the duty factor ≤ 70%.

If duty factor > 70%: The output current value can be calculated with the following expression (where n represents the duty factor as a percentage).

- Total output current of pins = (I_{OL} × 0.7)/(n × 0.01)

<Example> Where n = 80% and I_{OL} = 10.0 mA

Total output current of pins = (10.0 × 0.7)/(80 × 0.01) ≅ 8.7 mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

4. 24-pin products only.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (3/4)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Input voltage, high	V_{IH1}	Normal input buffer 20-, 24-pin products: P00 to P03[Note 2], P10 to P14, P40 to P42 30-pin products: P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147		0.8V_{DD}		V_{DD}	V
	V_{IH2}	TTL input buffer 20-, 24-pin products: P10, P11 30-pin products: P01, P10, P11, P13 to P17	4.0 V ≤ V_{DD} ≤ 5.5 V	2.2		V_{DD}	V
			3.3 V ≤ V_{DD} < 4.0 V	2.0		V_{DD}	V
			1.8 V ≤ V_{DD} < 3.3 V	1.5		V_{DD}	V
	V_{IH3}	Normal input buffer P20 to P23		0.7V_{DD}		V_{DD}	V
	V_{IH4}	P60, P61		0.7V_{DD}		6.0	V
	V_{IH5}	P121, P122, P125[Note 1], P137, EXCLK, $\overline{\text{RESET}}$		0.8V_{DD}		V_{DD}	V
Input voltage, low	V_{IL1}	Normal input buffer 20-, 24-pin products: P00 to P03[Note 2], P10 to P14, P40 to P42 30-pin products: P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147		0		0.2V_{DD}	V
	V_{IL2}	TTL input buffer 20-, 24-pin products: P10, P11 30-pin products: P01, P10, P11, P13 to P17	4.0 V ≤ V_{DD} ≤ 5.5 V	0		0.8	V
			3.3 V ≤ V_{DD} < 4.0 V	0		0.5	V
			1.8 V ≤ V_{DD} < 3.3 V	0		0.32	V
	V_{IL3}	P20 to P23		0		0.3V_{DD}	V
	V_{IL4}	P60, P61		0		0.3V_{DD}	V
	V_{IL5}	P121, P122, P125[Note 1], P137, EXCLK, $\overline{\text{RESET}}$		0		0.2V_{DD}	V
Output voltage, high	V_{OH1}	20-, 24-pin products: P00 to P03[Note 2], P10 to P14, P40 to P42 30-pin products: P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147	4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OH1} = –10.0 mA	V_{DD}–1.5			V
			4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OH1} = –3.0 mA	V_{DD}–0.7			V
			2.7 V ≤ V_{DD} ≤ 5.5 V, I_{OH1} = –2.0 mA	V_{DD}–0.6			V
			1.8 V ≤ V_{DD} ≤ 5.5 V, I_{OH1} = –1.5 mA	V_{DD}–0.5			V
	V_{OH2}	P20 to P23	I_{OH2} = –100 μA	V_{DD}–0.5			V

Notes 1. 20, 24-pin products only.

2. 24-pin products only.

Caution The maximum value of V_{IH} of pins P10 to P12, P41 for 20-pin products, P01, P10 to P12, P41 for 24-pin products, and P00, P10 to P15, P17, P50 for 30-pin products is V_{DD} even in N-ch open-drain mode. High level is not output in the N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) **(4/4)**

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output voltage, low	V_{OL1}	20-, 24-pin products: P00 to P03[Note], P10 to P14, P40 to P42 30-pin products: P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147	4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 20.0 mA			1.3	V
			4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 8.5 mA			0.7	V
			2.7 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 3.0 mA			0.6	V
			2.7 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 1.5 mA			0.4	V
			1.8 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 0.6 mA			0.4	V
	V_{OL2}	P20 to P23	I_{OL2} = 400 μA			0.4	V
	V_{OL3}	P60, P61	4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 15.0 mA			2.0	V
			4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 5.0 mA			0.4	V
			2.7 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 3.0 mA			0.4	V
			1.8 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 2.0 mA			0.4	V
Input leakage current, high	I_{LIH1}	Other than P121, P122	V_I = V_{DD}			1	μA
	I_{LIH2}	P121, P122 (X1, X2/EXCLK)	V_I = V_{DD} Input port or external clock input			1	μA
			V_I = V_{DD} When resonator connected			10	μA
Input leakage current, low	I_{LIL1}	Other than P121, P122	V_I = V_{SS}			–1	μA
	I_{LIL2}	P121, P122 (X1, X2/EXCLK)	V_I = V_{SS} Input port or external clock input			–1	μA
			V_I = V_{SS} When resonator connected			–10	μA
On-chip pull-up resistance	R_U	20-, 24-pin products: P00 to P03[Note], P10 to P14, P40 to P42, P125, $\overline{\text{RESET}}$ 30-pin products: P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147	V_I = V_{SS}, input port	10	20	100	kΩ

Note 24-pin products only.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

28.3.2 Supply current characteristics

(1) 20-, 24-pin products

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) **(1/2)**

Parameter	Symbol	Conditions					MIN.	TYP.	MAX.	Unit
Supply current[Note 1]	I_{DD1}	Operating mode	HS(High-speed main) mode[Note 4]	f_{IH} = 24 MHz[Note 3]	Basic operation	V_{DD} = 5.0 V		1.5		mA
						V_{DD} = 3.0 V		1.5		
					Normal operation	V_{DD} = 5.0 V		3.3	5.0	mA
						V_{DD} = 3.0 V		3.3	5.0	
				f_{IH} = 16 MHz[Note 3]		V_{DD} = 5.0 V		2.5	3.7	mA
						V_{DD} = 3.0 V		2.5	3.7	
			LS(Low-speed main) mode[Note 4]	f_{IH} = 8 MHz[Note 3]		V_{DD} = 3.0 V		1.2	1.8	mA
						V_{DD} = 2.0 V		1.2	1.8	
			HS(High-speed main) mode[Note4]	f_{MX} = 20 MHz[Note 2], V_{DD} = 5.0 V		Square wave input		2.8	4.4	mA
						Resonator connection		3.0	4.6	
				f_{MX} = 20 MHz[Note 2], V_{DD} = 3.0 V		Square wave input		2.8	4.4	mA
						Resonator connection		3.0	4.6	
				f_{MX} = 10 MHz[Note 2], V_{DD} = 5.0 V		Square wave input		1.8	2.6	mA
						Resonator connection		1.8	2.6	
				f_{MX} = 10 MHz[Note 2], V_{DD} = 3.0 V		Square wave input		1.8	2.6	mA
						Resonator connection		1.8	2.6	
			LS(Low-speed main) mode[Note 4]	f_{MX} = 8 MHz[Note 2], V_{DD} = 3.0 V		Square wave input		1.1	1.7	mA
						Resonator connection		1.1	1.7	
				f_{MX} = 8 MHz[Note 2], V_{DD} = 2.0 V		Square wave input		1.1	1.7	mA
						Resonator connection		1.1	1.7	

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.

2. When high-speed on-chip oscillator clock is stopped.

3. When high-speed system clock is stopped

4. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS(High speed main) mode: V_{DD} = 2.7 V to 5.5 V @1 MHz to 24 MHz
V_{DD} = 2.4 V to 5.5 V @1 MHz to 16 MHz

LS(Low speed main) mode: V_{DD} = 1.8 V to 5.5 V @1 MHz to 8 MHz

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{IH}: high-speed on-chip oscillator clock frequency

3. Temperature condition of the TYP. value is T_A = 25°C.

(1) 20-, 24-pin products

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) **(2/2)**

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current[Note 1]	I_{DD2}[Note 2]	HALT mode	HS(High-speed main) mode[Note 6]	f_{IH} = 24 MHz[Note 4]	V_{DD} = 5.0 V		440	1210	μA
					V_{DD} = 3.0 V		440	1210	
				f_{IH} = 16 MHz[Note 4]	V_{DD} = 5.0 V		400	950	μA
					V_{DD} = 3.0 V		400	950	
			LS(Low-speed main) mode[Note 6]	f_{IH} = 8 MHz[Note 4]	V_{DD} = 3.0 V		270	542	μA
					V_{DD} = 2.0 V		270	542	
			HS(High-speed main) mode[Note 6]	f_{MX} = 20 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		280	1000	μA
					Resonator connection		450	1170	
				f_{MX} = 20 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		280	1000	μA
					Resonator connection		450	1170	
				f_{MX} = 10 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		190	590	μA
					Resonator connection		260	660	
				f_{MX} = 10 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		190	590	μA
					Resonator connection		260	660	
			LS(Low-speed main) mode[Note 6]	f_{MX} = 8 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		110	360	μA
					Resonator connection		150	416	
				f_{MX} = 8 MHz[Note 3], V_{DD} = 2.0 V	Square wave input		110	360	μA
					Resonator connection		150	416	
	I_{DD3}[Note 5]	STOP mode	T_A = –40°C				0.19	0.50	μA
			T_A = +25°C				0.24	0.50	
			T_A = +50°C				0.32	0.80	
			T_A = +70°C				0.48	1.20	
			T_A = +85°C				0.74	2.20	

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.

2. During HALT instruction execution by flash memory.

3. When high-speed on-chip oscillator clock is stopped.

4. When high-speed system clock is stopped.

5. Not including the current flowing into the 12-bit interval timer and watchdog timer.

6. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS(High speed main) mode: V_{DD} = 2.7 V to 5.5 V @1 MHz to 24 MHz
V_{DD} = 2.4 V to 5.5 V @1 MHz to 16 MHz

LS(Low speed main) mode: V_{DD} = 1.8 V to 5.5 V @1 MHz to 8 MHz

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{IH}: high-speed on-chip oscillator clock frequency

3. Except STOP mode, temperature condition of the TYP. value is T_A = 25°C

(2) 30-pin products

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) **(1/2)**

Parameter	Symbol	Conditions					MIN.	TYP.	MAX.	Unit
Supply current[Note 1]	I_{DD1}	Operating mode	HS(High-speed main) mode[Note 4]	f_{IH} = 24 MHz[Note 3]	Basic operation	V_{DD} = 5.0 V		1.5		mA
						V_{DD} = 3.0 V		1.5		
					Normal operation	V_{DD} = 5.0 V		3.7	5.5	mA
						V_{DD} = 3.0 V		3.7	5.5	
				f_{IH} = 16 MHz[Note 3]		V_{DD} = 5.0 V		2.7	4.0	mA
						V_{DD} = 3.0 V		2.7	4.0	
			LS(Low-speed main) mode[Note 4]	f_{IH} = 8 MHz[Note 3]		V_{DD} = 3.0 V		1.2	1.8	mA
						V_{DD} = 2.0 V		1.2	1.8	
			HS(High-speed main) mode[Note 4]	f_{MX} = 20 MHz[Note 2], V_{DD} = 5.0 V		Square wave input		3.0	4.6	mA
						Resonator connection		3.2	4.8	
				f_{MX} = 20 MHz[Note 2], V_{DD} = 3.0 V		Square wave input		3.0	4.6	mA
						Resonator connection		3.2	4.8	
				f_{MX} = 10 MHz[Note 2], V_{DD} = 5.0 V		Square wave input		1.9	2.7	mA
						Resonator connection		1.9	2.7	
				f_{MX} = 10 MHz[Note 2], V_{DD} = 3.0 V		Square wave input		1.9	2.7	mA
						Resonator connection		1.9	2.7	
			LS(Low-speed main) mode[Note 4]	f_{MX} = 8 MHz[Note 2], V_{DD} = 3.0 V		Square wave input		1.1	1.7	mA
						Resonator connection		1.1	1.7	
				f_{MX} = 8 MHz[Note 2], V_{DD} = 2.0 V		Square wave input		1.1	1.7	mA
						Resonator connection		1.1	1.7	

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.

2. When high-speed on-chip oscillator clock is stopped.

3. When high-speed system clock is stopped

4. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS(High speed main) mode: V_{DD} = 2.7 V to 5.5 V @1 MHz to 24 MHz
V_{DD} = 2.4 V to 5.5 V @1 MHz to 16 MHz

LS(Low speed main) mode: V_{DD} = 1.8 V to 5.5 V @1 MHz to 8 MHz

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{IH}: high-speed on-chip oscillator clock frequency

3. Temperature condition of the TYP. value is T_A = 25°C.

(2) 30-pin products

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) **(2/2)**

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current[Note 1]	I_{DD2}[Note 2]	HALT mode	HS (High-speed main) mode[Note 6]	f_{IH} = 24 MHz[Note 4]	V_{DD} = 5.0 V		440	1280	μA
					V_{DD} = 3.0 V		440	1280	
				f_{IH} = 16 MHz[Note 4]	V_{DD} = 5.0 V		400	1000	μA
					V_{DD} = 3.0 V		400	1000	
			LS (Low-speed main) mode[Note 6]	f_{IH} = 8 MHz[Note 4]	V_{DD} = 3.0 V		260	530	μA
					V_{DD} = 2.0 V		260	530	
			HS (High-speed main) mode[Note 6]	f_{MX} = 20 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		280	1000	μA
					Resonator connection		450	1170	
				f_{MX} = 20 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		280	1000	μA
					Resonator connection		450	1170	
				f_{MX} = 10 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		190	600	μA
					Resonator connection		260	670	
				f_{MX} = 10 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		190	600	μA
					Resonator connection		260	670	
			LS (Low-speed main) mode[Note 6]	f_{MX} = 8 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		95	330	μA
					Resonator connection		145	380	
				f_{MX} = 8 MHz[Note 3] V_{DD} = 2.0 V	Square wave input		95	330	μA
					Resonator connection		145	380	
	I_{DD3}[Note 5]	STOP mode	T_A = –40°C				0.18	0.50	μA
			T_A = +25°C				0.23	0.50	
			T_A = +50°C				0.30	1.10	
			T_A = +70°C				0.46	1.90	
			T_A = +85°C				0.75	3.30	

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.

2. During HALT instruction execution by flash memory.

3. When high-speed on-chip oscillator clock is stopped.

4. When high-speed system clock is stopped.

5. Not including the current flowing into the 12-bit interval timer and watchdog timer.

6. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS(High speed main) mode: V_{DD} = 2.7 V to 5.5 V @1 MHz to 24 MHz
V_{DD} = 2.4 V to 5.5 V @1 MHz to 16 MHz

LS(Low speed main) mode: V_{DD} = 1.8 V to 5.5 V @1 MHz to 8 MHz

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{IH}: high-speed on-chip oscillator clock frequency

3. Except STOP mode, temperature condition of the TYP. value is T_A = 25°C.

(3) Peripheral functions (Common to all products)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Low-speed onchip oscillator operating current	I_{FIL} Note 1				0.20		μA
12-bit interval timer operating current	I_{TMKA} Notes 1, 2, 3				0.02		μA
Watchdog timer operating current	I_{WDT} Notes 1, 2, 4	f_{IL} = 15 kHz			0.22		μA
A/D converter operating current	I_{ADC} Notes 1, 5	When conversion at maximum speed	Normal mode, AV_{REFP} = V_{DD} = 5.0 V		1.30	1.70	mA
			Low voltage mode, AV_{REFP} = V_{DD} = 3.0 V		0.50	0.70	mA
A/D converter reference voltage operation current	I_{ADREF} Note 1				75.0		μA
Temperature sensor operating current	I_{TMPS} Note 1				75.0		μA
LVD operating current	I_{LVD} Notes 1, 6				0.08		μA
Self-programming operating current	I_{FSP} Notes 1, 8				2.00	12.20	mA
BGO operating current	I_{BGO} Notes 1, 7				2.00	12.20	mA
SNOOZE operating current	I_{SNOZ} Note 1	ADC operation	The mode is performed Note 9		0.50	0.60	mA
			The A/D conversion operations are performed, Low voltage mode, AV_{REFP} = V_{DD} = 3.0 V		1.20	1.44	mA
		CSI/UART operation			0.70	0.84	mA

Notes 1. Current flowing to the V_{DD}.

2. When high speed on-chip oscillator and high-speed system clock are stopped.

3. Current flowing only to the 12-bit interval timer (excluding the operating current of the low-speed on-chip oscillator). The supply current of the RL78 microcontrollers is the sum of I_{DD1}, I_{DD2} or I_{DD3} and I_{TMKA} and I_{FIL} when the 12-bit interval timer operates.

4. Current flowing only to the watchdog timer (including the operating current of the low-speed on-chip oscillator). The supply current of the RL78 microcontrollers is the sum of I_{DD1}, I_{DD2} or I_{DD3} and I_{WDT} when the watchdog timer operates.

5. Current flowing only to the A/D converter. The supply current of the RL78 microcontrollers is the sum of I_{DD1} or I_{DD2} and I_{ADC} when the A/D converter operates in an operation mode or the HALT mode.

6. Current flowing only to the LVD circuit. The supply current of the RL78 microcontrollers is the sum of I_{DD1}, I_{DD2} or I_{DD3} and I_{LVD} when the LVD circuit is in operation.

7. Current flowing only during data flash rewrite.

8. Current flowing only during self programming.

9. Refer to shift time to the SNOOZE mode, see **17.2.3 SNOOZE mode**.

Remarks 1. f_{IL}: Low-speed on-chip oscillator clock frequency

2. Temperature condition of the TYP. value is T_A = 25°C

28.4 AC Characteristics

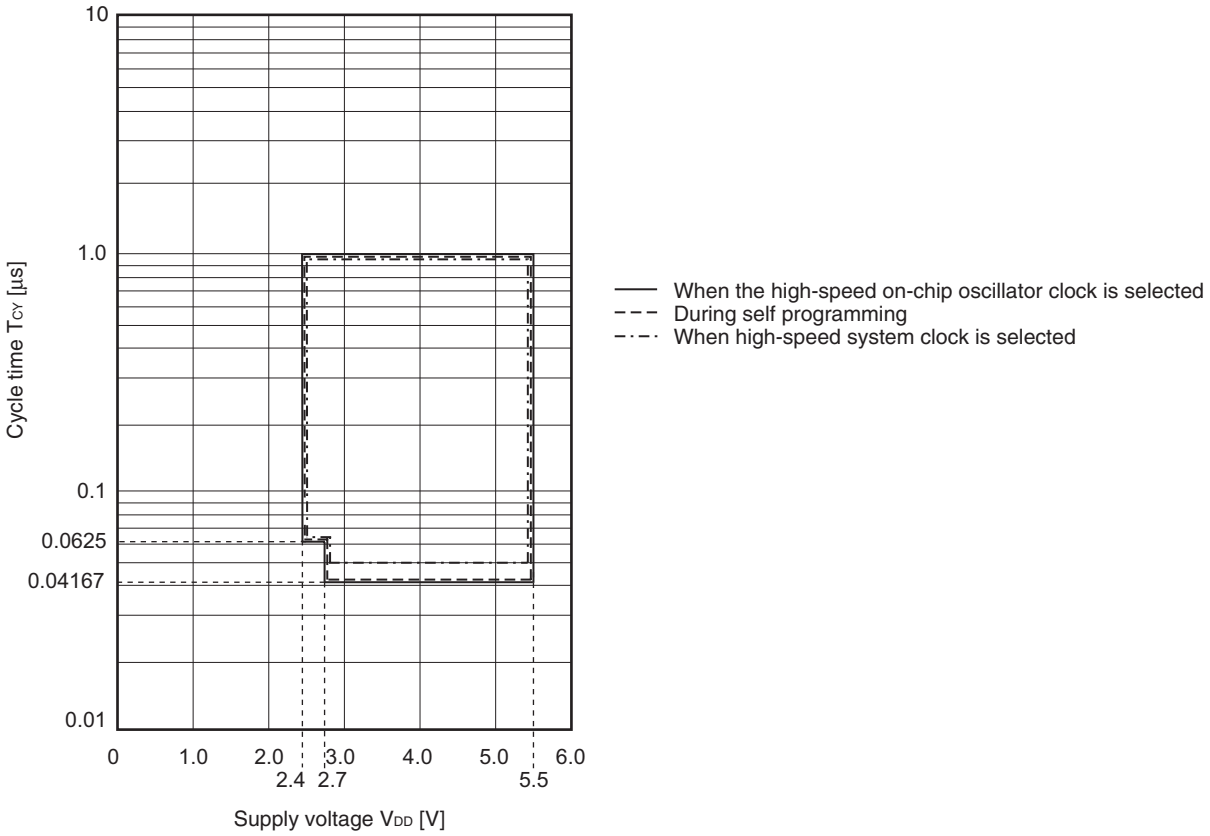
(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Items	Symbol	Conditions			MIN.	TYP.	MAX.	Unit
Instruction cycle (minimum instruction execution time)	T_{CY}	Main system clock (f_{MAIN}) operation	HS (High-speed main) mode	2.7 V ≤ V_{DD} ≤ 5.5 V	0.04167		1	μs
				2.4 V ≤ V_{DD} < 2.7 V	0.0625		1	μs
			LS (Low-speed main) mode	1.8 V ≤ V_{DD} ≤ 5.5 V	0.125		1	μs
		During self programming	HS (High-speed main) mode	2.7 V ≤ V_{DD} ≤ 5.5 V	0.04167		1	μs
				2.4 V ≤ V_{DD} < 2.7 V	0.0625		1	μs
			LS (Low-speed main) mode	1.8 V ≤ V_{DD} ≤ 5.5 V	0.125		1	μs
External main system clock frequency	f_{EX}	2.7 V ≤ V_{DD} ≤ 5.5 V			1.0		20.0	MHz
		2.4 V ≤ V_{DD} < 2.7 V			1.0		16.0	MHz
		1.8 V ≤ V_{DD} < 2.4 V			1.0		8.0	MHz
External main system clock input high-level width, low-level width	t_{EXH}, t_{EXL}	2.7 V ≤ V_{DD} ≤ 5.5 V			24			ns
		2.4 V ≤ V_{DD} < 2.7 V			30			ns
		1.8 V ≤ V_{DD} < 2.4 V			60			ns
TI00 to TI07 input high-level width, low-level width	t_{TIH}, t_{TIL}				1/f_{MCK} + 10			ns
TO00 to TO07 output frequency	f_{TO}	4.0 V ≤ V_{DD} ≤ 5.5 V					12	MHz
		2.7 V ≤ V_{DD} < 4.0 V					8	MHz
		1.8 V ≤ V_{DD} < 2.7 V					4	MHz
PCLBUZ0, or PCLBUZ1 output frequency	f_{PCL}	4.0 V ≤ V_{DD} ≤ 5.5 V					16	MHz
		2.7 V ≤ V_{DD} < 4.0 V					8	MHz
		1.8 V ≤ V_{DD} < 2.7 V					4	MHz
INTP0 to INTP5 input high-level width, low-level width	t_{INTH}, t_{INTL}				1			μs
KR0 to KR9 input available width	t_{KR}				250			ns
$\overline{\text{RESET}}$ low-level width	t_{RSL}				10			μs

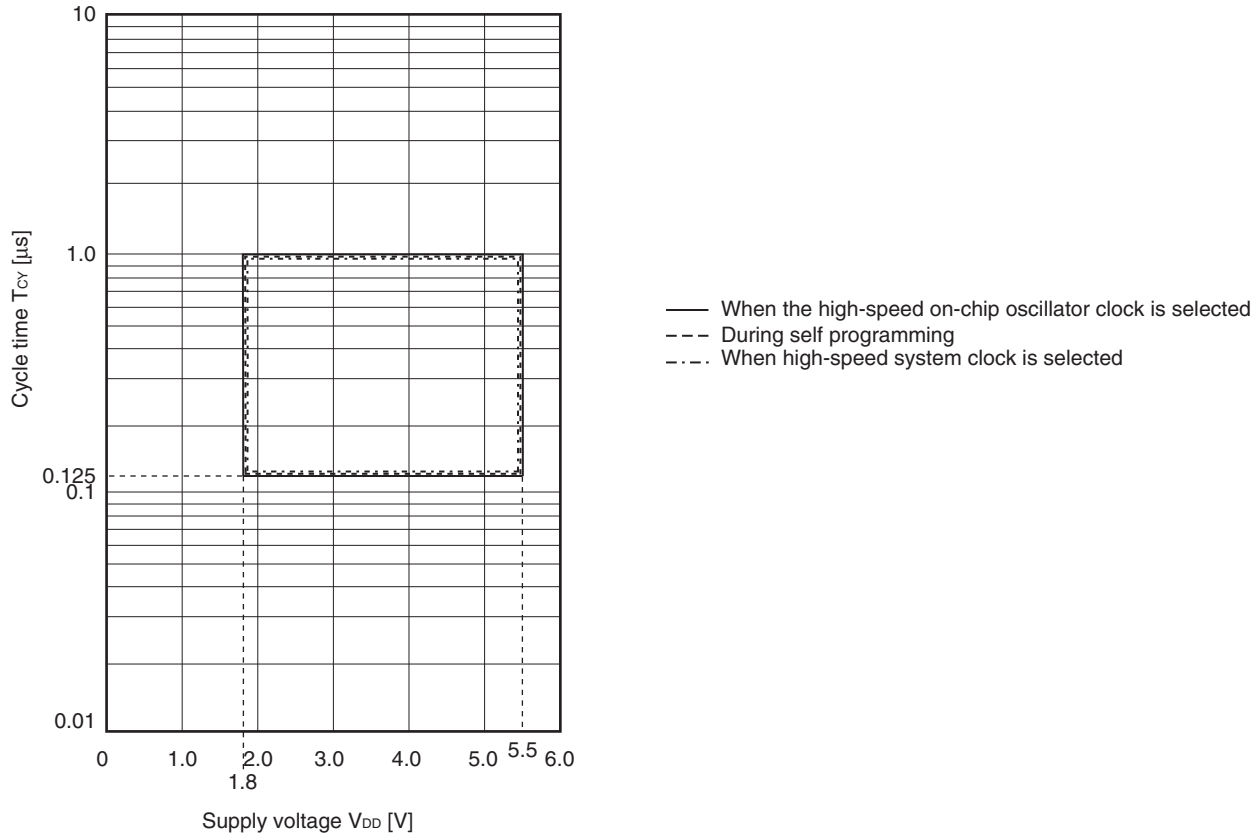
Remark f_{MCK}: Timer array unit operation clock frequency
(Operation clock to be set by the CKS0n bit of timer mode register 0n (TMR0n), and the Timer clock select register 0 (TPS0). n: Channel number (n = 0 to 7))

Minimum Instruction Execution Time during Main System Clock Operation

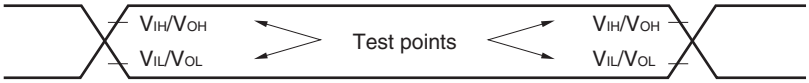
T_{CY} vs V_{DD} (HS (high-speed main) mode)



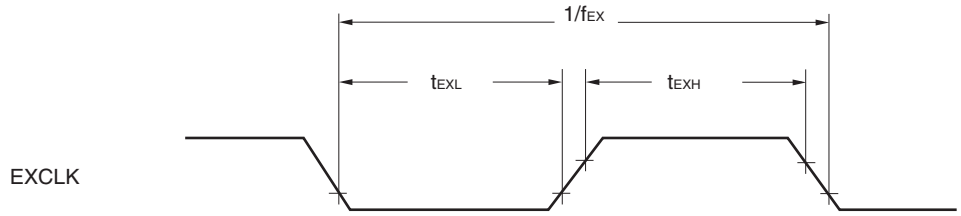
T_{CY} vs V_{DD} (LS (low-speed main) mode)



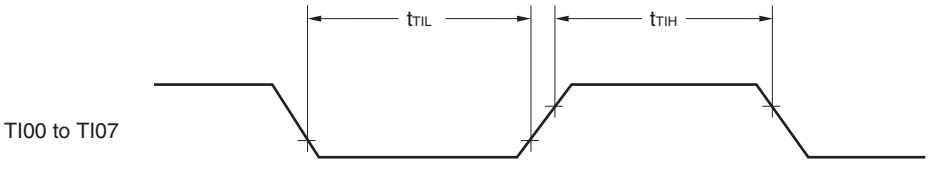
AC Timing Test Point

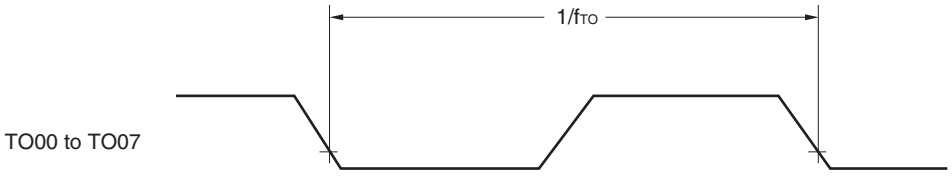


External main system clock timing

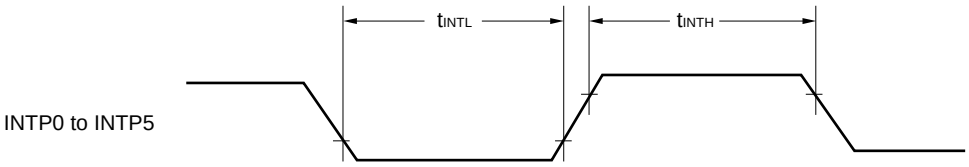


TI/TO timing

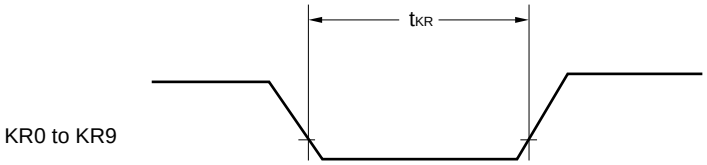




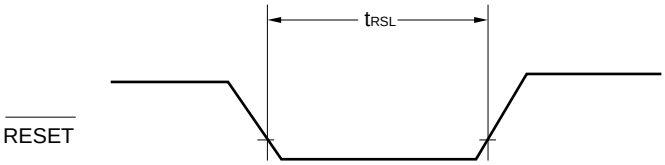
Interrupt Request Input Timing



Key Interrupt Input Timing

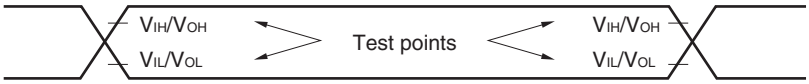


$\overline{\text{RESET}}$ input timing



28.5 Peripheral Functions Characteristics

AC Timing Test Point



28.5.1 Serial array unit

(1) During communication at same potential (UART mode)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

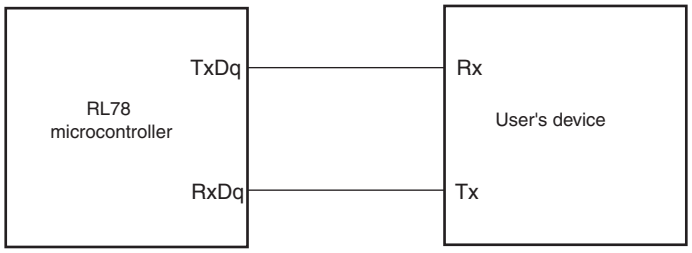
Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	
Transfer rate Note 1				f_{MCK}/6		f_{MCK}/6	bps
		Theoretical value of the maximum transfer rate $f_{CLK} = f_{MCK}$ Note2		4.0		1.3	Mbps

Notes 1. Transfer rate in the SNOOZE mode is 4800 bps only.

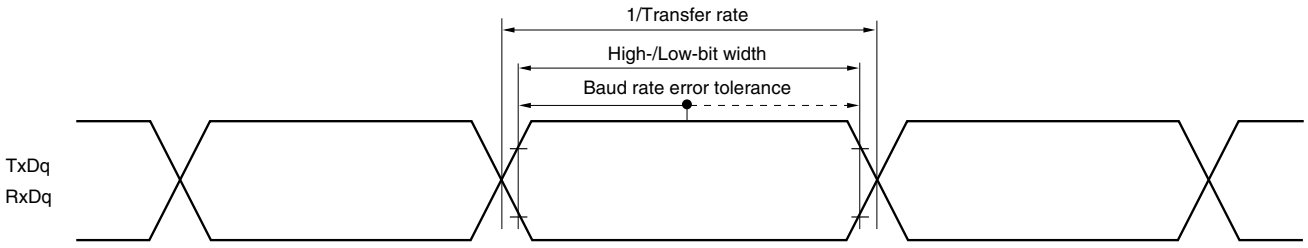
2. The maximum operating frequencies of the CPU/peripheral hardware clock (f_{CLK}) are:
HS (high-speed main) mode: 24 MHz (2.7 V ≤ V_{DD} ≤ 5.5 V)
16 MHz (2.4 V ≤ V_{DD} ≤ 5.5 V)
LS (low-speed main) mode: 8 MHz (1.8 V ≤ V_{DD} ≤ 5.5 V)

Caution Select the normal input buffer for the RxDq pin and the normal output mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg)

UART mode connection diagram (during communication at same potential)



UART mode bit width (during communication at same potential) (reference)



Remarks 1. q: UART number (q = 0 to 2), g: PIM, POM number (g = 0, 1)

2. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn), and the Serial clock select register m (SPSm). m: Unit number, n: Channel number (mn = 00 to 03, 10, 11))

(2) During communication at same potential (CSI mode) (master mode, SCK00... internal clock output, corresponding CSI00 only)

(T_A = –40 to +85°C, 2.7 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	
SCK00 cycle time	t_{KCY1}	$t_{KCY1} \geq 2/f_{CLK}$	83.3		250		ns
SCK00 high - / low-level width	t_{KH1}, t_{KL1}	4.0 V ≤ V_{DD} ≤ 5.5 V	$t_{KCY1}/2-7$		$t_{KCY1}/2-50$		ns
		2.7 V ≤ V_{DD} ≤ 5.5 V	$t_{KCY1}/2-10$		$t_{KCY1}/2-50$		ns
SI00 setup time (to SCK00↑) Note 1	t_{SIK1}	4.0 V ≤ V_{DD} ≤ 5.5 V	23		110		ns
		2.7 V ≤ V_{DD} ≤ 5.5 V	33		110		ns
SI00 hold time (to SCK00↑) Note2	t_{KSI1}		10		10		ns
Delay time from SCK00↓ to SO00 output Note 3	t_{KSO1}	C = 20 pF Note 4		10		10	ns

Notes 1. When DAP00 = 0 and CKP00 = 0, or DAP00 = 1 and CKP00 = 1. The SI00 setup time becomes "to SCK00↓" when DAP00 = 0 and CKP00 = 1, or DAP00 = 1 and CKP00 = 0.

2. When DAP00 = 0 and CKP00 = 0, or DAP00 = 1 and CKP00 = 1. The SI00 hold time becomes "from SCK00↓" when DAP00 = 0 and CKP00 = 1, or DAP00 = 1 and CKP00 = 0.

3. When DAP00 = 0 and CKP00 = 0, or DAP00 = 1 and CKP00 = 1. The delay time to SO00 output becomes "from SCK00↑" when DAP00 = 0 and CKP00 = 1, or DAP00 = 1 and CKP00 = 0.

4. C is the load capacitance of the SCK00 and SO00 output lines.

Caution Select the normal input buffer for the SI00 pin and the normal output mode for the SO00 and SCK00 pins by using port input mode register 1 (PIM1) and port output mode register 1 (POM1).

Remarks 1. This specification is valid only when CSI00's peripheral I/O redirect function is not used.

2. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKS00 bit of serial mode register (SMR00), and the Serial clock select register 0 (SPS0).

(3) During communication at same potential (CSI mode) (master mode, SCKp... internal clock output)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	
SCKp cycle time	t_{KCY1}	t_{KCY1} ≥ 4/f_{CLK}	2.7 V ≤ V_{DD} ≤ 5.5 V	167		500		ns
			2.4 V ≤ V_{DD} ≤ 5.5 V	250		500		ns
			1.8 V ≤ V_{DD} ≤ 5.5 V	–		500		ns
SCKp high-/low-level width	t_{KH1}, t_{KL1}	4.0 V ≤ V_{DD} ≤ 5.5 V		t_{KCY1}/2–12		t_{KCY1}/2–50		ns
		2.7 V ≤ V_{DD} ≤ 5.5 V		t_{KCY1}/2–18		t_{KCY1}/2–50		ns
		2.4 V ≤ V_{DD} ≤ 5.5 V		t_{KCY1}/2–38		t_{KCY1}/2–50		ns
		1.8 V ≤ V_{DD} ≤ 5.5 V		–		t_{KCY1}/2–50		ns
SIp setup time (to SCKp↑) Note 1	t_{SIK1}	4.0 V ≤ V_{DD} ≤ 5.5 V		44		110		ns
		2.7 V ≤ V_{DD} ≤ 5.5 V		44		110		ns
		2.4 V ≤ V_{DD} ≤ 5.5 V		75		110		ns
		1.8 V ≤ V_{DD} ≤ 5.5 V		–		110		ns
SIp hold time (from SCKp↑) Note 2	t_{KSI1}			19		19		ns
Delay time from SCKp↓ to SOp output Note 3	t_{KSO1}	C = 30 pF Note4			25		25	ns

Notes 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

4. C is the load capacitance of the SCKp and SOp output lines.

Caution Select the normal input buffer for the SIp pin and the normal output mode for the SOp and SCKp pins by using port input mode register 1 (PIM1) and port output mode registers 0, 1, 4 (POM0, POM1, POM4).

Remarks 1. p: CSI number (p = 00, 01, 11, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0, 1, 3: "1, 3" is for the R5F102 products only.)

2. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn), and the Serial clock select register m (SPSm). m: Unit number (m = 0, 1), n: Channel number (n = 0, 1, 3; "1, 3" is for the R5F102 products only.)

(4) During communication at same potential (CSI mode) (slave mode, SCKp... external clock input)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	
SCKp cycle time Note4	t_{KCY2}	4.0 V ≤ V_{DD} ≤ 5.5 V	20 MHz < f_{MCK}	8/f_{MCK}		–		ns
			f_{MCK} ≤ 20 MHz	6/f_{MCK}		6/f_{MCK}		ns
		2.7 V ≤ V_{DD} ≤ 5.5 V	16 MHz < f_{MCK}	8/f_{MCK}		–		ns
			f_{MCK} ≤ 16 MHz	6/f_{MCK}		6/f_{MCK}		ns
		2.4 V ≤ V_{DD} ≤ 5.5 V		6/f_{MCK} and 500		6/f_{MCK} and 500		ns
		1.8 V ≤ V_{DD} ≤ 5.5 V		–		6/f_{MCK} and 750		ns
SCKp high-/low-level width	t_{KH2}, t_{KL2}	4.0 V ≤ V_{DD} ≤ 5.5 V		t_{KCY2}/2–7		t_{KCY2}/2–7		ns
		2.7 V ≤ V_{DD} ≤ 5.5 V		t_{KCY2}/2–8		t_{KCY2}/2–8		ns
		2.4 V ≤ V_{DD} ≤ 5.5 V		t_{KCY2}/2–18		t_{KCY2}/2–18		ns
		1.8 V ≤ V_{DD} ≤ 5.5 V		–		t_{KCY2}/2–18		ns
SIp setup time (to SCKp↑) Note 1	t_{SIK2}	2.7 V ≤ V_{DD} ≤ 5.5 V		1/f_{MCK} + 20		1/f_{MCK} + 30		ns
		2.4 V ≤ V_{DD} ≤ 5.5 V		1/f_{MCK} + 30		1/f_{MCK} + 30		ns
		1.8 V ≤ V_{DD} ≤ 5.5 V		–		1/f_{MCK} + 30		ns
SIp hold time (from SCKp↑) Note 2	t_{KSI2}			1/f_{MCK} + 31		1/f_{MCK} + 31		ns
Delay time from SCKp↓ to SOp output Note 3	t_{KSO2}	C = 30 pF Note4	2.7 V ≤ V_{DD} ≤ 5.5 V		2/f_{MCK} + 44		2/f_{MCK} + 110	ns
			2.4 V ≤ V_{DD} ≤ 5.5 V		2/f_{MCK} + 75		2/f_{MCK} + 110	ns
			1.8 V ≤ V_{DD} ≤ 5.5 V		–		2/f_{MCK} + 110	ns

Notes 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

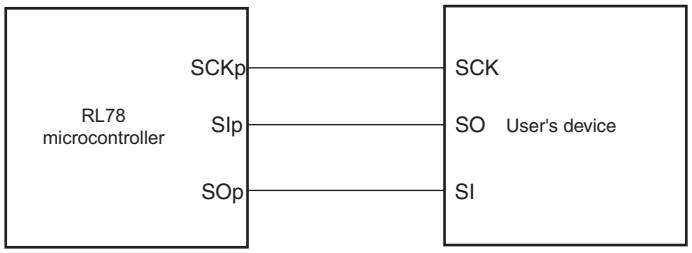
3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

4. C is the load capacitance of the SOp output lines.

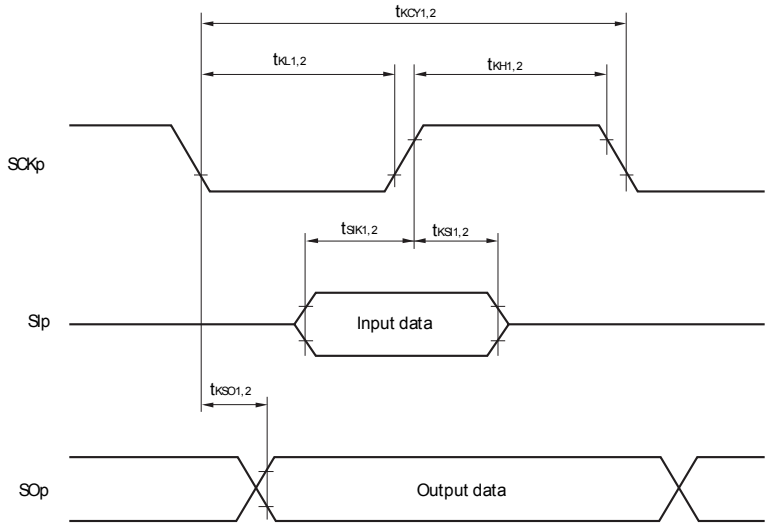
5. Transfer rate in the SNOOZE mode: MAX. 1 Mbps

Caution Select the normal input buffer for the SIp pin and the normal output mode for the SOp and SCKp pins by using port input mode register 1 (PIM1) and port output mode registers 0, 1, 4 (POM0, POM1, POM4).

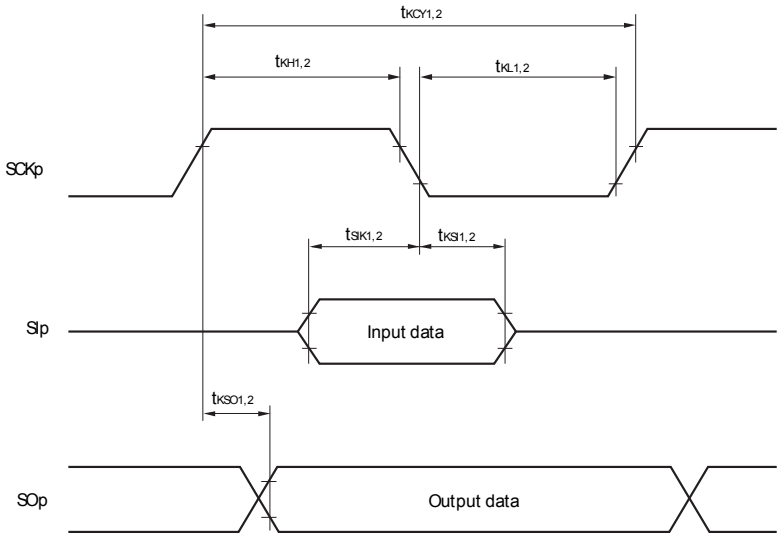
CSI mode connection diagram (during communication at same potential)



CSI mode serial transfer timing (during communication at same potential)
(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)



CSI mode serial transfer timing (during communication at same potential)
(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



(**Remarks** are listed on the next page.)

Remarks 1. p: CSI number (p = 00, 01, 11, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0, 1, 3; “1, 3” is for the R5F102 products only.)

2. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn), and the Serial clock select register m (SPSm). m: Unit number (m = 0, 1), n: Channel number (n = 0, 1, 3; “1, 3” is for the R5F102 products only.)

(5) During communication at same potential (simplified I^2C mode)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode LS (low-speed main) Mode		Unit
			MIN.	MAX.	
SCLr clock frequency	f_{SCL}	1.8 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ		400 Note 1	kHz
		1.8 V ≤ V_{DD} < 2.7 V, C_b = 100 pF, R_b = 5 kΩ		300 Note 1	kHz
Hold time when SCLr = “L”	t_{LOW}	1.8 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ	1150		ns
		1.8 V ≤ V_{DD} < 2.7 V, C_b = 100 pF, R_b = 5 kΩ	1550		ns
Hold time when SCLr = “H”	t_{HIGH}	1.8 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ	1150		ns
		1.8 V ≤ V_{DD} < 2.7 V, C_b = 100 pF, R_b = 5 kΩ	1550		ns
Data setup time (reception)	$t_{SU:DAT}$	1.8 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ	$1/f_{MCK}$ + 145 Note 2		ns
		1.8 V ≤ V_{DD} < 2.7 V, C_b = 100 pF, R_b = 5 kΩ	$1/f_{MCK}$ + 230 Note 2		ns
Data hold time (transmission)	$t_{HD:DAT}$	1.8 V ≤ V_{DD} ≤ 5.5 V, C_b = 100 pF, R_b = 3 kΩ	0	355	ns
		1.8 V ≤ V_{DD} < 2.7 V, C_b = 100 pF, R_b = 5 kΩ	0	405	ns

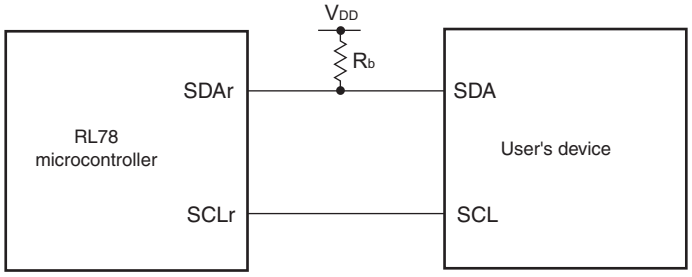
Notes 1. The value must also be equal to or less than f_{MCK}/4.

2. Set the $t_{SU:DAT}$ value to keep the hold time of SCLr = "L" and SCLr = "H".

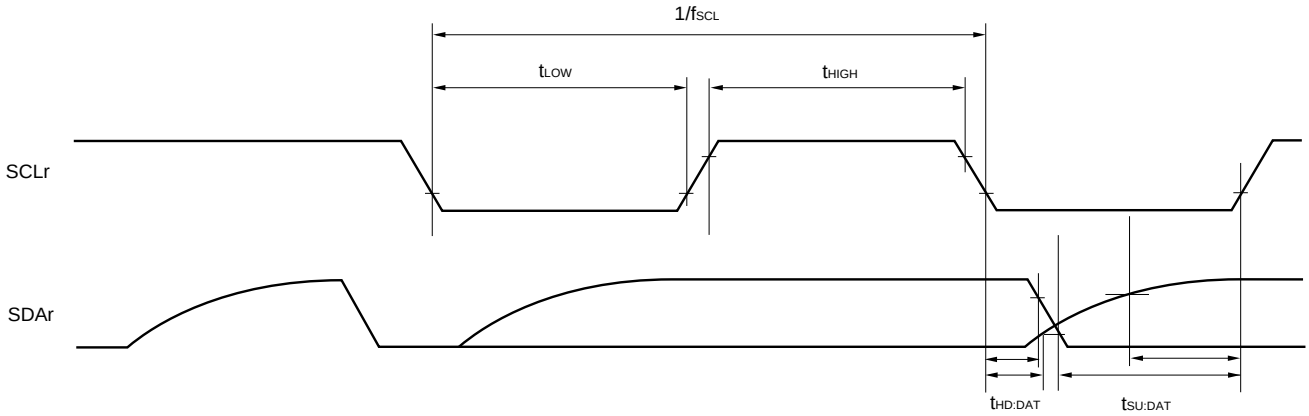
Caution Select the N-ch open drain output (V_{DD} tolerance) mode for SDAr by using port output mode register h (POMh).

(**Remarks** are listed on the next page.)

Simplified I^2C mode connection diagram (during communication at same potential)



Simplified I^2C mode serial transfer timing (during communication at same potential)



Remarks 1. R_b [Ω]:Communication line (SDAr) pull-up resistance
C_b [F]: Communication line (SCLr, SDAr) load capacitance

2. r: IIC number (r = 00, 01, 11, 20), h: = POM number (h = 0, 1, 4. 5)

3. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn), and the Serial clock select register m (SPSm). m: Unit number (m = 0, 1), n: Channel number (0, 1, 3)

4. Simplified I^2C mode is supported only by the R5F102 products.

(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions			HS (high-speed main) Mode		LS (low-speed main) Mode		Unit
					MIN.	MAX.	MIN.	MAX.	
Transfer rate Note4		Reception	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V			f_{MCK}/6 Note1		f_{MCK}/6 Note1	bps
				Theoretical value of the maximum transfer rate f_{MCK} = f_{CLK} Note3		4.0		1.3	Mbps
			2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V			f_{MCK}/6 Note1		f_{MCK}/6 Note1	bps
				Theoretical value of the maximum transfer rate f_{MCK} = f_{CLK} Note3		4.0		1.3	Mbps
			1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V			f_{MCK}/6 Notes1, 2		f_{MCK}/6 Notes1, 2	bps
				Theoretical value of the maximum transfer rate f_{MCK} = f_{CLK} Note3		4.0		1.3	Mbps
		Transmission	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V			Note4		Note4	bps
				Theoretical value of the maximum transfer rate C_b = 50 pF, R_b = 1.4 kΩ, V_b = 2.7 V		2.8 Note5		2.8 Note5	Mbps
			2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V,			Note6		Note6	bps
				Theoretical value of the maximum transfer rate C_b = 50 pF, R_b = 2.7 kΩ, V_b = 2.3 V		1.2 Note7		1.2 Note7	Mbps
			1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V			Notes 2, 8		Notes 2, 8	bps
				Theoretical value of the maximum transfer rate C_b = 50 pF, R_b = 5.5 kΩ, V_b = 1.6 V		0.43 Note9		0.43 Note9	Mbps

Notes 1. Transfer rate in the SNOOZE mode is 4800 bps only.

2. Use it with $V_{DD} \geq V_b$.

3. The maximum operating frequencies of the CPU/peripheral hardware clock (f_{CLK}) are:

HS (high-speed main) mode: 24 MHz (2.7 V ≤ V_{DD} ≤ 5.5 V)

16 MHz (2.4 V ≤ V_{DD} ≤ 5.5 V)

LS (low-speed main) mode: 8 MHz (1.8 V ≤ V_{DD} ≤ 5.5 V)

4. The smaller maximum transfer rate derived by using f_{MCK}/6 or the following expression is the valid maximum transfer rate.
Expression for calculating the transfer rate when 4.0 V ≤ V_{DD} ≤ 5.5 V and 2.7 V ≤ V_b ≤ 4.0 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{2.2}{V_b})\} \times 3} \text{ [bps]}$$

$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.2}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 \text{ [\%]}$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

5. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to **Note 4** above to calculate the maximum transfer rate under conditions of the customer.

6. The smaller maximum transfer rate derived by using f_{MCK}/6 or the following expression is the valid maximum transfer rate.
Expression for calculating the transfer rate when 2.7 V ≤ V_{DD} < 4.0 V and 2.3 V ≤ V_b ≤ 2.7 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\} \times 3} \text{ [bps]}$$

$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 \text{ [\%]}$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

7. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to **Note 6** above to calculate the maximum transfer rate under conditions of the customer.

8. The smaller maximum transfer rate derived by using f_{MCK}/6 or the following expression is the valid maximum transfer rate.
Expression for calculating the transfer rate when 1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{1.5}{V_b})\} \times 3} \text{ [bps]}$$

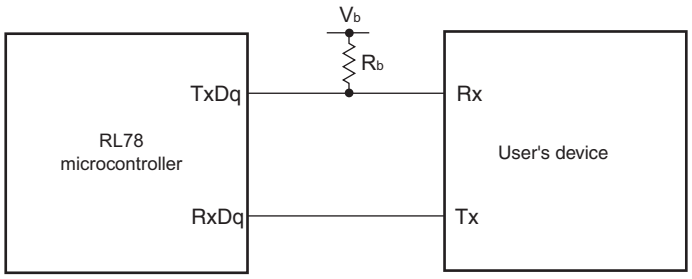
$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{1.5}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 \text{ [\%]}$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

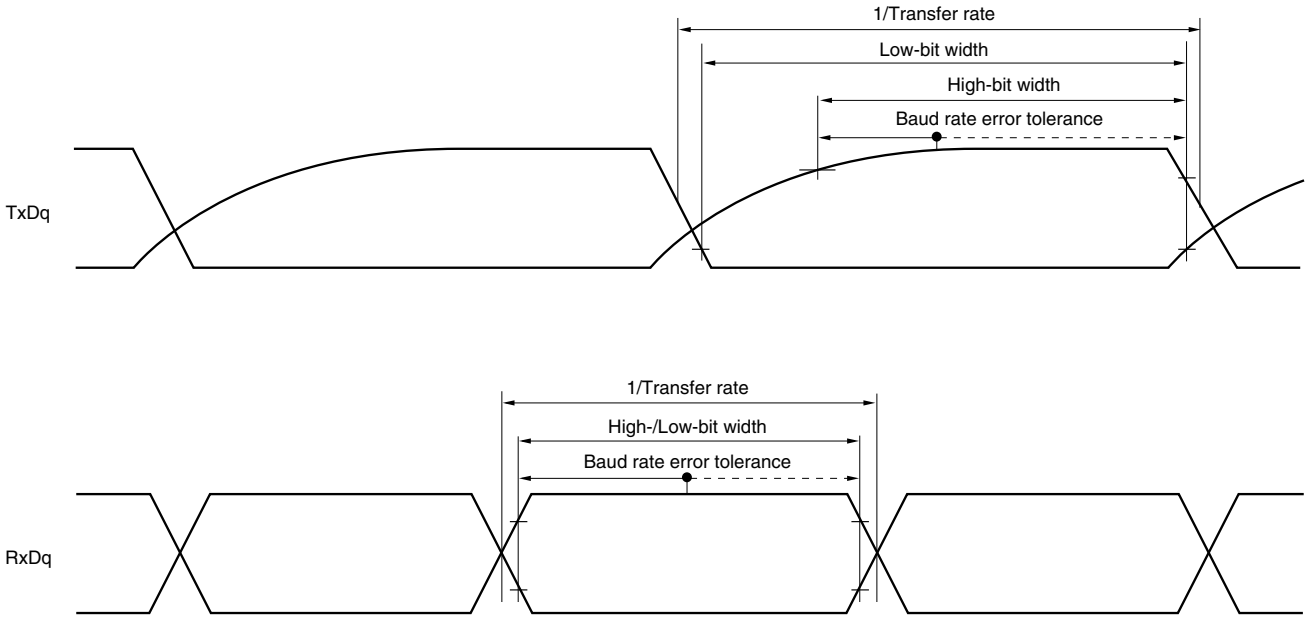
9. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to **Note 8** above to calculate the maximum transfer rate under conditions of the customer.

Caution Select the TTL input buffer for the RxDq pin and the N-ch open drain output (V_{DD} tolerance) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

UART mode connection diagram (during communication at different potential)



UART mode bit width (during communication at different potential) (reference)



Remarks 1. R_b[Ω]: Communication line (TxDq) pull-up resistance, C_b[F]: Communication line (TxDq) load capacitance, V_b[V]: Communication line voltage

2. q: UART number (q = 0 to 2), g: PIM and POM number (g = 0, 1)

3. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn), and the Serial clock select register m (SPSm). m: Unit number, n: Channel number (mn = 00 to 03, 10, 11))

4. UART0 in 20-, 24-pin products is valid the communication at different potential only when peripheral I/O redirect function is not used.

(7) Communication at different potential (2.5 V, 3 V) (CSI mode) (master mode, SCK00... internal clock output, corresponding CSI00 only)

(T_A = –40 to +85°C, 2.7 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	
SCK00 cycle time	t_{KCY1}	$t_{KCY1} \geq 2/f_{CLK}$	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 20 pF, R_b = 1.4 kΩ	200		1150		ns
			2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 20 pF, R_b = 2.7 kΩ	300		1150		ns
SCK00 high-level width	t_{KH1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 20 pF, R_b = 1.4 kΩ		t_{KCY1}/2 – 50		t_{KCY1}/2– 50		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 20 pF, R_b = 2.7 kΩ		t_{KCY1}/2 – 120		t_{KCY1}/2 – 120		ns
SCK00 low-level width	t_{KL1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 20 pF, R_b = 1.4 kΩ		t_{KCY1}/2 – 7		t_{KCY1}/2 – 50		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 20 pF, R_b = 2.7 kΩ		t_{KCY1}/2 – 10		t_{KCY1}/2 – 50		ns
SI00 setup time (to SCK00↑) Note 1	t_{SIK1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 20 pF, R_b = 1.4 kΩ		58		479		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 20 pF, R_b = 2.7 kΩ		121		479		ns
SI00 hold time (from SCK00↑) Note 1	t_{KSI1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 20 pF, R_b = 1.4 kΩ		10		10		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 20 pF, R_b = 2.7 kΩ		10		10		ns
Delay time from SCK00↓ to SO00 output Note 1	t_{KSO1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 20 pF, R_b = 1.4 kΩ			60		60	ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 20 pF, R_b = 2.7 kΩ			130		130	ns
SI00 setup time (to SCK00↓) Note 2	t_{SIK1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 20 pF, R_b = 1.4 kΩ		23		110		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 20 pF, R_b = 2.7 kΩ		33		110		ns
SI00 hold time (from SCK00↓) Note 2	t_{KSI1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 20 pF, R_b = 1.4 kΩ		10		10		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 20 pF, R_b = 2.7 kΩ		10		10		ns
Delay time from SCK00↑ to SO00 output Note 2	t_{KSO1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 20 pF, R_b = 1.4 kΩ			10		10	ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 20 pF, R_b = 2.7 kΩ			10		10	ns

(**Notes**, **Caution**, and **Remarks** are listed on the next page.)

Notes 1. When DAP00 = 0 and CKP00 = 0, or DAP00 = 1 and CKP00 = 1

2. When DAP00 = 0 and CKP00 = 1, or DAP00 = 1 and CKP00 = 0.

Caution Select the TTL input buffer for the SI00 pin and the N-ch open drain output (V_{DD} tolerance) mode for the SO00 pin and SCK00 pin by using port input mode register 1 (PIM1) and port output mode register 1 (POM1). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

Remarks 1. R_b [Ω]:Communication line (SCK00, SO00) pull-up resistance, C_b [F]: Communication line (SCK00, SO00) load capacitance, V_b [V]: Communication line voltage

2. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKS00 bit of serial mode register (SMR00), and the Serial clock select register 0 (SPS0).

(8) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output) (1/3)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	
SCKp cycle time	t_{KCY1}	t_{KCY1} ≥ 4/f_{CLK}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ	300		1150		ns
			2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ	500		1150		ns
			1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V Note, C_b = 30 pF, R_b = 5.5 kΩ	1150		1150		ns
SCKp high-level width	t_{KH1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ		t_{KCY1}/2 –75		t_{KCY1}/2–75		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ		t_{KCY1}/2 –170		t_{KCY1}/2–170		ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V Note, C_b = 30 pF, R_b = 5.5 kΩ		t_{KCY1}/2 –458		t_{KCY1}/2–458		ns
SCKp low-level width	t_{KL1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ		t_{KCY1}/2 –12		t_{KCY1}/2–50		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ		t_{KCY1}/2 –18		t_{KCY1}/2–50		ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V Note, C_b = 30 pF, R_b = 5.5 kΩ		t_{KCY1}/2 –50		t_{KCY1}/2–50		ns

Note Use it with V_{DD} ≥ V_b.

Cautions **1.** Select the TTL input buffer for the SIp pin and the N-ch open drain output (V_{DD} tolerance) mode for the SOp pin and SCKp pin by using port input mode register 1 (PIM1) and port output mode register 1 (POM1). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

2. **Communication at different potential is not allowed in CSI01, CSI11.**

Remarks 1. R_b [Ω]: Communication line (SCKp, SOp) pull-up resistance, C_b [F]: Communication line (SCKp, SOp) load capacitance, V_b [V]: Communication line voltage

2. p: CSI number (p = 00, 20)

(8) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output) (2/3)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	
SIp setup time (to SCKp↑) Note 1	t_{SIK1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ	81		479		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ	177		479		ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V Note 2, C_b = 30 pF, R_b = 5.5 kΩ	479		479		ns
SIp hold time (from SCKp↑) Note 1	t_{KSI1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ	19		19		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ	19		19		ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V Note 2, C_b = 30 pF, R_b = 5.5 kΩ	19		19		ns
Delay time from SCKp↓ to SOp output Note 1	t_{KSO1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ		100		100	ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ		195		195	ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V Note 2, C_b = 30 pF, R_b = 5.5 kΩ		483		483	ns

Notes 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.

2. Use it with $V_{DD} \geq V_b$.

(**Cautions** and **Remarks** are listed on the next page.)

(8) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output) (3/3)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	
SIp setup time (to SCKp↓) Note 1	t_{SIK1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ	44		110		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ	44		110		ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V Note 2, C_b = 30 pF, R_b = 5.5 kΩ	110		110		ns
SIp hold time (from SCKp↓) Note 1	t_{KSI1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ	19		19		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ	19		19		ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V Note 2, C_b = 30 pF, R_b = 5.5 kΩ	19		19		ns
Delay time from SCKp↑ to SOp output Note 1	t_{KSO1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ		25		25	ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ		25		25	ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V Note 2, C_b = 30 pF, R_b = 5.5 kΩ		25		25	ns

Notes 1. When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

2. Use it with $V_{DD} \geq V_b$.

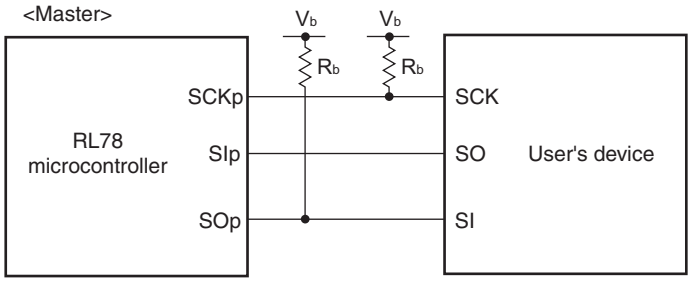
Cautions **1.** Select the TTL input buffer for the SIp pin and the N-ch open drain output (V_{DD} tolerance) mode for the SOp pin and SCKp pin by using port input mode register 1 (PIM1) and port output mode register 1 (POM1). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

2. **Communication at different potential is not allowed in CSI01, CSI11.**

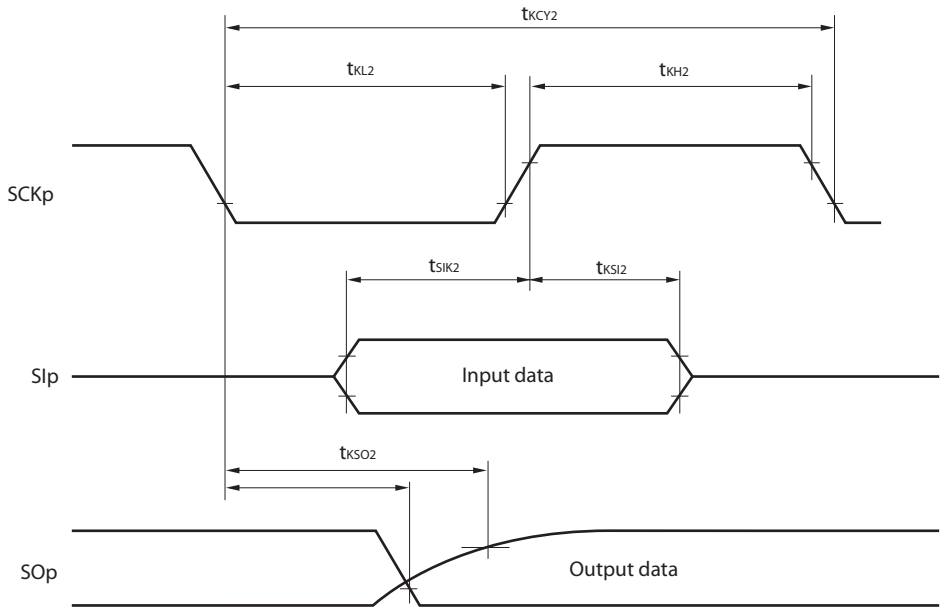
Remarks 1. R_b [Ω]: Communication line (SCKp, SOp) pull-up resistance, C_b [F]: Communication line (SCKp, SOp) load capacitance, V_b [V]: Communication line voltage

2. p: CSI number (p = 00, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0)

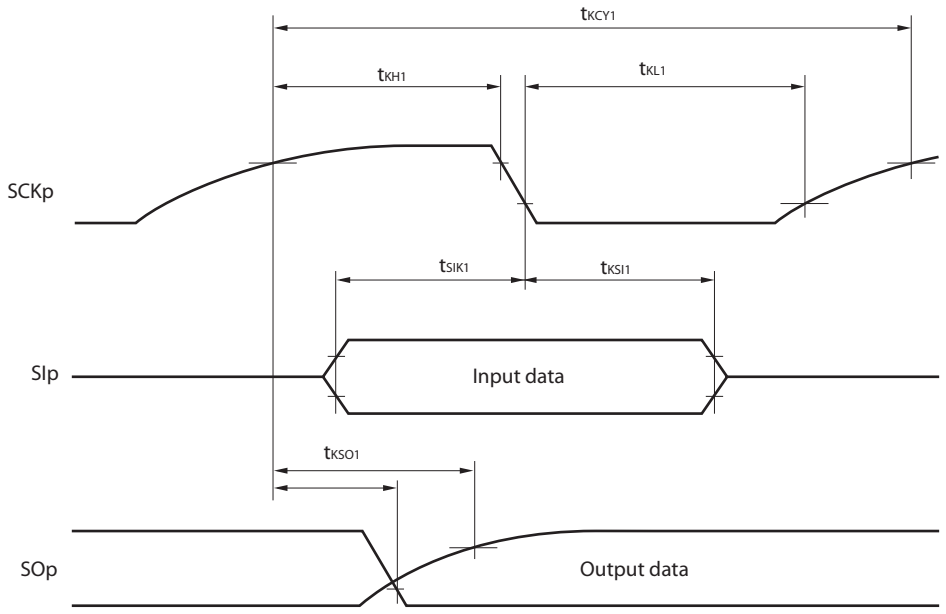
CSI mode connection diagram (during communication at different potential)



CSI mode serial transfer timing (master mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1)



CSI mode serial transfer timing (master mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



Remark p: CSI number (p = 00, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0)

(9) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (slave mode, SCKp... external clock input)
(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	
SCKp cycle time Note 1	t_{KCY2}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V	20 MHz < f_{MCK} ≤ 24 MHz	12/f_{MCK}		–		ns
			8 MHz < f_{MCK} ≤ 20 MHz	10/f_{MCK}		–		ns
			4 MHz < f_{MCK} ≤ 8 MHz	8/f_{MCK}		16/f_{MCK}		ns
			f_{MCK} ≤ 4 MHz	6/f_{MCK}		10/f_{MCK}		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V	20 MHz < f_{MCK} ≤ 24 MHz	16/f_{MCK}		–		ns
			16 MHz < f_{MCK} ≤ 20 MHz	14/f_{MCK}		–		ns
			8 MHz < f_{MCK} ≤ 16 MHz	12/f_{MCK}		–		ns
			4 MHz < f_{MCK} ≤ 8 MHz	8/f_{MCK}		16/f_{MCK}		ns
			f_{MCK} ≤ 4 MHz	6/f_{MCK}		10/f_{MCK}		ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V Note 2	20 MHz < f_{MCK} ≤ 24 MHz	36/f_{MCK}		–		ns
			16 MHz < f_{MCK} ≤ 20 MHz	32/f_{MCK}		–		ns
			8 MHz < f_{MCK} ≤ 16 MHz	26/f_{MCK}		–		ns
			4 MHz < f_{MCK} ≤ 8 MHz	16/f_{MCK}		16/f_{MCK}		ns
			f_{MCK} ≤ 4 MHz	10/f_{MCK}		10/f_{MCK}		ns
SCKp high-/low-level width	t_{KH2}, t_{KL2}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V		t_{KCY2}/2 – 12		t_{KCY2}/2 – 50		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V		t_{KCY2}/2 – 18		t_{KCY2}/2 – 50		ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V Note 2		t_{KCY2}/2 – 50		t_{KCY2}/2 – 50		ns
SIp setup time (to SCKp↑) Note 3	t_{SIK2}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V		1/f_{MCK} + 20		1/f_{MCK} + 30		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V		1/f_{MCK} + 20		1/f_{MCK} + 30		ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V Note 2		1/f_{MCK} + 30		1/f_{MCK} + 30		ns
SIp hold time (from SCKp↑) Note 4	t_{KSI2}			1/f_{MCK} + 31		1/f_{MCK} + 31		ns
Delay time from SCKp↓ to SOp output Note 5	t_{KSO2}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ			2/f_{MCK} + 120		2/f_{MCK} + 573	ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ			2/f_{MCK} + 214		2/f_{MCK} + 573	ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V Note 2, C_b = 30 pF, R_b = 5.5 kΩ			2/f_{MCK} + 573		2/f_{MCK} + 573	ns

Notes 1. Transfer rate in the SNOOZE mode: MAX. 1 Mbps

2. Use it with $V_{DD} \geq V_b$.

3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

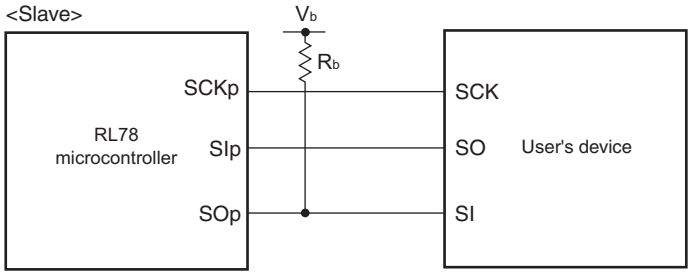
4. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

5. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Cautions **1.** Select the TTL input buffer for the SIp pin and SCKp pin, and the N-ch open drain output (V_{DD} tolerance) mode for the SOp pin by using port input mode register 1 (PIM1) and port output mode register 1 (POM1). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

2. **Communication at different potential is not allowed in CSI01, CSI11.**

CSI mode connection diagram (during communication at different potential)

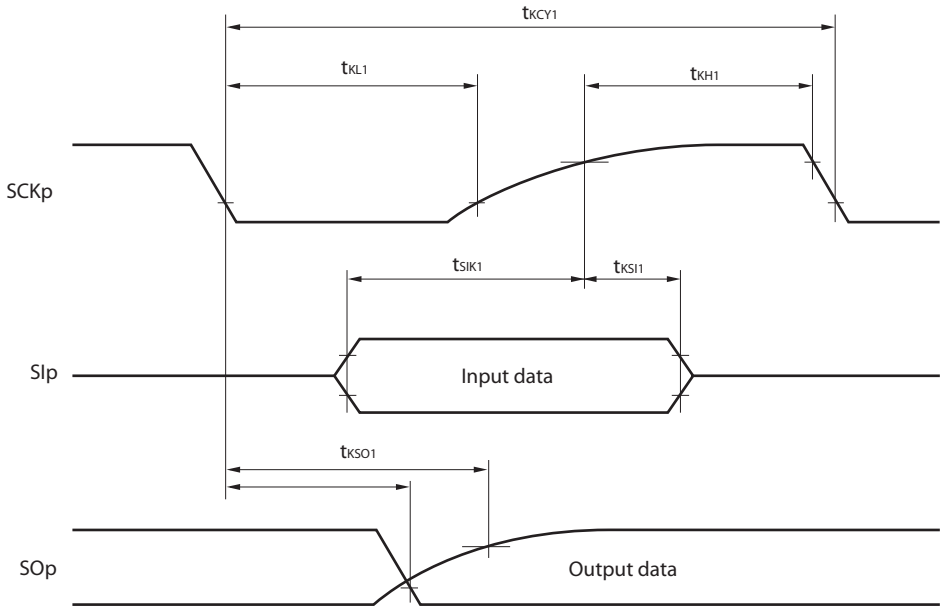


Remarks 1. R_b [Ω]: Communication line (SOp) pull-up resistance, C_b [F]: Communication line (SOp) load capacitance, V_b [V]: Communication line voltage

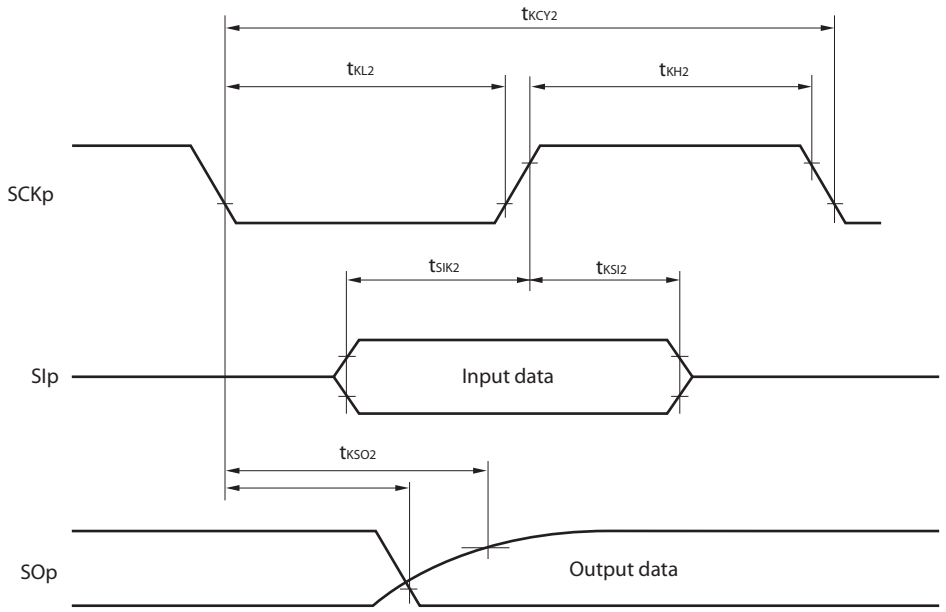
2. p: CSI number (p = 00, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0)

3. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn), and the Serial clock select register m (SPSm). m: Unit number, n: Channel number (mn = 00, 10)

CSI mode serial transfer timing (slave mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)



CSI mode serial transfer timing (slave mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



Remark p: CSI number (p = 00, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0)

(10) Communication at different potential (1.8 V, 2.5 V, 3 V) (simplified I^2C mode)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	
SCLr clock frequency	f_{SCL}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 100 pF, R_b = 2.8 kΩ		400 Note1		300 Note1	kHz
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 100 pF, R_b = 2.7 kΩ		400 Note1		300 Note1	kHz
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, Note2 C_b = 100 pF, R_b = 5.5 kΩ		300 Note1		300 Note1	kHz
Hold time when SCLr = "L"	t_{LOW}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 100 pF, R_b = 2.8 kΩ	1150		1550		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 100 pF, R_b = 2.7 kΩ	1150		1550		ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, Note2 C_b = 100 pF, R_b = 5.5 kΩ	1550		1550		ns
Hold time when SCLr = "H"	t_{HIGH}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 100 pF, R_b = 2.8 kΩ	675		610		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 100 pF, R_b = 2.7 kΩ	600		610		ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, Note2 C_b = 100 pF, R_b = 5.5 kΩ	610		610		ns
Data setup time (reception)	$t_{SU:DAT}$	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 100 pF, R_b = 2.8 kΩ	1/f_{MCK} + 190 Note3		1/f_{MCK} + 190 Note3		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 100 pF, R_b = 2.7 kΩ	1/f_{MCK} + 190 Note3		1/f_{MCK} + 190 Note3		ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, Note2 C_b = 100 pF, R_b = 5.5 kΩ	1/f_{MCK} + 190 Note3		1/f_{MCK} + 190 Note3		ns
Data setup time (transmission)"	$t_{HD:DAT}$	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 100 pF, R_b = 2.8 kΩ	0	355	0	355	ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 100 pF, R_b = 2.7 kΩ	0	355	0	355	ns
		1.8 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, Note2 C_b = 100 pF, R_b = 5.5 kΩ	0	405	0	405	ns

Notes 1. The value must also be equal to or less than f_{MCK}/4.

2. Use it with $V_{DD} \geq V_b$.

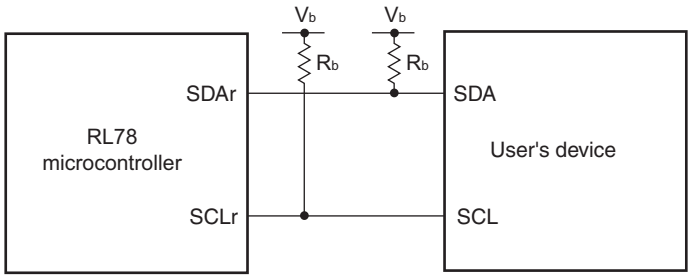
3. Set the $t_{SU:DAT}$ value to keep the hold time of SCLr = "L" and SCLr = "H".

Cautions **1.** Select the TTL input buffer and the N-ch open drain output (VDD tolerance) mode for the SDAr pin and the N-ch open drain output (VDD tolerance) mode for the SCLr pin by using port input mode register 1 (PIM1) and port output mode register 1 (POM1). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

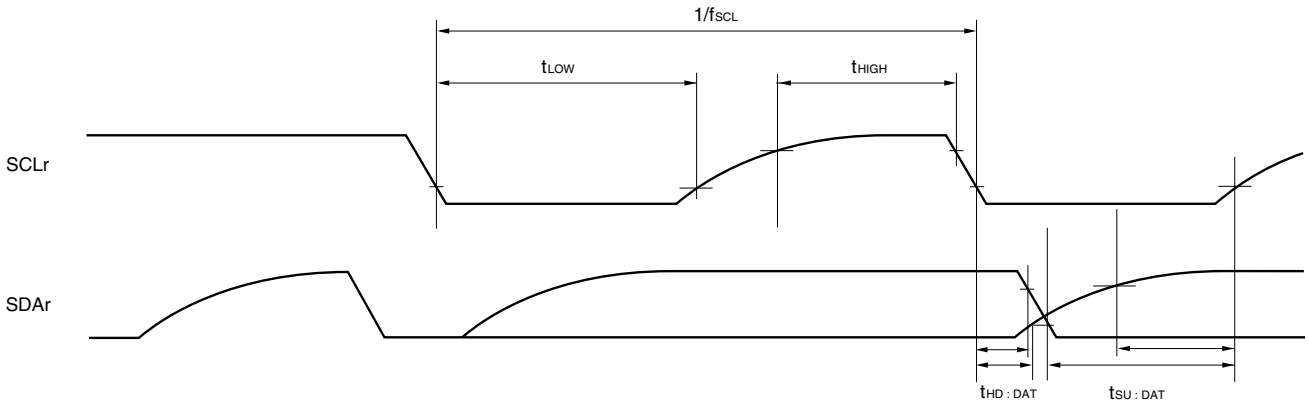
2. **Communication at different potential is not allowed in IIC01, IIC11.**

(**Remarks** are listed on the next page.)

Simplified I^2C mode connection diagram (during communication at different potential)



Simplified I^2C mode serial transfer timing (during communication at different potential)



Remarks 1. R_b [Ω]: Communication line (SDAr, SCLr) pull-up resistance, C_b [F]: Communication line (SDAr, SCLr) load capacitance, V_b [V]: Communication line voltage

2. r: IIC Number (r = 00, 20)

3. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn), and the Serial clock select register m (SPSm). m: Unit number (m = 0,1), n: Channel number (n = 0))

4. Simplified I^2C mode is supported only by the R5F102 products.

28.5.2 Serial interface IICA

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode / LS (low-speed main) Mode				Unit
			Standard Mode		Fast Mode		
			MIN.	MAX.	MIN.	MAX.	
SCLA0 clock frequency	f_{SCL}	Fast mode: f_{CLK} ≥ 3.5 MHz			0	400	kHz
		Normal mode: f_{CLK} ≥ 1 MHz	0	100			kHz
Setup time of restart condition	$t_{SU:STA}$		4.7		0.6		μs
Hold time Note 1	$t_{HD:STA}$		4.0		0.6		μs
Hold time when SCLA0 = "L"	t_{LOW}		4.7		1.3		μs
Hold time when SCLA0 = "H"	t_{HIGH}		4.0		0.6		μs
Data setup time (reception)	$t_{SU:DAT}$		250		100		ns
Data hold time (transmission) Note 2	$t_{HD:DAT}$		0	3.45	0	0.9	μs
Setup time of stop condition	$t_{SU:STO}$		4.0		0.6		μs
Bus-free time	t_{BUF}		4.7		1.3		μs

Notes 1. The first clock pulse is generated after this period when the start/restart condition is detected.

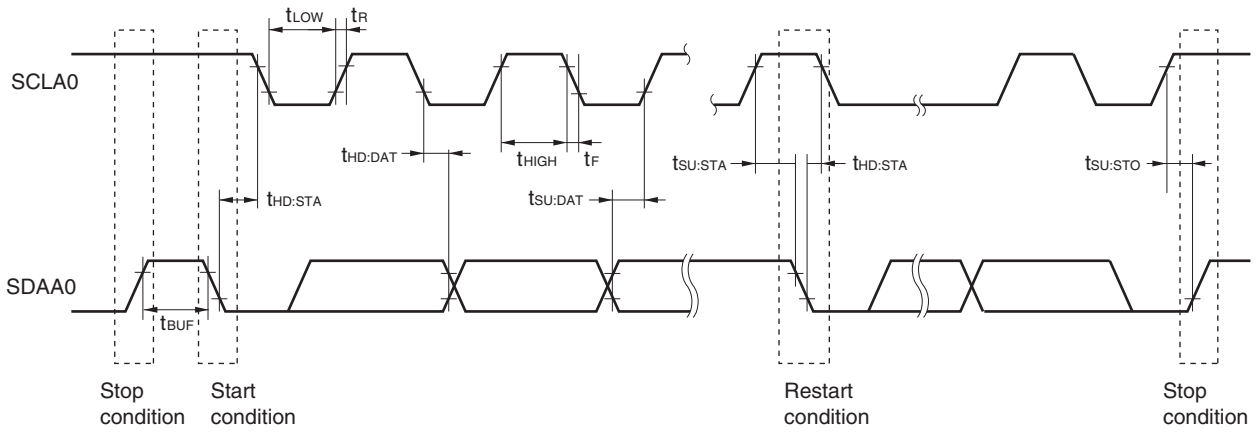
2. The maximum value (MAX.) of $t_{HD:DAT}$ is during normal transfer and a wait state is inserted in the $\overline{ACK}$ (acknowledge) timing.

Caution The values in the above table are applied even when bit 2 (PIOR2) in the peripheral I/O redirection register (PIOR) is 1 in 30-pin products only. At this time, the pin characteristics (I_{OH1}, I_{OL1}, V_{OH1}, V_{OL1}) must satisfy the values in the redirect destination.

Remark The maximum value of C_b (communication line capacitance) and the value of R_b (communication line pull-up resistor) at that time in each mode are as follows.

Normal mode: C_b = 400 pF, Rb = 2.7 kΩ
Fast mode: C_b = 320 pF, Rb = 1.1 kΩ

IICA serial transfer timing



28.6 Analog Characteristics

28.6.1 A/D converter characteristics

Classification of A/D converter characteristics

Input channel	Reference Voltage		
	Reference voltage (+) = AV_{REFP} Reference voltage (–) = AV_{REFM}	Reference voltage (+) = V_{DD} Reference voltage (–) = V_{SS}	Reference voltage (+) = V_{BGR} Reference voltage (–) = AV_{REFM}
ANI0 to ANI3	Refer to **28.6.1 (1)**.	Refer to **28.6.1 (3)**.	Refer to **28.6.1 (4)**.
ANI16 to ANI22	Refer to **28.6.1 (2)**.		
Internal reference voltage Temperature sensor output voltage	Refer to **28.6.1 (1)**.		–

(1) When reference voltage (+) = AV_{REFP}/ANI0 (ADREFP1 = 0, ADREFP0 = 1), reference voltage (–) = AV_{REFM}/ANI1 (ADREFM = 1), target pin: ANI2, ANI3, internal reference voltage, and temperature sensor output voltage

(T_A = –40 to +85°C, 1.8 V ≤ AV_{REFP} ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, Reference voltage (+) = AV_{REFP}, Reference voltage (–) = AV_{REFM} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error[Note 1]	AINL	10-bit resolution AV_{REFP} = V_{DD} [Note 3]			1.2	±3.5	LSB
					1.2	±7.0 [Note 4]	LSB
Conversion time	t_{CONV}	10-bit resolution Target pin: ANI2, ANI3	3.6 V ≤ V_{DD} ≤ 5.5 V	2.125		39	μs
			2.7 V ≤ V_{DD} ≤ 5.5 V	3.1875		39	μs
			1.8 V ≤ V_{DD} ≤ 5.5 V	17		39	μs
				57		95	μs
		10-bit resolution Target pin: Internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	3.6 V ≤ V_{DD} ≤ 5.5 V	2.375		39	μs
			2.7 V ≤ V_{DD} ≤ 5.5 V	3.5625		39	μs
			2.4 V ≤ V_{DD} ≤ 5.5 V	17		39	μs
Zero-scale error[Notes 1, 2]	EZS	10-bit resolution AV_{REFP} = V_{DD} [Note 3]				±0.25	%FSR
						±0.50 [Note 4]	%FSR
Full-scale error[Notes 1, 2]	EFS	10-bit resolution AV_{REFP} = V_{DD} [Note 3]				±0.25	%FSR
						±0.50 [Note 4]	%FSR
Integral linearity error[Note 1]	ILE	10-bit resolution AV_{REFP} = V_{DD} [Note 3]				±2.5	LSB
						±5.0 [Note 4]	LSB
Differential linearity error [Note 1]	DLE	10-bit resolution AV_{REFP} = V_{DD} [Note 3]				±1.5	LSB
						±2.0 [Note 4]	LSB
Analog input voltage	V_{AIN}	ANI2, ANI3		0		AV_{REFP}	V
		Internal reference voltage (2.4 V ≤ V_{DD} ≤ 5.5 V, HS (high-speed main) mode)		V_{BGR} [Note 5]			V
		Temperature sensor output voltage (2.4 V ≤ V_{DD} ≤ 5.5 V, HS (high-speed main) mode)		V_{TMPS25} [Note 5]			V

(**Notes** are listed on the next page.)

Notes 1. Excludes quantization error (±1/2 LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. When $AV_{REFP} < V_{DD}$, the MAX. values are as follows.
Overall error: Add ±1.0 LSB to the MAX. value when $AV_{REFP} = V_{DD}$.
Zero-scale error/Full-scale error: Add ±0.05%FSR to the MAX. value when $AV_{REFP} = V_{DD}$.
Integral linearity error/ Differential linearity error: Add ±0.5 LSB to the MAX. value when $AV_{REFP} = V_{DD}$.

4. Values when the conversion time is set to 57 μs (min.) and 95 μs (max.).

5. Refer to **28.6.2 Temperature sensor/internal reference voltage characteristics**.

(2) When reference voltage (+) = AV_{REFP}/ANI0 (ADREFP1 = 0, ADREFP0 = 1), reference voltage (–) = AV_{REFM}/ANI1 (ADREFM = 1), target pin: ANI16 to ANI22

(T_A = –40 to +85°C, 1.8 V ≤ AV_{REFP} ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, Reference voltage (+) = AV_{REFP}, Reference voltage (–) = AV_{REFM} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error Note 1	AINL	10-bit resolution $AV_{REFP} = V_{DD}$ Note 3			1.2	±5.0	LSB
					1.2	±8.5 Note 4	LSB
Conversion time	t_{CONV}	10-bit resolution Target ANI pin: ANI16 to ANI22	3.6 V ≤ V_{DD} ≤ 5.5 V	2.125		39	μs
			2.7 V ≤ V_{DD} ≤ 5.5 V	3.1875		39	μs
			1.8 V ≤ V_{DD} ≤ 5.5 V	17		39	μs
				57		95	μs
Zero-scale error Notes 1, 2	EZS	10-bit resolution $AV_{REFP} = V_{DD}$ Note 3				±0.35	%FSR
						±0.60 Note 4	%FSR
Full-scale error Notes 1, 2	EFS	10-bit resolution $AV_{REFP} = V_{DD}$ Note 3				±0.35	%FSR
						±0.60 Note 4	%FSR
Integral linearity error Note 1	ILE	10-bit resolution $AV_{REFP} = V_{DD}$ Note 3				±3.5	LSB
						±6.0 Note 4	LSB
Differential linearity error Note 1	DLE	10-bit resolution $AV_{REFP} = V_{DD}$ Note 3				±2.0	LSB
						±2.5 Note 4	LSB
Analog input voltage	V_{AIN}	ANI16 to ANI22		0		AV_{REFP} and V_{DD}	V

Notes 1. Excludes quantization error (±1/2 LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. When $AV_{REFP} \leq V_{DD}$, the MAX. values are as follows.
Overall error: Add ±4.0 LSB to the MAX. value when $AV_{REFP} = V_{DD}$.
Zero-scale error/Full-scale error: Add ±0.20%FSR to the MAX. value when $AV_{REFP} = V_{DD}$.
Integral linearity error/ Differential linearity error: Add ±2.0 LSB to the MAX. value when $AV_{REFP} = V_{DD}$.

4. When the conversion time is set to 57 μs (min.) and 95 μs (max.).

(3) When reference voltage (+) = V_{DD} (ADREFP1 = 0, ADREFP0 = 0), reference voltage (–) = V_{SS} (ADREFM = 0), target pin: ANI0 to ANI3, ANI16 to ANI22, internal reference voltage, and temperature sensor output voltage

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, Reference voltage (+) = V_{DD}, Reference voltage (–) = V_{SS})

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error Note 1	AINL	10-bit resolution			1.2	±7.0	LSB
					1.2	±10.5 Note 3	LSB
Conversion time	t_{CONV}	10-bit resolution Target pin: ANI0 to ANI3, ANI16 to ANI22	3.6 V ≤ V_{DD} ≤ 5.5 V	2.125		39	μs
			2.7 V ≤ V_{DD} ≤ 5.5 V	3.1875		39	μs
			1.8 V ≤ V_{DD} ≤ 5.5 V	17		39	μs
				57		95	μs
Conversion time	t_{CONV}	10-bit resolution Target pin: internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	3.6 V ≤ V_{DD} ≤ 5.5 V	2.375		39	μs
			2.7 V ≤ V_{DD} ≤ 5.5 V	3.5625		39	μs
			2.4 V ≤ V_{DD} ≤ 5.5 V	17		39	μs
Zero-scale error Notes 1, 2	EZS	10-bit resolution				±0.60	%FSR
						±0.85 Note 3	%FSR
Full-scale error Notes 1, 2	EFS	10-bit resolution				±0.60	%FSR
						±0.85 Note 3	%FSR
Integral linearity error Note 1	ILE	10-bit resolution				±4.0	LSB
						±6.5 Note 3	LSB
Differential linearity error Note 1	DLE	10-bit resolution				±2.0	LSB
						±2.5 Note 3	LSB
Analog input voltage	V_{AIN}	ANI0 to ANI3, ANI16 to ANI22		0		V_{DD}	V
		Internal reference voltage (2.4 V ≤ V_{DD} ≤ 5.5 V, HS (high-speed main) mode)		V_{BGR} Note 4			V
		Temperature sensor output voltage (2.4 V ≤ V_{DD} ≤ 5.5 V, HS (high-speed main) mode)		V_{TMPS25} Note 4			V

Notes 1. Excludes quantization error (±1/2 LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. When the conversion time is set to 57 μs (min.) and 95 μs (max.).

4. Refer to **28.6.2 Temperature sensor/internal reference voltage characteristics**.

(4) When reference voltage (+) = Internal reference voltage (ADREFP1 = 1, ADREFP0 = 0), reference voltage (–) = AV_{REFM} (ADREFM = 1), target pin: ANI0, ANI2, ANI3, and ANI16 to ANI22

(T_A = –40 to +85°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, Reference voltage (+) = V_{BGR} Note 3, Reference voltage (–) = AV_{REFM} Note 4 = 0 V, HS (high-speed main) mode)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution	RES			8		bit
Conversion time	t_{CONV}	8-bit resolution	17		39	μs
Zero-scale error Notes 1, 2	EZS	8-bit resolution			±0.60	%FSR
Integral linearity error Note 1	ILE	8-bit resolution			±2.0	LSB
Differential linearity error Note 1	DLE	8-bit resolution			±1.0	LSB
Analog input voltage	V_{AIN}		0		V_{BGR} Note 3	V

Notes 1. Excludes quantization error (±1/2 LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. Refer to **28.6.2 Temperature sensor/internal reference voltage characteristics**.

4. When reference voltage (–) = V_{SS}, the MAX. values are as follows.
Zero-scale error: Add ±0.35%FSR to the MAX. value when reference voltage (–) = AV_{REFM}.
Integral linearity error: Add ±0.5 LSB to the MAX. value when reference voltage (–) = AV_{REFM}.
Differential linearity error: Add ±0.2 LSB to the MAX. value when reference voltage (–) = AV_{REFM}.

28.6.2 Temperature sensor characteristics

(T_A = –40 to +85°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, HS (high-speed main) mode

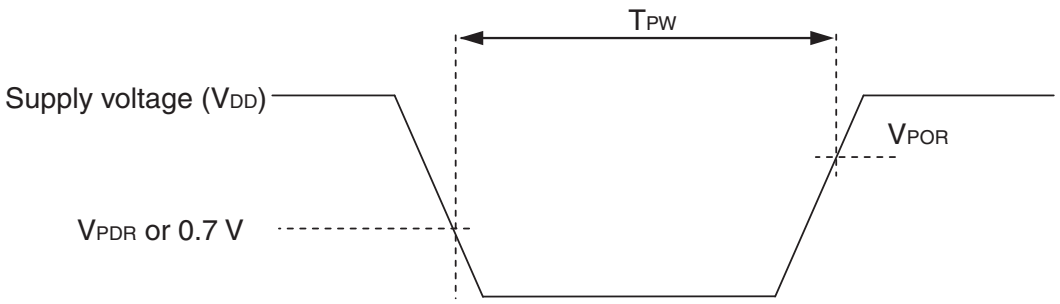
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Temperature sensor output voltage	V_{TMPS25}	Setting ADS register = 80H, T_A = +25°C		1.05		V
Reference output voltage	V_{BGR}	Setting ADS register = 81H	1.38	1.45	1.50	V
Temperature coefficient	F_{VTMPS}	Temperature sensor output voltage that depends on the temperature		–3.6		mV/°C
Operation stabilization wait time	t_{AMP}		5			μs

28.6.3 POR circuit characteristics

(T_A = –40 to +85°C, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	V_{POR}	Power supply rise time	1.47	1.51	1.55	V
	V_{PDR}	Power supply fall time	1.46	1.50	1.54	V
Minimum pulse width Note	T_{PW}		300			μs

Note Minimum time required for a POR reset when V_{DD} exceeds below V_{PDR}. This is also the minimum time required for a POR reset from when V_{DD} exceeds below 0.7 V to when V_{DD} exceeds V_{POR} while STOP mode is entered or the main system clock is stopped through setting bit 0 (HIOSTOP) and bit 7 (MSTOP) in the clock operation status control register (CSC).



28.6.4 LVD circuit characteristics

LVD Detection Voltage of Reset Mode and Interrupt Mode

(T_A = –40 to +85°C, $V_{PDR} \leq V_{DD} \leq$ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection supply voltage	V_{LVD0}	Power supply rise time	3.98	4.06	4.14	V
		Power supply fall time	3.90	3.98	4.06	V
	V_{LVD1}	Power supply rise time	3.68	3.75	3.82	V
		Power supply fall time	3.60	3.67	3.74	V
	V_{LVD2}	Power supply rise time	3.07	3.13	3.19	V
		Power supply fall time	3.00	3.06	3.12	V
	V_{LVD3}	Power supply rise time	2.96	3.02	3.08	V
		Power supply fall time	2.90	2.96	3.02	V
	V_{LVD4}	Power supply rise time	2.86	2.92	2.97	V
		Power supply fall time	2.80	2.86	2.91	V
	V_{LVD5}	Power supply rise time	2.76	2.81	2.87	V
		Power supply fall time	2.70	2.75	2.81	V
	V_{LVD6}	Power supply rise time	2.66	2.71	2.76	V
		Power supply fall time	2.60	2.65	2.70	V
	V_{LVD7}	Power supply rise time	2.56	2.61	2.66	V
		Power supply fall time	2.50	2.55	2.60	V
	V_{LVD8}	Power supply rise time	2.45	2.50	2.55	V
		Power supply fall time	2.40	2.45	2.50	V
	V_{LVD9}	Power supply rise time	2.05	2.09	2.13	V
		Power supply fall time	2.00	2.04	2.08	V
	V_{LVD10}	Power supply rise time	1.94	1.98	2.02	V
		Power supply fall time	1.90	1.94	1.98	V
	V_{LVD11}	Power supply rise time	1.84	1.88	1.91	V
		Power supply fall time	1.80	1.84	1.87	V
Minimum pulse width	t_{LW}		300			μs
Detection delay time					300	μs

LVD detection voltage of interrupt & reset mode

(T_A = –40 to +85°C, $V_{PDR} \leq V_{DD} \leq$ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Interrupt and reset mode	V_{LVDB0}	V_{POC2}, V_{POC1}, V_{POC0} = 0, 0, 1, falling reset voltage		1.80	1.84	1.87	V
	V_{LVDB1}	LVIS1, LVIS0 = 1, 0	Rising reset release voltage	1.94	1.98	2.02	V
			Falling interrupt voltage	1.90	1.94	1.98	V
	V_{LVDB2}	LVIS1, LVIS0 = 0, 1	Rising reset release voltage	2.05	2.09	2.13	V
			Falling interrupt voltage	2.00	2.04	2.08	V
	V_{LVDB3}	LVIS1, LVIS0 = 0, 0	Rising reset release voltage	3.07	3.13	3.19	V
			Falling interrupt voltage	3.00	3.06	3.12	V
	V_{LVDC0}	V_{POC2}, V_{POC1}, V_{POC0} = 0, 1, 0, falling reset voltage		2.40	2.45	2.50	V
	V_{LVDC1}	LVIS1, LVIS0 = 1, 0	Rising reset release voltage	2.56	2.61	2.66	V
			Falling interrupt voltage	2.50	2.55	2.60	V
	V_{LVDC2}	LVIS1, LVIS0 = 0, 1	Rising reset release voltage	2.66	2.71	2.76	V
			Falling interrupt voltage	2.60	2.65	2.70	V
	V_{LVDC3}	LVIS1, LVIS0 = 0, 0	Rising reset release voltage	3.68	3.75	3.82	V
			Falling interrupt voltage	3.60	3.67	3.74	V
	V_{LVDD0}	V_{POC2}, V_{POC1}, V_{POC1} = 0, 1, 1, falling reset voltage		2.70	2.75	2.81	V
	V_{LVDD1}	LVIS1, LVIS0 = 1, 0	Rising reset release voltage	2.86	2.92	2.97	V
			Falling interrupt voltage	2.80	2.86	2.91	V
	V_{LVDD2}	LVIS1, LVIS0 = 0, 1	Rising reset release voltage	2.96	3.02	3.08	V
			Falling interrupt voltage	2.90	2.96	3.02	V
	V_{LVDD3}	LVIS1, LVIS0 = 0, 0	Rising reset release voltage	3.98	4.06	4.14	V
			Falling interrupt voltage	3.90	3.98	4.06	V

28.6.5 Power supply voltage rising slope characteristics

(T_A = –40 to +85°C, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Power supply voltage rising slope	S_{VDD}				54	V/ms

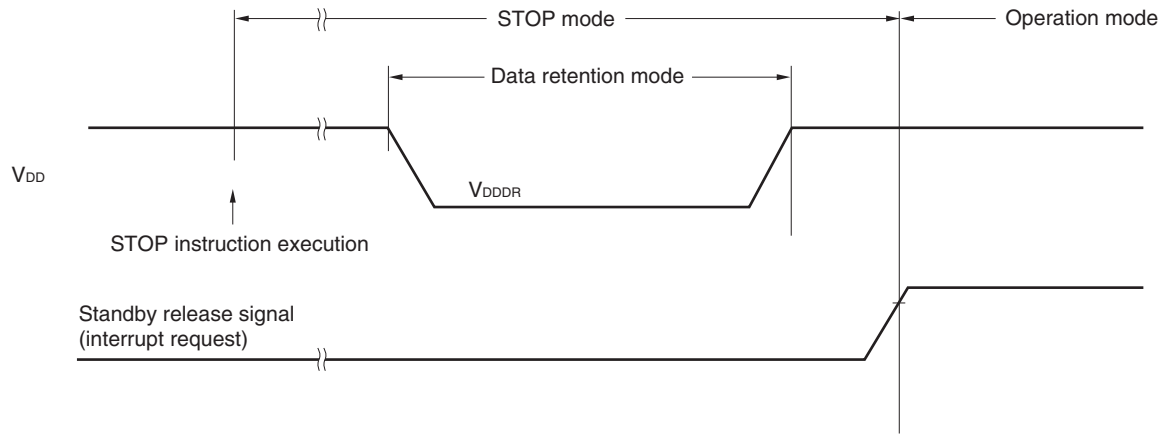
Caution Make sure to keep the internal reset state by the LVD circuit or an external reset until V_{DD} reaches the operating voltage range shown in 28.4 AC Characteristics.

28.7 Data Memory STOP Mode Low Supply Voltage Data Retention Characteristics

(T_A = –40 to +85°C, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Data retention supply voltage	V_{DDDR}		1.46 Note		5.5	V

Note The value depends on the POR detection voltage. When the voltage drops, the data is retained before a POR reset is affected, but data is not retained when a POR reset is affected.



28.8 Flash Memory Programming Characteristics

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
System clock frequency	f_{CLK}			1		24	MHz
Code flash memory rewritable times Notes 1, 2, 3	C_{erwr}	Retained for 20 years	T_A = 85°C	1,000			Times
Data flash memory rewritable times Notes 1, 2, 3		Retained for 1 year	T_A = 25°C		1,000,000		
		Retained for 5 years	T_A = 85°C	100,000			
		Retained for 20 years	T_A = 85°C	10,000			

Notes 1. 1 erase + 1 write after the erase is regarded as 1 rewrite. The retaining years are a period of time in which the next rewrite is performed after a rewrite.

2. When using flash memory programmer or library program from Renesas

3. This shows the flash memory characteristics. This is a result obtained from Renesas Electronics reliability test.

28.9 Dedicated Flash Memory Programmer Communication (UART)

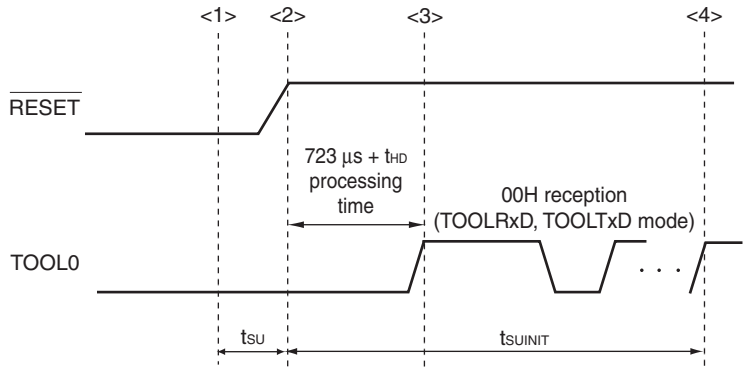
(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Transfer rate		During serial programming	115,200		1,000,000	bps

28.10 Timing Specs for Switching Flash Memory Programming Modes

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
How long from when an external reset ends until the initial communication settings are specified	t_{SUINIT}	POR and LVD reset must end before the external reset ends.			100	ms
How long from when the TOOL0 pin is placed at the low level until an external reset ends	t_{SU}	POR and LVD reset must end before the external reset ends.	10			μs
How long the TOOL0 pin must be kept at the low level after an external reset ends (excluding the processing time of the firmware to control the flash memory)	t_{HD}	POR and LVD reset must end before the external reset ends.	1			ms



<1> The low level is input to the TOOL0 pin.

<2> The external reset ends (POR and LVD reset must end before the external reset ends.).

<3> The TOOL0 pin is set to the high level.

<4> Setting of the flash memory programming mode by UART reception and complete the baud rate setting.

Remark t_{SUINIT}: The segment shows that it is necessary to finish specifying the initial communication settings within 100 ms from when the resets end.

t_{SU}: How long from when the TOOL0 pin is placed at the low level until an external reset ends.

t_{HD}: How long to keep the TOOL0 pin at the low level from when the external reset ends. (excluding the processing time of the firmware to control the flash memory)

To our valued customers:	RL78/G12 Technical Update Exhibit Chapter 29 ELECTRICAL SPECIFICATIONS (G: T_A = −40 to +105°C) (TARGET VALUES)	M C Y G - A B - 1 3 - 0 1 5 6 - 1 July 24, 2013 Hiroshi Uchimura Manager 1st Solution Business Unit 3rd MCU Business Division Brand Strategy Department Renesas Electronics Corporation

(Rep. Takehiro Furukawa)

Thank you for your continued support for Renesas Electronics products.

Please be advised that the misstatements found in the following User's Manual have been fixed.

The second and following pages in this document include "Chapter 29 ELECTRICAL SPECIFICATIONS (G: T_A = −40 to +105°C) (TARGET VALUES)" which has been updated by the Correction for incorrect description notice RL78/G12 Descriptions in the User's Manual: Hardware Rev.1.10 changed (TN-RL*-A006A/E).

1. Applicable products:

RL78/G12

R5F102xxG

2. Reference documents:

Correction for incorrect description notice RL78/G12 Descriptions in the User's Manual: Hardware Rev.1.10 changed (TN-RL*-A006A/E)

RL78/G12 User's Manual: Hardware Rev.1.10 (R01UH0200EJ0110)

CHAPTER 29 ELECTRICAL SPECIFICATIONS (G: T_A = –40 to +105°C) (TARGET VALUES)

This chapter describes the electrical specifications for the products "G: Industrial applications (TA = -40 to +105°C)".

Cautions 1. The specifications in this chapter show target values, which may change after device evaluation.

2. The RL78 microcontrollers have an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. Renesas Electronics is not liable for problems occurring when the on-chip debug function is used.

3. The pins mounted depend on the product. Refer to 2.1 Port Function to 2.2.1 Functions Mounted According to Product.

There are following differences between the products "G: Industrial applications (T_A = -40 to +105°C)" and the products “A: Consumer applications, and D: Industrial applications”.

Parameter	Application	
	A: Consumer applications, D: Industrial applications	G: Industrial applications
Operating ambient temperature	T_A = -40 to +85°C	T_A = -40 to +105°C
Operating mode Operating voltage range	HS (high-speed main) mode: 2.7 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 24 MHz 2.4 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 16 MHz LS (low-speed main) mode: 1.8 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 8 MHz	HS (high-speed main) mode only: 2.7 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 24 MHz 2.4 V ≤ V_{DD} ≤ 5.5 V@1 MHz to 16 MHz
High-speed on-chip oscillator clock accuracy	In the R5F102 products, 1.8 V ≤ V_{DD} ≤ 5.5 V : ±1.0%@ T_A = -20 to +85°C ±1.5%@ T_A = -40 to -20°C In the R5F103 products, 1.8 V ≤ V_{DD} ≤ 5.5 V : ±5.0%@ T_A = -40 to +85°C	In the R5F102 products, 2.4 V ≤ V_{DD} ≤ 5.5 V : ±2.0%@ T_A = +85 to +105°C ±1.0%@ T_A = -20 to +85°C ±1.5%@ T_A = -40 to -20°C
Serial array unit	UART CSI: f_{CLK}/2 (supporting 12 Mbps), f_{CLK}/4 Simplified I^2C communication	UART CSI: f_{CLK}/4 Simplified I^2C communication
Voltage detector	Rise detection voltage: 1.88 V to 4.06 V (12 levels) Fall detection voltage: 1.84 V to 3.98 V (12 levels)	Rise detection voltage: 2.61 V to 4.06 V (8 levels) Fall detection voltage: 2.55 V to 3.98 V (8 levels)

Remark The electrical characteristics of the products G: Industrial applications (T_A = -40 to +105°C) are different from those of the products “A: Consumer applications and D: Industrial applications”. For details, refer to 29.1 to 29.10.

29.1 Absolute Maximum Ratings

(T_A = 25°C)

Parameter	Symbols	Conditions		Ratings	Unit
Supply Voltage	V_{DD}			−0.5 to + 6.5	V
REGC terminal input voltage[Note1]	V_{IREGC}	REGC		−0.3 to +2.8 and −0.3 to V_{DD} + 0.3 [Note 2]	V
Input Voltage	V_{I1}	Other than P60, P61		−0.3 to V_{DD} + 0.3[Note 3]	V
	V_{I2}	P60, P61 (N-ch open drain)		−0.3 to 6.5	V
Output Voltage	V_O			−0.3 to V_{DD} + 0.3[Note 3]	V
Analog input voltage	V_{AI}	20-, 24-pin products: ANI0 to ANI3, ANI16 to ANI22 30-pin products: ANI0 to ANI3, ANI16 to ANI19		−0.3 to V_{DD} + 0.3 and −0.3 to AVREF(+)+0.3 [Notes 3, 4]	V
Output current, high	I_{OH1}	Per pin	Other than P20 to P23	−40	mA
		Total of all pins	All the terminals other than P20 to P23	−170	mA
			20-, 24-pin products: P40 to P42 30-pin products: P00, P01, P40, P120	−70	mA
			20-, 24-pin products: P00 to P03[Note 5], P10 to P14 30-pin products: P10 to P17, P30, P31, P50, P51, P147	−100	mA
	I_{OH2}	Per pin	P20 to P23	−0.5	mA
		Total of all pins		−2	mA
Output current, low	I_{OL1}	Per pin	Other than P20 to P23	40	mA
		Total of all pins	All the terminals other than P20 to P23	170	mA
			20-, 24-pin products: P40 to P42 30-pin products: P00, P01, P40, P120	70	mA
			20-, 24-pin products: P00 to P03[Note 5], P10 to P14, P60, P61 30-pin products: P10 to P17, P30, P31, P50, P51, P60, P61, P147	100	mA
	I_{OL2}	Per pin	P20 to P23	1	mA
		Total of all pins		5	mA
Operating ambient temperature	T_A			−40 to +105 [Note 6]	°C
Storage temperature	T_{stg}			−65 to +150	°C

Notes 1. 30-pin products only.

2. Connect the REGC pin to V_{SS} via a capacitor (0.47 to 1 μF). This value determines the absolute maximum rating of the REGC pin. Do not use it with voltage applied.

3. Must be 6.5 V or lower.

4. Do not exceed $AV_{REF}(+)$ + 0.3 V in case of A/D conversion target pin.

5. 24-pin products only.

6. **Total operating time in Ta = +85°C to +105°C : 10,000 hours**

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Remarks 1. Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

2. $AV_{REF}(+)$: + side reference voltage of the A/D converter.

3. V_{SS} : Reference voltage

29.2 Oscillator Characteristics

29.2.1 X1 oscillator characteristics

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Resonator	Conditions	MIN.	TYP.	MAX.	Unit
X1 clock oscillation frequency (f_X)[Note]	Ceramic resonator / Crystal oscillator	2.7 V ≤ V_{DD} ≤ 5.5 V	1.0		20.0	MHz
		2.4 V ≤ V_{DD} < 2.7 V	1.0		8.0	

Note Indicates only permissible oscillator frequency ranges. Refer to AC Characteristics for instruction execution time. Request evaluation by the manufacturer of the oscillator circuit mounted on a board to check the oscillator characteristics.

Caution Since the CPU is started by the high-speed on-chip oscillator clock after a reset release, check the X1 clock oscillation stabilization time using the oscillation stabilization time counter status register (OSTC) by the user. Determine the oscillation stabilization time of the OSTC register and the oscillation stabilization time select register (OSTS) after sufficiently evaluating the oscillation stabilization time with the resonator to be used.

Remark When using the X1 oscillator, refer to **5.4 System Clock Oscillator**.

29.2.2 On-chip oscillator characteristics

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Oscillators	Parameters	Conditions		MIN.	TYP.	MAX.	Unit
High-speed on-chip oscillator clock frequency [Notes 1, 2]	f_{IH}			1		24	MHz
High-speed on-chip oscillator clock frequency accuracy		R5F102 products	T_A = –20 to +85°C	-1.0		+1.0	%
			T_A = –40 to –20°C	-1.5		+1.5	%
			T_A = +85 to +105°C	-2.0		+2.0	%
Low-speed on-chip oscillator clock frequency	f_{IL}				15		kHz
Low-speed on-chip oscillator clock frequency accuracy				-15		+15	%

Notes 1. High-speed on-chip oscillator frequency is selected by bits 0 to 3 of option byte (000C2H) and bits 0 to 2 of HOCODIV register.

2. This only indicates the oscillator characteristics. Refer to AC Characteristics for instruction execution time.

29.3 DC Characteristics

29.3.1 Pin characteristics

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (1/4)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, high[Note 1]	I_{OH1}	20-, 24-pin products: Per pin for P00 to P03[Note 4], P10 to P14, P40 to P42 30-pin products: Per pin for P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147				–3.0 [Note 2]	mA
		20-, 24-pin products: Total of P40 to P42 30-pin products: Total of P00, P01, P40, P120 (When duty ≤ 70% [Note 3])	4.0 V ≤ V_{DD} ≤ 5.5 V			–9.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			–6.0	mA
			2.4 V ≤ V_{DD} < 2.7 V			–4.5	mA
		20-, 24-pin products: Total of P00 to P03[Note 4], P10 to P14 30-pin products: Total of P10 to P17, P30, P31, P50, P51, P147 (When duty ≤ 70% [Note 3])	4.0 V ≤ V_{DD} ≤ 5.5 V			–27.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			–18.0	mA
			2.4 V ≤ V_{DD} < 2.7 V			–10.0	mA
		Total of all pins (When duty ≤ 70%[Note 3])				–36.0	mA
	I_{OH2}	Per pin for P20 to P23				–0.1	mA
		Total of all pins				–0.4	mA

Notes 1. value of current at which the device operation is guaranteed even if the current flows from the V_{DD} pin to an output pin.

2. However, do not exceed the total current value.

3. The output current value under conditions where the duty factor ≤ 70%.
If duty factor > 70%: The output current value can be calculated with the following expression (where n represents the duty factor as a percentage).

- Total output current of pins = (I_{OH} × 0.7)/(n × 0.01)

<Example> Where n = 80% and I_{OH} = –10.0 mA

Total output current of pins = (–10.0 × 0.7)/(80 × 0.01) ≅ –8.7 mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

4. 24-pin products only.

Caution P10 to P12, P41 for 20-pin products, P01, P10 to P12, P41 for 24-pin products, and P00, P10 to P15, P17, P50 for 30-pin products do not output high level in N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) **(2/4)**

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, low[Note 1]	I_{OL1}	20-, 24-pin products: Per pin for P00 to P03[Note 4], P10 to P14, P40 to P42 30-pin products: Per pin for P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147				8.5 [Note 2]	mA
		Per pin for P60, P61				15.0 [Note 2]	mA
		20-, 24-pin products: Total of P40 to P42 30-pin products: Total of P00, P01, P40, P120 (When duty ≤ 70% [Note 3])	4.0 V ≤ V_{DD} ≤ 5.5 V			25.5	mA
			2.7 V ≤ V_{DD} < 4.0 V			9.0	mA
			2.4 V ≤ V_{DD} < 2.7 V			1.8	mA
		20-, 24-pin products: Total of P00 to P03[Note 4], P10 to P14, P60, P61 30-pin products: Total of P10 to P17, P30, P31, P50, P51, P60, P61, P147 (When duty ≤ 70% [Note 3])	4.0 V ≤ V_{DD} ≤ 5.5 V			40.0	mA
			2.7 V ≤ V_{DD} < 4.0 V			27.0	mA
			2.4 V ≤ V_{DD} < 2.7 V			5.4	mA
		Total of all pins (When duty ≤ 70%[Note 3])				65.5	mA
	I_{OL2}	Per pin for P20 to P23				0.4	mA
		Total of all pins				1.6	mA

Notes 1. Value of current at which the device operation is guaranteed even if the current flows from an output pin to the V_{SS} pin.

2. However, do not exceed the total current value.

3. The output current value under conditions where the duty factor ≤ 70%.
If duty factor > 70%: The output current value can be calculated with the following expression (where n represents the duty factor as a percentage).

- Total output current of pins = (I_{OL} × 0.7)/(n × 0.01)

<Example> Where n = 80% and I_{OL} = 10.0 mA

Total output current of pins = (10.0 × 0.7)/(80 × 0.01) ≅ 8.7 mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

4. 24-pin products only.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) (3/4)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Input voltage, high	V_{IH1}	Normal input buffer 20-, 24-pin products: P00 to P03[Note 2], P10 to P14, P40 to P42 30-pin products: P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147		0.8V_{DD}		V_{DD}	V
	V_{IH2}	TTL input buffer 20-, 24-pin products: P10, P11 30-pin products: P01, P10, P11, P13 to P17	4.0 V ≤ V_{DD} ≤ 5.5 V	2.2		V_{DD}	V
			3.3 V ≤ V_{DD} < 4.0 V	2.0		V_{DD}	V
			2.4 V ≤ V_{DD} < 3.3 V	1.5		V_{DD}	V
	V_{IH3}	Normal input buffer P20 to P23		0.7V_{DD}		V_{DD}	V
	V_{IH4}	P60, P61		0.7V_{DD}		6.0	V
	V_{IH5}	P121, P122, P125[Note 1], P137, EXCLK, $\overline{\text{RESET}}$		0.8V_{DD}		V_{DD}	V
Input voltage, low	V_{IL1}	Normal input buffer 20-, 24-pin products: P00 to P03[Note 2], P10 to P14, P40 to P42 30-pin products: P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147		0		0.2V_{DD}	V
	V_{IL2}	TTL input buffer 20-, 24-pin products: P10, P11 30-pin products: P01, P10, P11, P13 to P17	4.0 V ≤ V_{DD} ≤ 5.5 V	0		0.8	V
			3.3 V ≤ V_{DD} < 4.0 V	0		0.5	V
			2.4 V ≤ V_{DD} < 3.3 V	0		0.32	V
	V_{IL3}	P20 to P23		0		0.3V_{DD}	V
	V_{IL4}	P60, P61		0		0.3V_{DD}	V
	V_{IL5}	P121, P122, P125[Note 1], P137, EXCLK, $\overline{\text{RESET}}$		0		0.2V_{DD}	V
Output voltage, high	V_{OH1}	20-, 24-pin products: P00 to P03[Note 2], P10 to P14, P40 to P42 30-pin products: P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147	4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OH1} = –3.0 mA	V_{DD}–0.7			V
			2.7 V ≤ V_{DD} ≤ 5.5 V, I_{OH1} = –2.0 mA	V_{DD}–0.6			V
			2.4 V ≤ V_{DD} ≤ 5.5 V, I_{OH1} = –1.5 mA	V_{DD}–0.5			V
	V_{OH2}	P20 to P23	I_{OH2} = –100 μA	V_{DD}–0.5			V

Notes 1. 20, 24-pin products only.

2. 24-pin products only.

Caution The maximum value of V_{IH} of pins P10 to P12, P41 for 20-pin products, P01, P10 to P12, P41 for 24-pin products, and P00, P10 to P15, P17, P50 for 30-pin products is V_{DD} even in N-ch open-drain mode. High level is not output in the N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) **(4/4)**

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output voltage, low	V_{OL1}	20-, 24-pin products: P00 to P03[Note], P10 to P14, P40 to P42 30-pin products: P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147	4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 8.5 mA			0.7	V
			2.7 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 3.0 mA			0.6	V
			2.7 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 1.5 mA			0.4	V
			2.4 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 0.6 mA			0.4	V
	V_{OL2}	P20 to P23	I_{OL2} = 400 μA			0.4	V
	V_{OL3}	P60, P61	4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 15.0 mA			2.0	V
			4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 5.0 mA			0.4	V
			2.7 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 3.0 mA			0.4	V
			2.4 V ≤ V_{DD} ≤ 5.5 V, I_{OL1} = 2.0 mA			0.4	V
Input leakage current, high	I_{LIH1}	Other than P121, P122	V_I = V_{DD}			1	μA
	I_{LIH2}	P121, P122 (X1, X2/EXCLK)	V_I = V_{DD} Input port or external clock input			1	μA
			V_I = V_{DD} When resonator connected			10	μA
Input leakage current, low	I_{LIL1}	Other than P121, P122	V_I = V_{SS}			–1	μA
	I_{LIL2}	P121, P122 (X1, X2/EXCLK)	V_I = V_{SS} Input port or external clock input			–1	μA
			V_I = V_{SS} When resonator connected			–10	μA
On-chip pull-up resistance	R_U	20-, 24-pin products: P00 to P03[Note], P10 to P14, P40 to P42, P125, $\overline{\text{RESET}}$ 30-pin products: P00, P01, P10 to P17, P30, P31, P40, P50, P51, P120, P147	V_I = V_{SS}, input port	10	20	100	kΩ

Note 24-pin products only.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

29.3.2 Supply current characteristics

(1) 20-, 24-pin products

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) **(1/2)**

Parameter	Symbol	Conditions					MIN.	TYP.	MAX.	Unit
Supply current[Note 1]	I_{DD1}	Operating mode	HS (High-speed main) mode[Note 4]	f_{IH} = 24 MHz[Note 3]	Basic operation	V_{DD} = 5.0 V		1.5		mA
						V_{DD} = 3.0 V		1.5		
					Normal operation	V_{DD} = 5.0 V		3.3	5.3	mA
						V_{DD} = 3.0 V		3.3	5.3	
				f_{IH} = 16 MHz[Note 3]		V_{DD} = 5.0 V		2.5	3.9	mA
						V_{DD} = 3.0 V		2.5	3.9	
				f_{MX} = 20 MHz[Note 2], V_{DD} = 5.0 V		Square wave input		2.8	4.7	mA
						Resonator connection		3.0	4.8	
				f_{MX} = 20 MHz[Note 2], V_{DD} = 3.0 V		Square wave input		2.8	4.7	mA
						Resonator connection		3.0	4.8	
				f_{MX} = 10 MHz[Note 2], V_{DD} = 5.0 V		Square wave input		1.8	2.8	mA
						Resonator connection		1.8	2.8	
				f_{MX} = 10 MHz[Note 2], V_{DD} = 3.0 V		Square wave input		1.8	2.8	mA
						Resonator connection		1.8	2.8	

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.

2. When high-speed on-chip oscillator clock is stopped.

3. When high-speed system clock is stopped

4. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.
HS(High speed main) mode: V_{DD} = 2.7 V to 5.5 V @1 MHz to 24 MHz
V_{DD} = 2.4 V to 5.5 V @1 MHz to 16 MHz

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{IH}: high-speed on-chip oscillator clock frequency

3. Temperature condition of the TYP. value is T_A = 25°C.

(1) 20-, 24-pin products

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) **(2/2)**

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current[Note 1]	I_{DD2}[Note 2]	HALT mode	HS (High-speed main) mode[Note 6]	f_{IH} = 24 MHz[Note 4]	V_{DD} = 5.0 V		440	2230	μA
					V_{DD} = 3.0 V		440	2230	
				f_{IH} = 16 MHz[Note 4]	V_{DD} = 5.0 V		400	1650	μA
					V_{DD} = 3.0 V		400	1650	
				f_{MX} = 20 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		280	1900	μA
					Resonator connection		450	2000	
				f_{MX} = 20 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		280	1900	μA
					Resonator connection		450	2000	
				f_{MX} = 10 MHz[Note 3], V_{DD} = 5.0 V	Square wave input		190	1010	μA
					Resonator connection		260	1090	
				f_{MX} = 10 MHz[Note 3], V_{DD} = 3.0 V	Square wave input		190	1010	μA
					Resonator connection		260	1090	
	I_{DD3}[Note 5]	STOP mode	T_A = –40°C				0.19	0.50	μA
			T_A = +25°C				0.24	0.50	
			T_A = +50°C				0.32	0.80	
			T_A = +70°C				0.48	1.20	
			T_A = +85°C				0.74	2.20	
			T_A = +105°C				1.50	10.20	

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.

2. During HALT instruction execution by flash memory.

3. When high-speed on-chip oscillator clock is stopped.

4. When high-speed system clock is stopped.

5. Not including the current flowing into the 12-bit interval timer and watchdog timer.

6. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS(High speed main) mode: V_{DD} = 2.7 V to 5.5 V @1 MHz to 24 MHz

V_{DD} = 2.4 V to 5.5 V @1 MHz to 16 MHz

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{IH}: high-speed on-chip oscillator clock frequency

3. Except STOP mode, temperature condition of the TYP. value is T_A = 25°C

(2) 30-pin products

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) **(1/2)**

Parameter	Symbol	Conditions					MIN.	TYP.	MAX.	Unit
Supply current[Note 1]	I_{DD1}	Operating mode	HS (High-speed main) mode[Note 4]	f_{IH} = 24 MHz[Note 3]	Basic operation	V_{DD} = 5.0 V		1.5		mA
						V_{DD} = 3.0 V		1.5		
					Normal operation	V_{DD} = 5.0 V		3.7	5.8	mA
						V_{DD} = 3.0 V		3.7	5.8	
				f_{IH} = 16 MHz[Note 3]		V_{DD} = 5.0 V		2.7	4.2	mA
						V_{DD} = 3.0 V		2.7	4.2	
				f_{MX} = 20 MHz[Note 2], V_{DD} = 5.0 V		Square wave input		3.0	4.9	mA
						Resonator connection		3.2	5.0	
				f_{MX} = 20 MHz[Note 2], V_{DD} = 3.0 V		Square wave input		3.0	4.9	mA
						Resonator connection		3.2	5.0	
				f_{MX} = 10 MHz[Note 2], V_{DD} = 5.0 V		Square wave input		1.9	2.9	mA
						Resonator connection		1.9	2.9	
				f_{MX} = 10 MHz[Note 2], V_{DD} = 3.0 V		Square wave input		1.9	2.9	mA
						Resonator connection		1.9	2.9	

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.

2. When high-speed on-chip oscillator clock is stopped.

3. When high-speed system clock is stopped

4. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.
HS(High speed main) mode: V_{DD} = 2.7 V to 5.5 V @1 MHz to 24 MHz
V_{DD} = 2.4 V to 5.5 V @1 MHz to 16 MHz

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{IH}: high-speed on-chip oscillator clock frequency

3. Temperature condition of the TYP. value is T_A = 25°C.

(2) 30-pin products

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V) **(2/2)**

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current Note 1	I_{DD2} Note 2	HALT mode	HS (High-speed main) mode Note 6	f_{IH} = 24 MHz Note 4	V_{DD} = 5.0 V		440	2300	μA
					V_{DD} = 3.0 V		440	2300	
				f_{IH} = 16 MHz Note 4	V_{DD} = 5.0 V		400	1700	μA
					V_{DD} = 3.0 V		400	1700	
				f_{MX} = 20 MHz Note 3, V_{DD} = 5.0 V	Square wave input		280	1900	μA
					Resonator connection		450	2000	
				f_{MX} = 20 MHz Note 3, V_{DD} = 3.0 V	Square wave input		280	1900	μA
					Resonator connection		450	2000	
				f_{MX} = 10 MHz Note 3, V_{DD} = 5.0 V	Square wave input		190	1020	μA
					Resonator connection		260	1100	
				f_{MX} = 10 MHz Note 3, V_{DD} = 3.0 V	Square wave input		190	1020	μA
					Resonator connection		260	1100	
	I_{DD3} Note 5	STOP mode	T_A = –40°C				0.18	0.50	μA
			T_A = +25°C				0.23	0.50	
			T_A = +50°C				0.30	1.10	
			T_A = +70°C				0.46	1.90	
			T_A = +85°C				0.75	3.30	
			T_A = +105°C				2.94	15.30	

Notes 1. Total current flowing into V_{DD}, including the input leakage current flowing when the level of the input pin is fixed to V_{DD} or V_{SS}. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.

2. During HALT instruction execution by flash memory.

3. When high-speed on-chip oscillator clock is stopped.

4. When high-speed system clock is stopped.

5. Not including the current flowing into the 12-bit interval timer and watchdog timer.

6. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (High speed main) mode: V_{DD} = 2.7 V to 5.5 V @1 MHz to 24 MHz

V_{DD} = 2.4 V to 5.5 V @1 MHz to 16 MHz

Remarks 1. f_{MX}: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{IH}: high-speed on-chip oscillator clock frequency

3. Except STOP mode, temperature condition of the TYP. value is T_A = 25°C.

(3) Peripheral functions (Common to all products)

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Low-speed onchip oscillator operating current	I_{FIL} Note 1				0.20		μA
12-bit interval timer operating current	I_{TMKA} Notes 1, 2, 3				0.02		μA
Watchdog timer operating current	I_{WDT} Notes 1, 2, 4	f_{IL} = 15 kHz			0.22		μA
A/D converter operating current	I_{ADC} Notes 1, 5	When conversion at maximum speed	Normal mode, AV_{REFP} = V_{DD} = 5.0 V		1.30	1.70	mA
			Low voltage mode, AV_{REFP} = V_{DD} = 3.0 V		0.50	0.70	mA
A/D converter reference voltage operation current	I_{ADREF} Note 1				75.0		μA
Temperature sensor operating current	I_{TMPS} Note 1				75.0		μA
LVD operating current	I_{LVD} Notes 1, 6				0.08		μA
Self-programming operating current	I_{FSP} Notes 1, 8				2.00	12.20	mA
BGO operating current	I_{BGO} Notes 1, 7				2.00	12.20	mA
SNOOZE operating current	I_{SNOZ} Note 1	ADC operation	The mode is performed Note 9		0.50	1.10	mA
			The A/D conversion operations are performed, Low voltage mode, AV_{REFP} = V_{DD} = 3.0 V		1.20	2.04	mA
		CSI/UART operation			0.70	1.54	mA

Notes 1. Current flowing to the V_{DD}.

2. When high speed on-chip oscillator and high-speed system clock are stopped.

3. Current flowing only to the 12-bit interval timer (excluding the operating current of the low-speed on-chip oscillator). The supply current of the RL78 microcontrollers is the sum of the values of I_{DD1}, I_{DD2} or I_{DD3} and I_{TMKA} and I_{FIL} when the 12-bit interval timer operates.

4. Current flowing only to the watchdog timer (including the operating current of the low-speed on-chip oscillator). The current value of the RL78 microcontrollers is the sum of I_{DD1}, I_{DD2} or I_{DD3} and I_{WDT} when the watchdog timer operates.

5. Current flowing only to the A/D converter. The supply current of the RL78 microcontrollers is the sum of the values of I_{DD1} or I_{DD2} and I_{ADC} when the A/D converter operates in an operation mode or the HALT mode.

6. Current flowing only to the LVD circuit. The supply current of the RL78 microcontrollers is the sum of the values of I_{DD1}, I_{DD2} or I_{DD3} and I_{LVD} when the LVD circuit is in operation.

7. Current flowing only during data flash rewrite.

8. Current flowing only during self programming.

9. Refer to shift time to the SNOOZE mode, see **17.2.3 SNOOZE mode**.

Remarks 1. f_{IL}: Low-speed on-chip oscillator clock frequency

2. Temperature condition of the TYP. value is T_A = 25°C

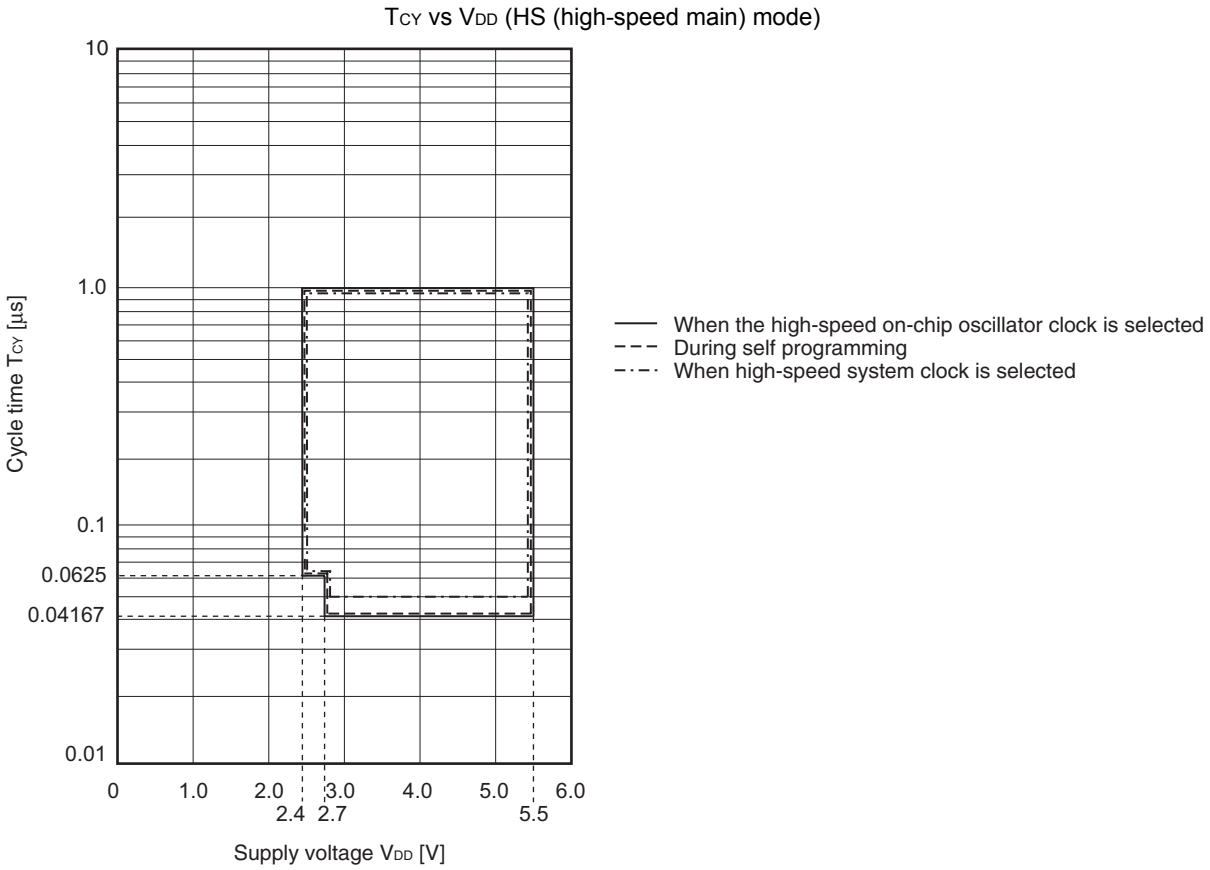
29.4 AC Characteristics

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

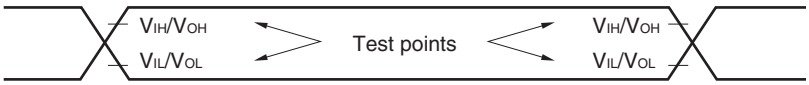
Items	Symbol	Conditions			MIN.	TYP.	MAX.	Unit
Instruction cycle (minimum instruction execution time)	T_{CY}	Main system clock (f_{MAIN}) operation	HS (High-speed main) mode	2.7 V ≤ V_{DD} ≤ 5.5 V	0.04167		1	μs
				2.4 V ≤ V_{DD} < 2.7 V	0.0625		1	μs
		During self programming	HS (High-speed main) mode	2.7 V ≤ V_{DD} ≤ 5.5 V	0.04167		1	μs
				2.4 V ≤ V_{DD} < 2.7 V	0.0625		1	μs
External main system clock frequency	f_{EX}	2.7 V ≤ V_{DD} ≤ 5.5 V			1.0		20.0	MHz
		2.4 V ≤ V_{DD} < 2.7 V			1.0		16.0	MHz
External main system clock input high-level width, low-level width	t_{EXH}, t_{EXL}	2.7 V ≤ V_{DD} ≤ 5.5 V			24			ns
		2.4 V ≤ V_{DD} < 2.7 V			30			ns
TI00 to TI07 input high-level width, low-level width	t_{TIH}, t_{TIL}				1/f_{MCK} + 10			ns
TO00 to TO07 output frequency	f_{TO}	4.0 V ≤ V_{DD} ≤ 5.5 V					12	MHz
		2.7 V ≤ V_{DD} < 4.0 V					8	MHz
		2.4 V ≤ V_{DD} < 2.7 V					4	MHz
PCLBUZ0, or PCLBUZ1 output frequency	f_{PCL}	4.0 V ≤ V_{DD} ≤ 5.5 V					16	MHz
		2.7 V ≤ V_{DD} < 4.0 V					8	MHz
		2.4 V ≤ V_{DD} < 2.7 V					4	MHz
INTP0 to INTP5 input high-level width, low-level width	t_{INTH}, t_{INTL}				1			μs
KR0 to KR9 input available width	t_{KR}				250			ns
$\overline{\text{RESET}}$ low-level width	t_{RSL}				10			μs

Remark f_{MCK}: Timer array unit operation clock frequency
(Operation clock to be set by the CKS0n bit of timer mode register 0n (TMR0n), and the Timer clock select register 0 (TPS0). n: Channel number (n = 0 to 7))

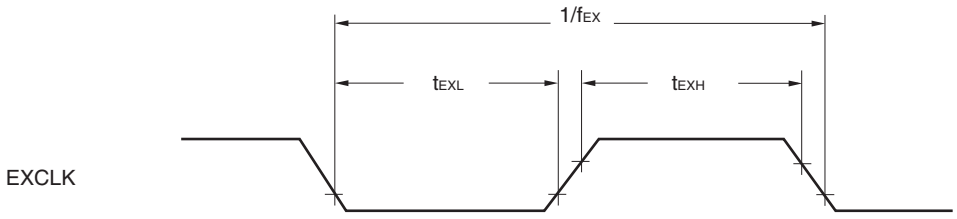
Minimum Instruction Execution Time during Main System Clock Operation



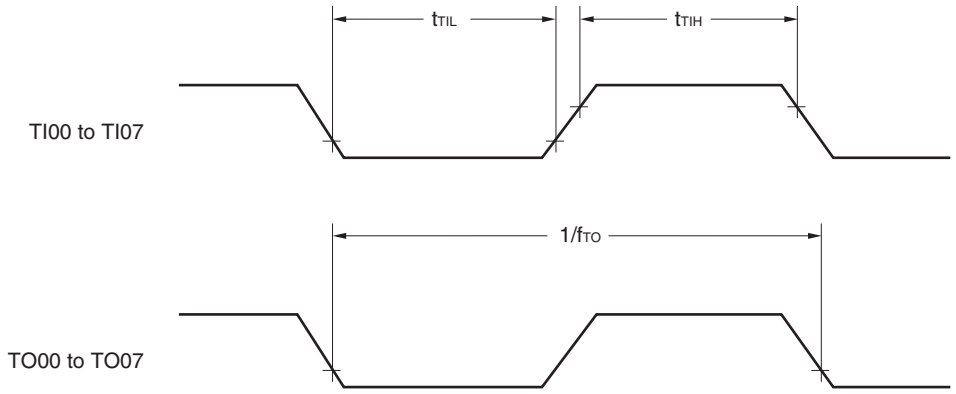
AC Timing Test Point



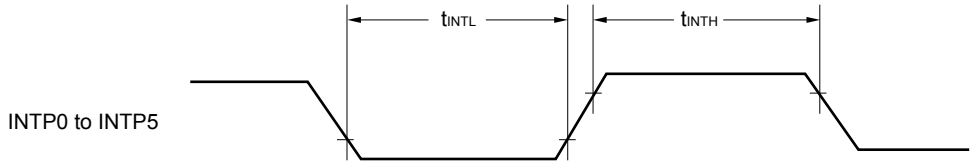
External main system clock timing



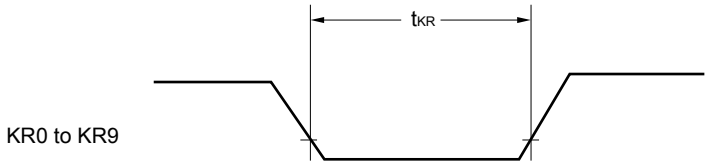
TI/TO timing



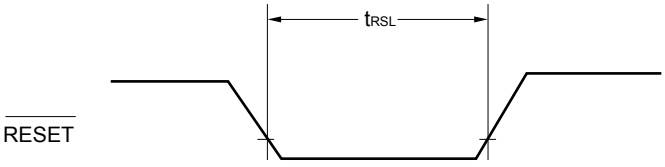
Interrupt Request Input Timing



Key Interrupt Input Timing

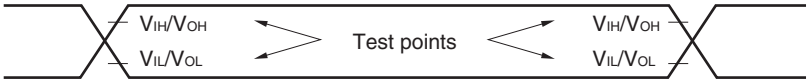


$\overline{\text{RESET}}$ input timing



29.5 Peripheral Functions Characteristics

AC Timing Test Point



29.5.1 Serial array unit

(1) During communication at same potential (UART mode)

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

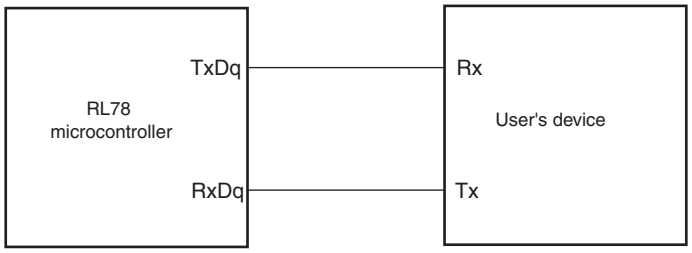
Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
Transfer rate Note 1				f_{MCK}/12	bps
		Theoretical value of the maximum transfer rate f_{CLK} = f_{MCK} Note2		2.0	Mbps

Notes 1. Transfer rate in the SNOOZE mode is 4800 bps only.

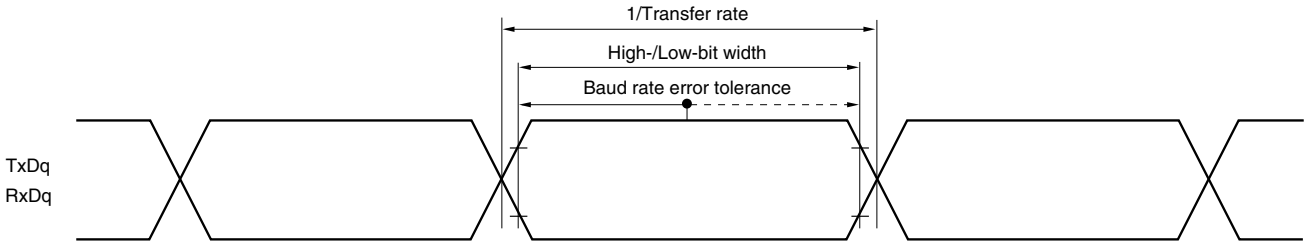
2. The maximum operating frequencies of the CPU/peripheral hardware clock (f_{CLK}) are:
HS (high-speed main) mode: 24 MHz (2.7 V ≤ V_{DD} ≤ 5.5 V)
16 MHz (2.4 V ≤ V_{DD} ≤ 5.5 V)

Caution Select the normal input buffer for the RxDq pin and the normal output mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg)

UART mode connection diagram (during communication at same potential)



UART mode bit width (during communication at same potential) (reference)



Remarks 1. q: UART number (q = 0 to 2), g: PIM, POM number (g = 0, 1)

2. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn), and the Serial clock select register m (SPSm). m: Unit number, n: Channel number (mn = 00 to 03, 10, 11))

(2) During communication at same potential (CSI mode) (master mode, SCKp... internal clock output)

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		Unit
				MIN.	MAX.	
SCKp cycle time	t_{KCY1}	$t_{KCY1} \geq 4/f_{CLK}$	2.7 V ≤ V_{DD} ≤ 5.5 V	334		ns
			2.4 V ≤ V_{DD} ≤ 5.5 V	500		ns
SCKp high-/low-level width	t_{KH1}, t_{KL1}	4.0 V ≤ V_{DD} ≤ 5.5 V		t_{KCY1}/2–24		ns
		2.7 V ≤ V_{DD} ≤ 5.5 V		t_{KCY1}/2–36		ns
		2.4 V ≤ V_{DD} ≤ 5.5 V		t_{KCY1}/2–76		ns
SIp setup time (to SCKp↑) Note 1	t_{SIK1}	4.0 V ≤ V_{DD} ≤ 5.5 V		66		ns
		2.7 V ≤ V_{DD} ≤ 5.5 V		66		ns
		2.4 V ≤ V_{DD} ≤ 5.5 V		113		ns
SIp hold time (from SCKp↑) Note 2	t_{KSI1}			38		ns
Delay time from SCKp↓ to SOp output Note 3	t_{KSO1}	C = 30 pF Note4			50	ns

Notes 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

4. C is the load capacitance of the SCKp and SOp output lines.

Caution Select the normal input buffer for the SIp pin and the normal output mode for the SOp and SCKp pins by using port input mode registers 1 (PIM1) and port output mode registers 0, 1, 4 (POM0, POM1, POM4).

Remarks 1. p: CSI number (p = 00, 01, 11, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0, 1, 3)

2. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn), and the Serial clock select register m (SPSm). m: Unit number (m = 0, 1), n: Channel number (n = 0, 1, 3)

(3) During communication at same potential (CSI mode) (slave mode, SCKp... external clock input)

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		Unit
				MIN.	MAX.	
SCKp cycle time Note4	t_{KCY2}	4.0 V ≤ V_{DD} ≤ 5.5 V	20 MHz < f_{MCK}	16/f_{MCK}		ns
			f_{MCK} ≤ 20 MHz	12/f_{MCK}		ns
		2.7 V ≤ V_{DD} ≤ 5.5 V	16 MHz < f_{MCK}	16/f_{MCK}		ns
			f_{MCK} ≤ 16 MHz	12/f_{MCK}		ns
		2.4 V ≤ V_{DD} ≤ 5.5 V		12/f_{MCK} and 1000		ns
SCKp high-/low-level width	t_{KH2}, t_{KL2}	4.0 V ≤ V_{DD} ≤ 5.5 V		t_{KCY2}/2–14		ns
		2.7 V ≤ V_{DD} ≤ 5.5 V		t_{KCY2}/2–16		ns
		2.4 V ≤ V_{DD} ≤ 5.5 V		t_{KCY2}/2–36		ns
SIp setup time (to SCKp↑) Note 1	t_{SIK2}	2.7 V ≤ V_{DD} ≤ 5.5 V		1/f_{MCK} + 40		ns
		2.4 V ≤ V_{DD} ≤ 5.5 V		1/f_{MCK} + 60		ns
SIp hold time (from SCKp↑) Note 2	t_{KSI2}			1/f_{MCK} + 62		ns
Delay time from SCKp↓ to SOp output Note 3	t_{KSO2}	C = 30 pF Note4	2.7 V ≤ V_{DD} ≤ 5.5 V		2/f_{MCK} + 66	ns
			2.4 V ≤ V_{DD} ≤ 5.5 V		2/f_{MCK} + 113	ns

Notes 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

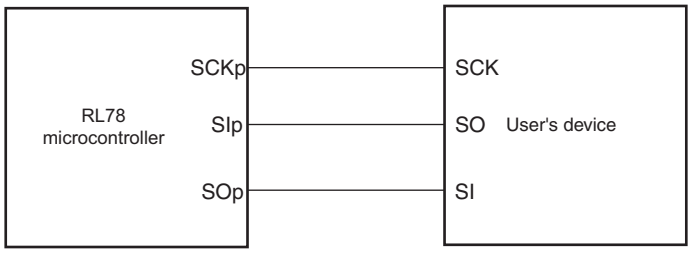
3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

4. C is the load capacitance of the SOp output lines.

5. Transfer rate in the SNOOZE mode: MAX. 1 Mbps

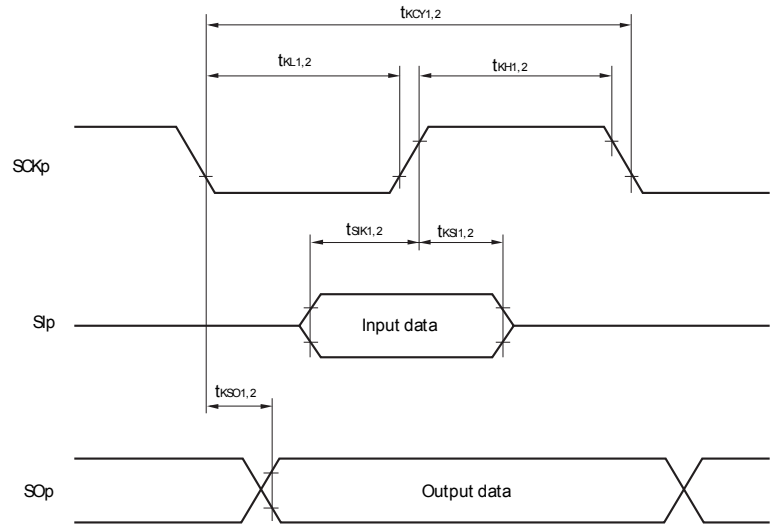
Caution Select the normal input buffer for the SIp pin and the normal output mode for the SOp and SCKp pins by using port input mode registers 1 (PIM1) and port output mode registers 0, 1, 4 (POM0, POM1, POM4).

CSI mode connection diagram (during communication at same potential)

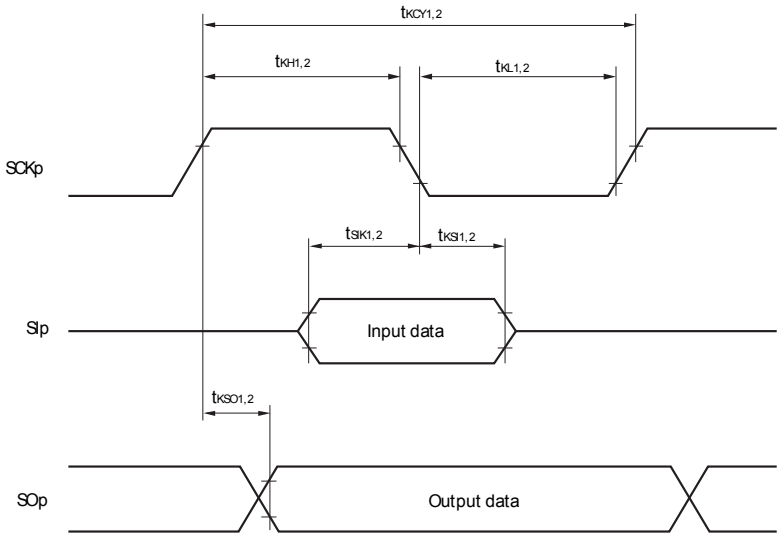


(**Remarks** are listed on the next page.)

CSI mode serial transfer timing (during communication at same potential)
(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)



CSI mode serial transfer timing (during communication at same potential)
(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



Remarks 1. p: CSI number (p = 00, 01, 11, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0, 1, 3)

2. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn), and the Serial clock select register m (SPSm). m: Unit number (m = 0, 1), n: Channel number (n = 0, 1, 3))

(4) During communication at same potential (simplified I²C mode)

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

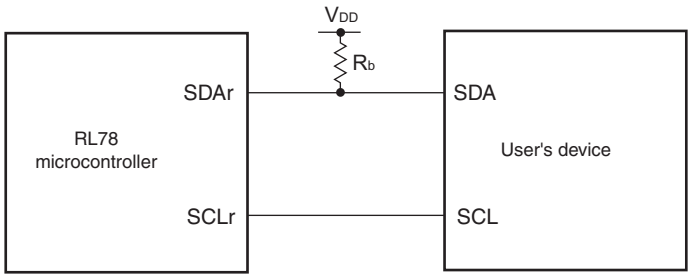
Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
SCLr clock frequency	f_{SCL}	C_b = 100 pF, R_b = 3 kΩ		100 Note 1	kHz
Hold time when SCLr = "L"	t_{LOW}	C_b = 100 pF, R_b = 3 kΩ	4600		ns
Hold time when SCLr = "H"	t_{HIGH}	C_b = 100 pF, R_b = 3 kΩ	4600		ns
Data setup time (reception)	$t_{SU:DAT}$	C_b = 100 pF, R_b = 3 kΩ	1/f_{MCK} + 580 Note 2		ns
Data hold time (transmission)	$t_{HD:DAT}$	C_b = 100 pF, R_b = 3 kΩ	0	1420	ns

Notes 1. The value must also be equal to or less than f_{MCK}/4.

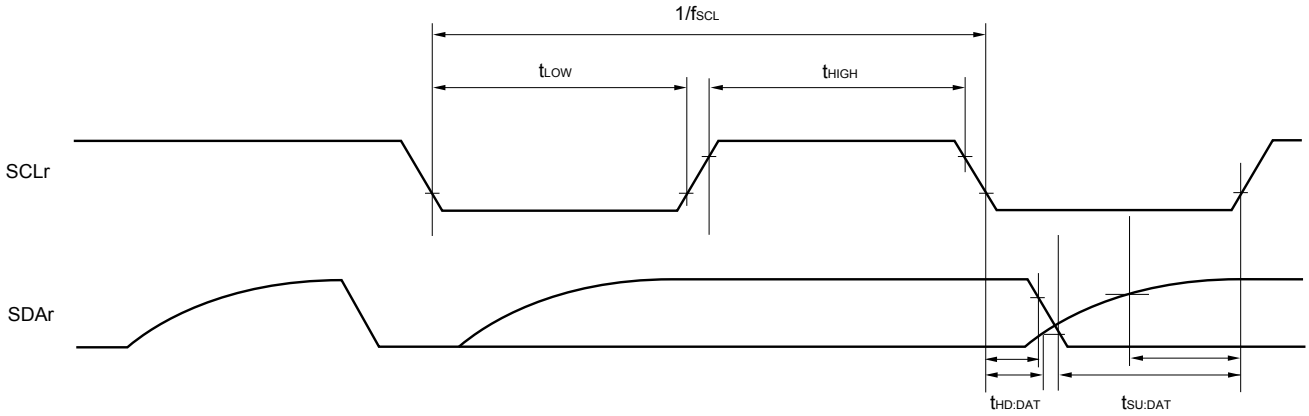
2. Set the $t_{SU:DAT}$ value to keep the hold time of SCLr = "L" and SCLr = "H".

Caution Select the N-ch open drain output (V_{DD} tolerance) mode for SDAr by using port output mode register h (POMh).

Simplified I²C mode connection diagram (during communication at same potential)



Simplified I²C mode serial transfer timing (during communication at same potential)



Remarks 1. R_b [Ω]:Communication line (SDAr) pull-up resistance,
C_b [F]: Communication line (SCLr, SDAr) load capacitance

2. r: IIC number (r = 00, 01, 11, 20), h: = POM number (h = 0, 1, 4, 5)

3. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn), and the Serial clock select register m (SPSm). m: Unit number (m = 0, 1), n: Channel number (0, 1, 3))

(5) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode)

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		Unit
				MIN.	MAX.	
Transfer rate Note4		Reception	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V		f_{MCK}/12 Note1	bps
			Theoretical value of the maximum transfer rate f_{MCK} = f_{CLK} Note2		2.0	Mbps
			2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V		f_{MCK}/12 Note1	bps
			Theoretical value of the maximum transfer rate f_{MCK} = f_{CLK} Note2		2.0	Mbps
			2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V		f_{MCK}/12 Notes1, 2	bps
			Theoretical value of the maximum transfer rate f_{MCK} = f_{CLK} Note2		2.0	Mbps
		Transmission	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V		**Note 3**	bps
			Theoretical value of the maximum transfer rate C_b = 50 pF, R_b = 1.4 kΩ, V_b = 2.7 V		2.0 Note 4	Mbps
			2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V,		**Note 5**	bps
			Theoretical value of the maximum transfer rate C_b = 50 pF, R_b = 2.7 kΩ, V_b = 2.3 V		1.2 Note 6	Mbps
			2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V		**Note 7**	bps
			Theoretical value of the maximum transfer rate C_b = 50 pF, R_b = 5.5 kΩ, V_b = 1.6 V		0.43 Note 8	Mbps

Notes 1. Transfer rate in the SNOOZE mode is 4800 bps only.

2. The maximum operating frequencies of the CPU/peripheral hardware clock (f_{CLK}) are:

HS (high-speed main) mode: 24 MHz (2.7 V ≤ V_{DD} ≤ 5.5 V)

16 MHz (2.4 V ≤ V_{DD} ≤ 5.5 V)

3. The smaller maximum transfer rate derived by using f_{MCK}/12 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 4.0 V ≤ V_{DD} ≤ 5.5 V and 2.7 V ≤ V_b ≤ 4.0 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{2.2}{V_b})\} \times 3} \text{ [bps]}$$

$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.2}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 \text{ [\%]}$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

4. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to **Note 3** above to calculate the maximum transfer rate under conditions of the customer.

5. The smaller maximum transfer rate derived by using f_{MCK}/12 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 2.7 V ≤ V_{DD} < 4.0 V and 2.3 V ≤ V_b ≤ 2.7 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\} \times 3} \text{ [bps]}$$

$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 \text{ [\%]}$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

6. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to **Note 5** above to calculate the maximum transfer rate under conditions of the customer.

7. The smaller maximum transfer rate derived by using f_{MCK}/12 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V

$$\text{Maximum transfer rate} = \frac{1}{\{-C_b \times R_b \times \ln(1 - \frac{1.5}{V_b})\} \times 3} \text{ [bps]}$$

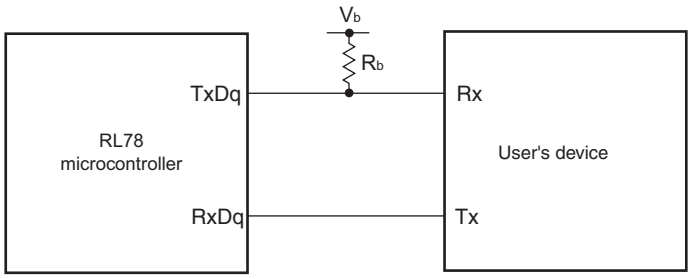
$$\text{Baud rate error (theoretical value)} = \frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{1.5}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 \text{ [\%]}$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

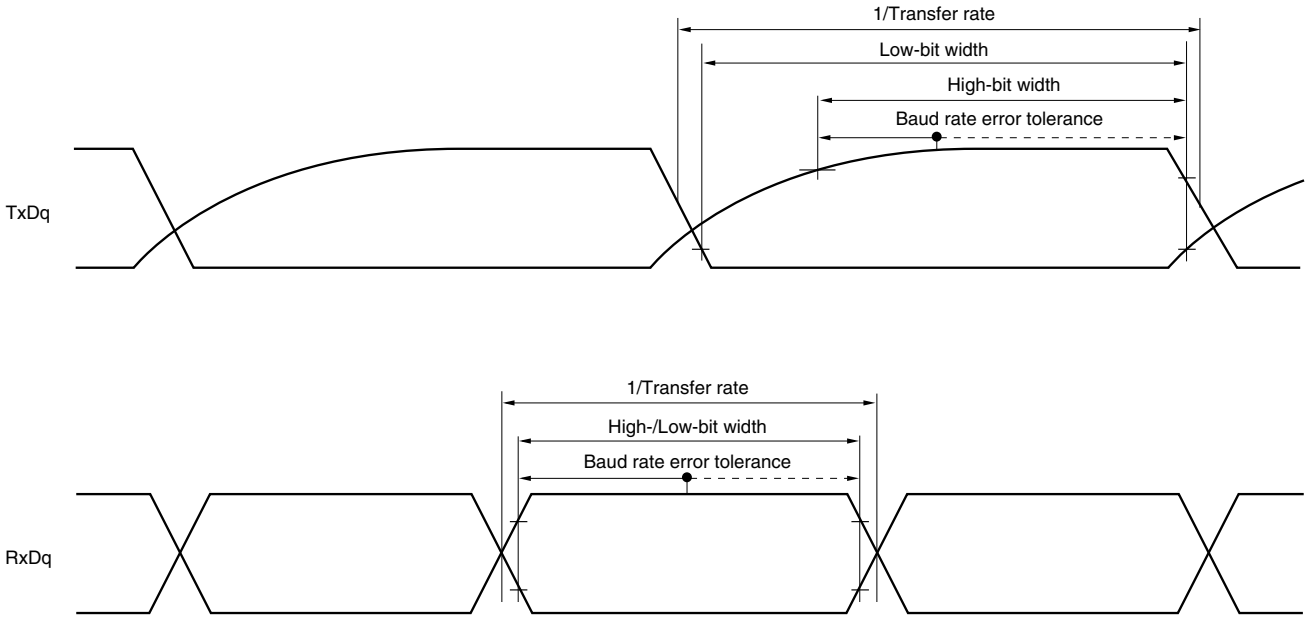
8. This value as an example is calculated when the conditions described in the “Conditions” column are met. Refer to **Note 7** above to calculate the maximum transfer rate under conditions of the customer.

Caution Select the TTL input buffer for the RxDq pin and the N-ch open drain output (V_{DD} tolerance) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

UART mode connection diagram (during communication at different potential)



UART mode bit width (during communication at different potential) (reference)



Remarks 1. R_b[Ω]: Communication line (TxDq) pull-up resistance, C_b[F]: Communication line (TxDq) load capacitance, V_b[V]: Communication line voltage

2. q: UART number (q = 0 to 2), g: PIM and POM number (g = 0, 1)

3. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn), and the Serial clock select register m (SPSm). m: Unit number, n: Channel number (mn = 00 to 03, 10, 11))

4. UART0 in 20-, 24-pin products is valid the communication at different potential only when peripheral I/O redirect function is not used.

(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output) (1/3)

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		Unit
				MIN.	MAX.	
SCKp cycle time	t_{KCY1}	$t_{KCY1} \geq 4/f_{CLK}$	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ	600		ns
			2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ	1000		ns
			2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 30 pF, R_b = 5.5 kΩ	2300		ns
SCKp high-level width	t_{KH1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ		t_{KCY1}/2 –150		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ		t_{KCY1}/2 –340		ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 30 pF, R_b = 5.5 kΩ		t_{KCY1}/2 –916		ns
SCKp low-level width	t_{KL1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ		t_{KCY1}/2 –24		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ		t_{KCY1}/2 –36		ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 30 pF, R_b = 5.5 kΩ		t_{KCY1}/2 –100		ns

Cautions 1. **Select the TTL input buffer for the SIp pin and the N-ch open drain output (V_{DD} tolerance) mode for the SOp pin and SCKp pin by using port input mode register 1 (PIM1) and port output mode register 1 (POM1). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.**

2. **Communication at different potential is not allowed in CSI01, CSI11.**

Remarks 1. R_b [Ω]: Communication line (SCKp, SOp) pull-up resistance, C_b [F]: Communication line (SCKp, SOp) load capacitance, V_b [V]: Communication line voltage

2. p: CSI number (p = 00, 20)

(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output) (2/3)

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
SIp setup time (to SCKp↑) Note	t_{SIK1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ	162		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ	354		ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 30 pF, R_b = 5.5 kΩ	958		ns
SIp hold time (from SCKp↑) Note	t_{KSI1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ	38		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ	38		ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 30 pF, R_b = 5.5 kΩ	38		ns
Delay time from SCKp↓ to SOp output Note	t_{KSO1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ		200	ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ		390	ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 30 pF, R_b = 5.5 kΩ		966	ns

Note When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.

(**Cautions** and **Remarks** are listed on the next page.)

(6) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output) (3/3)

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
SIp setup time (to SCKp↓) Note	t_{SIK1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ	88		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ	88		ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 30 pF, R_b = 5.5 kΩ	220		ns
SIp hold time (from SCKp↓) Note	t_{KSI1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ	38		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ	38		ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 30 pF, R_b = 5.5 kΩ	38		ns
Delay time from SCKp↑ to SOp output Note	t_{KSO1}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ		50	ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ		50	ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 30 pF, R_b = 5.5 kΩ		50	ns

Note When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

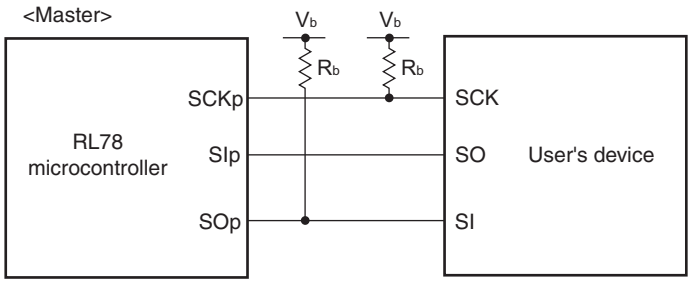
Cautions 1. **Select the TTL input buffer for the SIp pin and the N-ch open drain output (V_{DD} tolerance) mode for the SOp pin and SCKp pin by using port input mode register 1 (PIM1) and port output mode register 1 (POM1). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.**

2. **Communication at different potential is not allowed in CSI01, CSI11.**

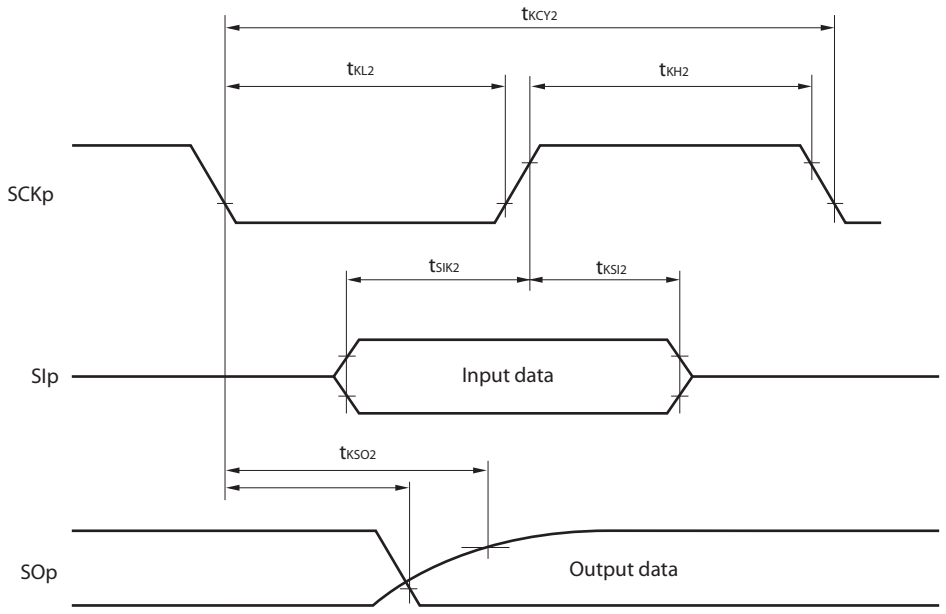
Remarks 1. R_b [Ω]: Communication line (SCKp, SOp) pull-up resistance, C_b [F]: Communication line (SCKp, SOp) load capacitance, V_b [V]: Communication line voltage

2. p: CSI number (p = 00, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0)

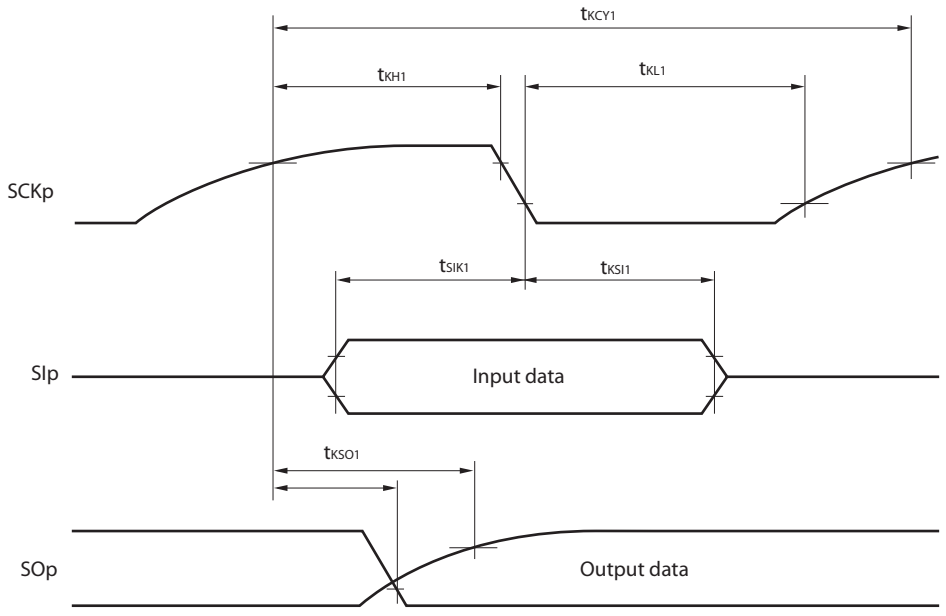
CSI mode connection diagram (during communication at different potential)



CSI mode serial transfer timing (master mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1)



CSI mode serial transfer timing (master mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



Remark p: CSI number (p = 00, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0)

(7) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (slave mode, SCKp... external clock input)
(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		HS (high-speed main) Mode		Unit
				MIN.	MAX.	
SCKp cycle time Note 1	t_{KCY2}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V	20 MHz < f_{MCK} ≤ 24 MHz	24/f_{MCK}		ns
			8 MHz < f_{MCK} ≤ 20 MHz	20/f_{MCK}		ns
			4 MHz < f_{MCK} ≤ 8 MHz	16/f_{MCK}		ns
			f_{MCK} ≤ 4 MHz	12/f_{MCK}		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V	20 MHz < f_{MCK} ≤ 24 MHz	32/f_{MCK}		ns
			16 MHz < f_{MCK} ≤ 20 MHz	28/f_{MCK}		ns
			8 MHz < f_{MCK} ≤ 16 MHz	24/f_{MCK}		ns
			4 MHz < f_{MCK} ≤ 8 MHz	16/f_{MCK}		ns
			f_{MCK} ≤ 4 MHz	12/f_{MCK}		ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V	20 MHz < f_{MCK} ≤ 24 MHz	72/f_{MCK}		ns
			16 MHz < f_{MCK} ≤ 20 MHz	64/f_{MCK}		ns
			8 MHz < f_{MCK} ≤ 16 MHz	52/f_{MCK}		ns
			4 MHz < f_{MCK} ≤ 8 MHz	32/f_{MCK}		ns
			f_{MCK} ≤ 4 MHz	20/f_{MCK}		ns
SCKp high-/low-level width	t_{KH2}, t_{KL2}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V		t_{KCY2}/2 – 24		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V		t_{KCY2}/2 – 36		ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V		t_{KCY2}/2 – 100		ns
SIp setup time (to SCKp↑) Note 2	t_{SIK2}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V		1/f_{MCK} + 40		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V		1/f_{MCK} + 40		ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V		1/f_{MCK} + 60		ns
SIp hold time (from SCKp↑) Note 3	t_{KSI2}			1/f_{MCK} + 62		ns
Delay time from SCKp↓ to SOp output Note 4	t_{KSO2}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 30 pF, R_b = 1.4 kΩ			2/f_{MCK} + 240	ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 30 pF, R_b = 2.7 kΩ			2/f_{MCK} + 428	ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 30 pF, R_b = 5.5 kΩ			2/f_{MCK} + 1146	ns

Notes 1. Transfer rate in the SNOOZE mode: MAX. 1 Mbps

2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

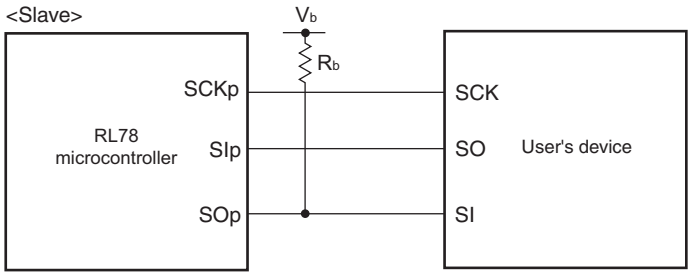
4. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp↑" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.

Cautions 1. **Select the TTL input buffer for the SIp pin and SCKp pin, and the N-ch open drain output (V_{DD} tolerance) mode for the SOp pin by using port input mode register 1 (PIM1) and port output mode register 1 (POM1). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.**

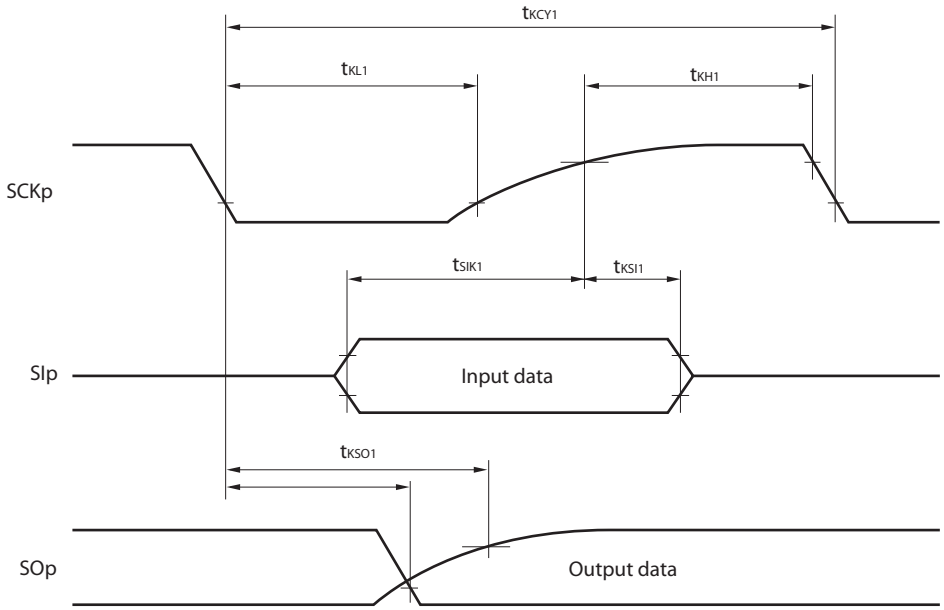
2. **Communication at different potential is not allowed in CSI01, CSI11.**

(Remarks **are listed on the next page.)**

CSI mode connection diagram (during communication at different potential)



CSI mode serial transfer timing (slave mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)

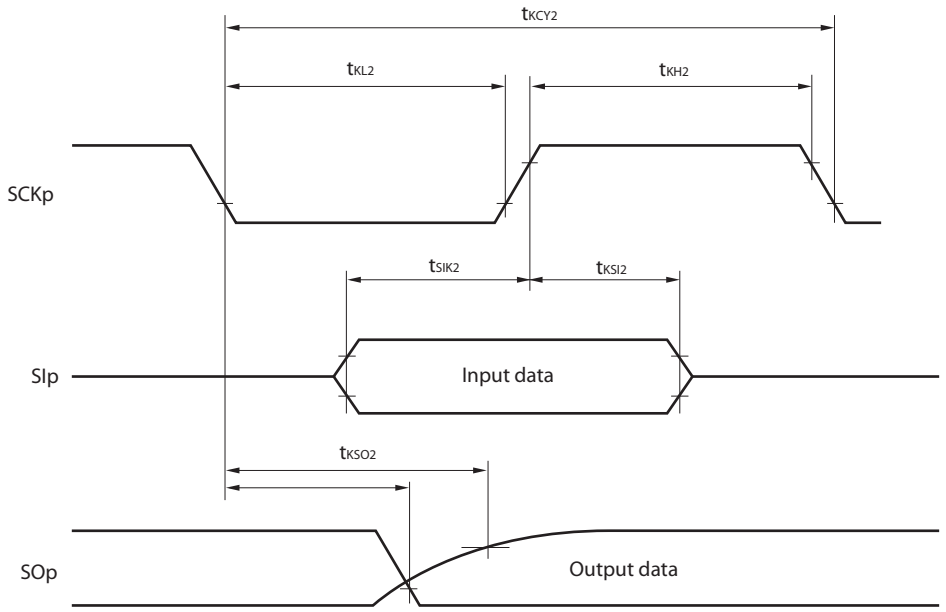


Remarks 1. R_b [Ω]: Communication line (SOp) pull-up resistance, C_b [F]: Communication line (SOp) load capacitance, V_b [V]: Communication line voltage

2. p: CSI number (p = 00, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0)

3. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn), and the Serial clock select register m (SPSm). m: Unit number, n: Channel number (mn = 00, 10))

CSI mode serial transfer timing (slave mode) (during communication at different potential)
(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



Remark p: CSI number (p = 00, 20), m: Unit number (m = 0, 1), n: Channel number (n = 0)

(8) Communication at different potential (1.8 V, 2.5 V, 3 V) (simplified I^2C mode)

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		Unit
			MIN.	MAX.	
SCLr clock frequency	f_{SCL}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 100 pF, R_b = 2.8 kΩ		100 Note1	kHz
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 100 pF, R_b = 2.7 kΩ		100 Note1	kHz
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 100 pF, R_b = 5.5 kΩ		100 Note1	kHz
Hold time when SCLr = "L"	t_{LOW}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 100 pF, R_b = 2.8 kΩ	4600		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 100 pF, R_b = 2.7 kΩ	4600		ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 100 pF, R_b = 5.5 kΩ	4650		ns
Hold time when SCLr = "H"	t_{HIGH}	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 100 pF, R_b = 2.8 kΩ	2700		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 100 pF, R_b = 2.7 kΩ	2400		ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 100 pF, R_b = 5.5 kΩ	1830		ns
Data setup time (reception)	$t_{SU:DAT}$	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 100 pF, R_b = 2.8 kΩ	1/f_{MCK} + 760 Note2		ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 100 pF, R_b = 2.7 kΩ	1/f_{MCK} + 760 Note2		ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 100 pF, R_b = 5.5 kΩ	1/f_{MCK} + 570 Note2		ns
Data setup time (transmission)"	$t_{HD:DAT}$	4.0 V ≤ V_{DD} ≤ 5.5 V, 2.7 V ≤ V_b ≤ 4.0 V, C_b = 100 pF, R_b = 2.8 kΩ	0	1420	ns
		2.7 V ≤ V_{DD} < 4.0 V, 2.3 V ≤ V_b ≤ 2.7 V, C_b = 100 pF, R_b = 2.7 kΩ	0	1420	ns
		2.4 V ≤ V_{DD} < 3.3 V, 1.6 V ≤ V_b ≤ 2.0 V, C_b = 100 pF, R_b = 5.5 kΩ	0	1215	ns

Notes 1. The value must also be equal to or less than f_{MCK}/4.

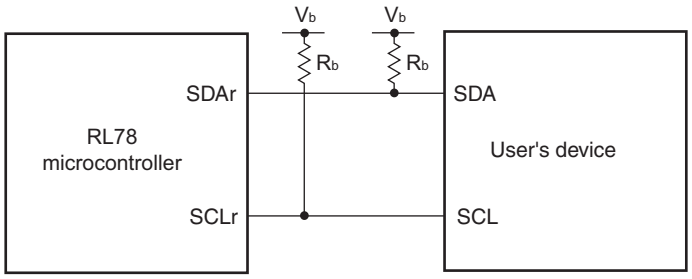
2. Set the $t_{SU:DAT}$ value to keep the hold time of SCLr = "L" and SCLr = "H".

Cautions **1.** Select the TTL input buffer and the N-ch open drain output (VDD tolerance) mode for the SDAr pin and the N-ch open drain output (VDD tolerance) mode for the SCLr pin by using port input mode register 1 (PIM1) and port output mode register 1 (POM1). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

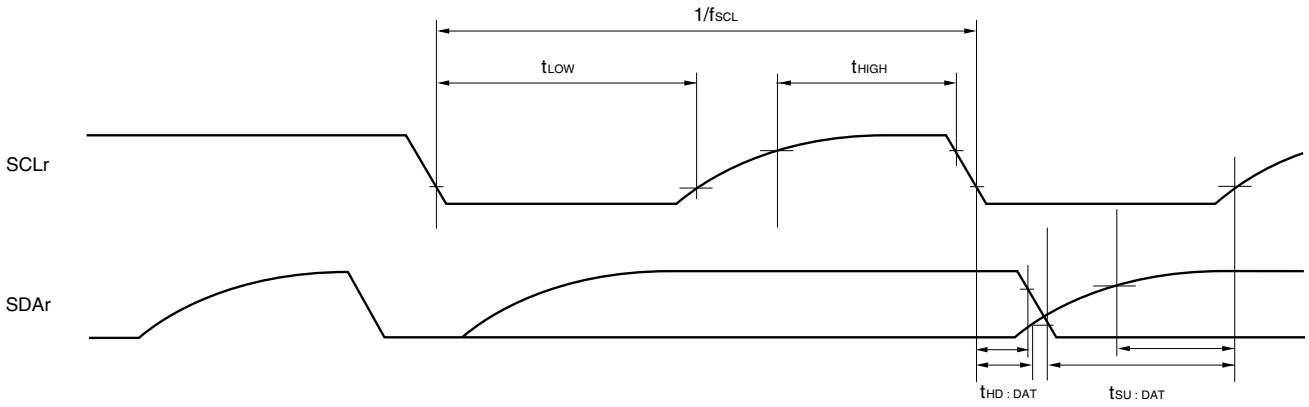
2. **Communication at different potential is not allowed in IIC01, IIC11.**

(**Remarks** are listed on the next page.)

Simplified I^2C mode connection diagram (during communication at different potential)



Simplified I^2C mode serial transfer timing (during communication at different potential)



Remarks 1. R_b [Ω]: Communication line (SDAr, SCLr) pull-up resistance, C_b [F]: Communication line (SDAr, SCLr) load capacitance, V_b [V]: Communication line voltage

2. r: IIC Number (r = 00, 20)

3. f_{MCK}: Serial array unit operation clock frequency
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn), and the Serial clock select register m (SPSm). m: Unit number (m = 0,1), n: Channel number (n = 0))

29.5.2 Serial interface IICA

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	HS (high-speed main) Mode				Unit
			Standard Mode		Fast Mode		
			MIN.	MAX.	MIN.	MAX.	
SCLA0 clock frequency	f_{SCL}	Fast mode: f_{CLK} ≥ 3.5 MHz			0	400	kHz
		Normal mode: f_{CLK} ≥ 1 MHz	0	100			kHz
Setup time of restart condition	$t_{SU:STA}$		4.7		0.6		μs
Hold time Note 1	$t_{HD:STA}$		4.0		0.6		μs
Hold time when SCLA0 = “L”	t_{LOW}		4.7		1.3		μs
Hold time when SCLA0 = “H”	t_{HIGH}		4.0		0.6		μs
Data setup time (reception)	$t_{SU:DAT}$		250		100		ns
Data hold time (transmission) Note 2	$t_{HD:DAT}$		0	3.45	0	0.9	μs
Setup time of stop condition	$t_{SU:STO}$		4.0		0.6		μs
Bus-free time	t_{BUF}		4.7		1.3		μs

Notes 1. The first clock pulse is generated after this period when the start/restart condition is detected.

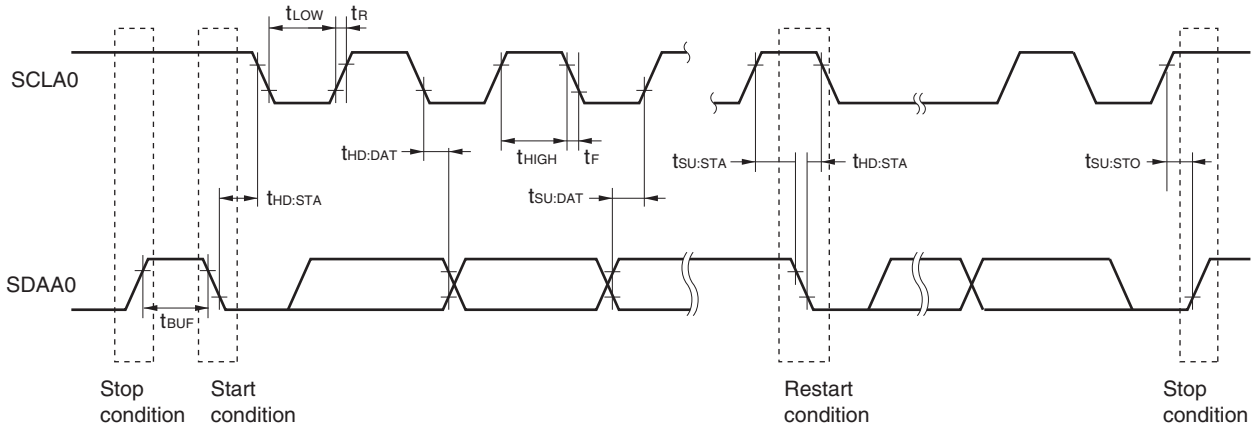
2. The maximum value (MAX.) of $t_{HD:DAT}$ is during normal transfer and a wait state is inserted in the $\overline{ACK}$ (acknowledge) timing.

Caution The values in the above table are applied even when bit 2 (PIOR2) in the peripheral I/O redirection register (PIOR) is 1 in 30-pin products only. At this time, the pin characteristics (I_{OH1}, I_{OL1}, V_{OH1}, V_{OL1}) must satisfy the values in the redirect destination.

Remark The maximum value of C_b (communication line capacitance) and the value of R_b (communication line pull-up resistor) at that time in each mode are as follows.

Normal mode: C_b = 400 pF, Rb = 2.7 kΩ
Fast mode: C_b = 320 pF, Rb = 1.1 kΩ

IICA serial transfer timing



29.6 Analog Characteristics

29.6.1 A/D converter characteristics

Classification of A/D converter characteristics

Input channel	Reference Voltage		
	Reference voltage (+) = AV_{REFP} Reference voltage (–) = AV_{REFM}	Reference voltage (+) = V_{DD} Reference voltage (–) = V_{SS}	Reference voltage (+) = V_{BGR} Reference voltage (–) = AV_{REFM}
ANI0 to ANI3	Refer to **29.6.1 (1)**.	Refer to **29.6.1 (3)**.	Refer to **29.6.1 (4)**.
ANI16 to ANI22	Refer to **29.6.1 (2)**.		
Internal reference voltage Temperature sensor output voltage	Refer to **29.6.1 (1)**.		–

(1) When reference voltage (+) = AV_{REFP}/ANI0 (ADREFP1 = 0, ADREFP0 = 1), reference voltage (–) = AV_{REFM}/ANI1 (ADREFM = 1), target pin: ANI2, ANI3, internal reference voltage, and temperature sensor output voltage

(T_A = –40 to +105°C, 2.4 V ≤ AV_{REFP} ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, Reference voltage (+) = AV_{REFP}, Reference voltage (–) = AV_{REFM} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error[Note 1]	AINL	10-bit resolution, AV_{REFP} = V_{DD} [Note 3]			1.2	±3.5	LSB
Conversion time	t_{CONV}	10-bit resolution Target pin: ANI2, ANI3	3.6 V ≤ V_{DD} ≤ 5.5 V	2.125		39	μs
			2.7 V ≤ V_{DD} ≤ 5.5 V	3.1875		39	μs
			2.4 V ≤ V_{DD} ≤ 5.5 V	17		39	μs
		10-bit resolution Target pin: Internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	3.6 V ≤ V_{DD} ≤ 5.5 V	2.375		39	μs
			2.7 V ≤ V_{DD} ≤ 5.5 V	3.5625		39	μs
			2.4 V ≤ V_{DD} ≤ 5.5 V	17		39	μs
Zero-scale error[Notes 1, 2]	EZS	10-bit resolution, AV_{REFP} = V_{DD} [Note 3]				±0.25	%FSR
Full-scale error[Notes 1, 2]	EFS	10-bit resolution, AV_{REFP} = V_{DD} [Note 3]				±0.25	%FSR
Integral linearity error[Note 1]	ILE	10-bit resolution, AV_{REFP} = V_{DD} [Note 3]				±2.5	LSB
Differential linearity error [Note 1]	DLE	10-bit resolution, AV_{REFP} = V_{DD} [Note 3]				±1.5	LSB
Analog input voltage	V_{AIN}	ANI2, ANI3		0		AV_{REFP}	V
		Internal reference voltage (HS (high-speed main) mode)		V_{BGR} [Note 4]			V
		Temperature sensor output voltage (HS (high-speed main) mode)		V_{TMPS25} [Note 4]			V

Notes 1. Excludes quantization error (±1/2 LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. When AV_{REFP} < V_{DD}, the MAX. values are as follows.
Overall error: Add ±1.0 LSB to the MAX. value when AV_{REFP} = V_{DD}.
Zero-scale error/Full-scale error: Add ±0.05%FSR to the MAX. value when AV_{REFP} = V_{DD}.
Integral linearity error/ Differential linearity error: Add ±0.5 LSB to the MAX. value when AV_{REFP} = V_{DD}.

4. Refer to **29.6.2 Temperature sensor/internal reference voltage characteristics**.

(2) When reference voltage (+) = AV_{REFP}/ANI0 (ADREFP1 = 0, ADREFP0 = 1), reference voltage (–) = AV_{REFM}/ANI1 (ADREFM = 1), target pin: ANI16 to ANI22

(T_A = –40 to +105°C, 2.4 V ≤ AV_{REFP} ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, Reference voltage (+) = AV_{REFP}, Reference voltage (–) = AV_{REFM} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error Note 1	AINL	10-bit resolution, AV_{REFP} = V_{DD} Note 3			1.2	±5.0	LSB
Conversion time	t_{CONV}	10-bit resolution Target ANI pin: ANI16 to ANI22	3.6 V ≤ V_{DD} ≤ 5.5 V	2.125		39	μs
			2.7 V ≤ V_{DD} ≤ 5.5 V	3.1875		39	μs
			2.4 V ≤ V_{DD} ≤ 5.5 V	17		39	μs
Zero-scale error Notes 1, 2	E_{ZS}	10-bit resolution, AV_{REFP} = V_{DD} Note 3				±0.35	%FSR
Full-scale error Notes 1, 2	E_{FS}	10-bit resolution, AV_{REFP} = V_{DD} Note 3				±0.35	%FSR
Integral linearity error Note 1	ILE	10-bit resolution, AV_{REFP} = V_{DD} Note 3				±3.5	LSB
Differential linearity error Note 1	DLE	10-bit resolution, AV_{REFP} = V_{DD} Note 3				±2.0	LSB
Analog input voltage	V_{AIN}	ANI16 to ANI22		0		AV_{REFP} and V_{DD}	V

Notes 1. Excludes quantization error (±1/2 LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. When AV_{REFP} ≤ V_{DD}, the MAX. values are as follows.
Overall error: Add ±4.0 LSB to the MAX. value when AV_{REFP} = V_{DD}.
Zero-scale error/Full-scale error: Add ±0.20%FSR to the MAX. value when AV_{REFP} = V_{DD}.
Integral linearity error/ Differential linearity error: Add ±2.0 LSB to the MAX. value when AV_{REFP} = V_{DD}.

(3) When reference voltage (+) = V_{DD} (ADREFP1 = 0, ADREFP0 = 0), reference voltage (–) = V_{SS} (ADREFM = 0), target pin: ANI0 to ANI3, ANI16 to ANI22, internal reference voltage, and temperature sensor output voltage

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, Reference voltage (+) = V_{DD}, Reference voltage (–) = V_{SS})

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error[Note 1]	AINL	10-bit resolution			1.2	±7.0	LSB
Conversion time	t_{CONV}	10-bit resolution Target pin: ANI0 to ANI3, ANI16 to ANI22	3.6 V ≤ V_{DD} ≤ 5.5 V	2.125		39	μs
			2.7 V ≤ V_{DD} ≤ 5.5 V	3.1875		39	μs
			2.4 V ≤ V_{DD} ≤ 5.5 V	17		39	μs
Conversion time	t_{CONV}	10-bit resolution Target pin: internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	3.6 V ≤ V_{DD} ≤ 5.5 V	2.375		39	μs
			2.7 V ≤ V_{DD} ≤ 5.5 V	3.5625		39	μs
			2.4 V ≤ V_{DD} ≤ 5.5 V	17		39	μs
Zero-scale error[Notes 1, 2]	E_{ZS}	10-bit resolution				±0.60	%FSR
Full-scale error[Notes 1, 2]	E_{FS}	10-bit resolution				±0.60	%FSR
Integral linearity error[Note 1]	ILE	10-bit resolution				±4.0	LSB
Differential linearity error[Note 1]	DLE	10-bit resolution				±2.0	LSB
Analog input voltage	V_{AIN}	ANI0 to ANI3, ANI16 to ANI22		0		V_{DD}	V
		Internal reference voltage (HS (high-speed main) mode)		V_{BGR} [Note 3]			V
		Temperature sensor output voltage (HS (high-speed main) mode)		V_{TMPS25} [Note 3]			V

Notes 1. Excludes quantization error (±1/2 LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. Refer to **29.6.2 Temperature sensor/internal reference voltage characteristics**.

(4) When reference voltage (+) = Internal reference voltage (ADREFP1 = 1, ADREFP0 = 0), reference voltage (–) = AV_{REFM} (ADREFM = 1), target pin: ANI0, ANI2, ANI3, and ANI16 to ANI22

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, Reference voltage (+) = V_{BGR} Note 3, Reference voltage (–) = AV_{REFM} Note 4 = 0 V, HS (high-speed main) mode)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Resolution	RES			8		bit
Conversion time	t_{CONV}	8-bit resolution	17		39	μs
Zero-scale error Notes 1, 2	E_{ZS}	8-bit resolution			±0.60	%FSR
Integral linearity error Note 1	ILE	8-bit resolution			±2.0	LSB
Differential linearity error Note 1	DLE	8-bit resolution			±1.0	LSB
Analog input voltage	V_{AIN}		0		V_{BGR} Note 3	V

Notes 1. Excludes quantization error (±1/2 LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. Refer to **29.6.2 Temperature sensor/internal reference voltage characteristics**.

4. When reference voltage (–) = V_{SS}, the MAX. values are as follows.
Zero-scale error: Add ±0.35%FSR to the MAX. value when reference voltage (–) = AV_{REFM}.
Integral linearity error: Add ±0.5 LSB to the MAX. value when reference voltage (–) = AV_{REFM}.
Differential linearity error: Add ±0.2 LSB to the MAX. value when reference voltage (–) = AV_{REFM}.

29.6.2 Temperature sensor characteristics

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V, HS (high-speed main) mode

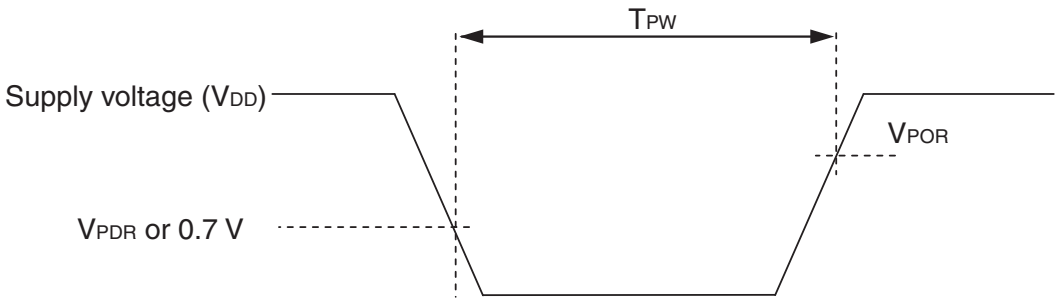
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Temperature sensor output voltage	V_{TMPS25}	Setting ADS register = 80H, T_A = +25°C		1.05		V
Reference output voltage	V_{BGR}	Setting ADS register = 81H	1.38	1.45	1.50	V
Temperature coefficient	F_{VTMPS}	Temperature sensor output voltage that depends on the temperature		–3.6		mV/°C
Operation stabilization wait time	t_{AMP}		5			μs

29.6.3 POR circuit characteristics

(T_A = –40 to +105°C, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	V_{POR}	Power supply rise time	1.45	1.51	1.57	V
	V_{PDR}	Power supply fall time	1.44	1.50	1.56	V
Minimum pulse width Note	T_{PW}		300			μs

Note Minimum time required for a POR reset when V_{DD} exceeds below V_{PDR}. This is also the minimum time required for a POR reset from when V_{DD} exceeds below 0.7 V to when V_{DD} exceeds V_{POR} while STOP mode is entered or the main system clock is stopped through setting bit 0 (HIOSTOP) and bit 7 (MSTOP) in the clock operation status control register (CSC).



29.6.4 LVD circuit characteristics

LVD Detection Voltage of Reset Mode and Interrupt Mode

(T_A = –40 to +105°C, $V_{PDR} \le V_{DD} \le 5.5$ V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection supply voltage	V_{LVD0}	Power supply rise time	3.90	4.06	4.22	V
		Power supply fall time	3.83	3.98	4.13	V
	V_{LVD1}	Power supply rise time	3.60	3.75	3.90	V
		Power supply fall time	3.53	3.67	3.81	V
	V_{LVD2}	Power supply rise time	3.01	3.13	3.25	V
		Power supply fall time	2.94	3.06	3.18	V
	V_{LVD3}	Power supply rise time	2.90	3.02	3.14	V
		Power supply fall time	2.85	2.96	3.07	V
	V_{LVD4}	Power supply rise time	2.81	2.92	3.03	V
		Power supply fall time	2.75	2.86	2.97	V
	V_{LVD5}	Power supply rise time	2.70	2.81	2.92	V
		Power supply fall time	2.64	2.75	2.86	V
	V_{LVD6}	Power supply rise time	2.61	2.71	2.81	V
		Power supply fall time	2.55	2.65	2.75	V
	V_{LVD7}	Power supply rise time	2.51	2.61	2.71	V
		Power supply fall time	2.45	2.55	2.65	V
Minimum pulse width	t_{LW}		300			μs
Detection delay time					300	μs

LVD detection voltage of interrupt & reset mode

(T_A = –40 to +105°C, $V_{PDR} \le V_{DD} \le 5.5$ V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Interrupt and reset mode	V_{LVDD0}	V_{POC2}, V_{POC1}, V_{POC1} = 0, 1, 1, falling reset voltage		2.64	2.75	2.86	V
	V_{LVDD1}	LVIS1, LVIS0 = 1, 0	Rising reset release voltage	2.81	2.92	3.03	V
			Falling interrupt voltage	2.75	2.86	2.97	V
	V_{LVDD2}	LVIS1, LVIS0 = 0, 1	Rising reset release voltage	2.90	3.02	3.14	V
			Falling interrupt voltage	2.85	2.96	3.07	V
	V_{LVDD3}	LVIS1, LVIS0 = 0, 0	Rising reset release voltage	3.90	4.06	4.22	V
			Falling interrupt voltage	3.83	3.98	4.13	V

29.6.5 Power supply voltage rising slope characteristics

(T_A = –40 to +105°C, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Power supply voltage rising slope	S_{VDD}				54	V/ms

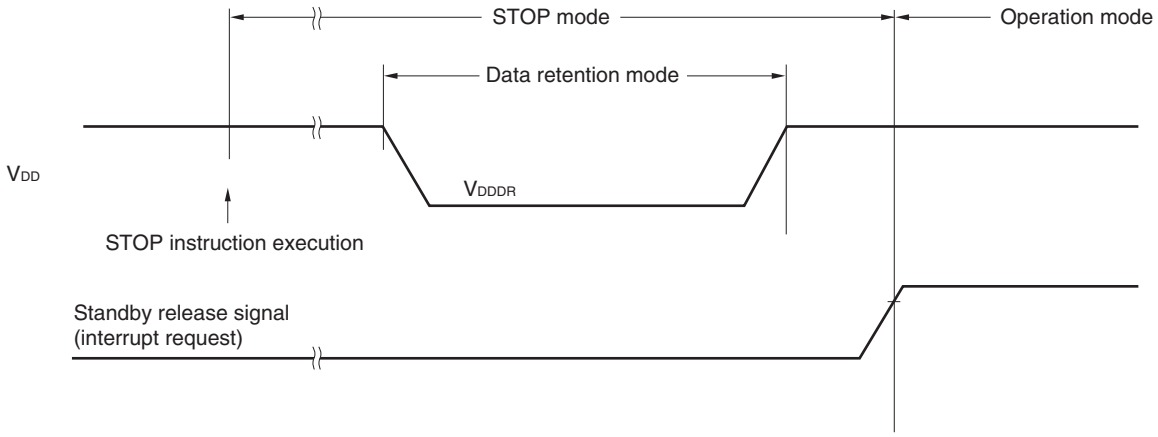
Caution Make sure to keep the internal reset state by the LVD circuit or an external reset until V_{DD} reaches the operating voltage range shown in 29.4 AC Characteristics.

29.7 Data Memory STOP Mode Low Supply Voltage Data Retention Characteristics

(T_A = –40 to +105°C, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Data retention supply voltage	V_{DDDR}		1.44 Note		5.5	V

Note The value depends on the POR detection voltage. When the voltage drops, the data is retained before a POR reset is affected, but data is not retained when a POR reset is affected.



29.8 Flash Memory Programming Characteristics

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
System clock frequency	f_{CLK}			1		24	MHz
Code flash memory rewritable times Notes 1, 2, 3	C_{erwr}	Retained for 20 years	T_A = 85°C	1,000			Times
Data flash memory rewritable times Notes 1, 2, 3		Retained for 1 year	T_A = 25°C		1,000,000		
		Retained for 5 years	T_A = 85°C	100,000			
		Retained for 20 years	T_A = 85°C	10,000			

Notes 1. 1 erase + 1 write after the erase is regarded as 1 rewrite. The retaining years are a period of time in which the next rewrite is performed after a rewrite.

2. When using flash memory programmer or library program from Renesas

3. This shows the flash memory characteristics. This is a result obtained from Renesas Electronics reliability test.

29.9 Dedicated Flash Memory Programmer Communication (UART)

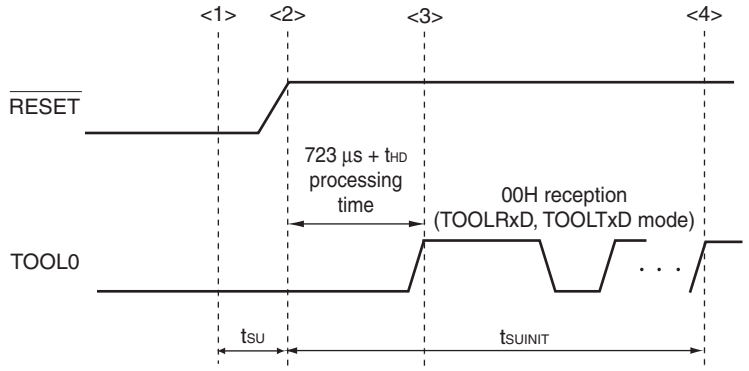
(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Transfer rate		During serial programming	115,200		1,000,000	bps

29.10 Timing Specs for Switching Flash Memory Programming Modes

(T_A = –40 to +105°C, 2.4 V ≤ V_{DD} ≤ 5.5 V, V_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
How long from when an external reset ends until the initial communication settings are specified	t_{SUINIT}	POR and LVD reset must end before the external reset ends.			100	ms
How long from when the TOOL0 pin is placed at the low level until an external reset ends	t_{su}	POR and LVD reset must end before the external reset ends.	10			μs
How long the TOOL0 pin must be kept at the low level after an external reset ends (excluding the processing time of the firmware to control the flash memory)	t_{HD}	POR and LVD reset must end before the external reset ends.	1			ms



<1> The low level is input to the TOOL0 pin.

<2> The external reset ends (POR and LVD reset must end before the external reset ends.).

<3> The TOOL0 pin is set to the high level.

<4> Setting of the flash memory programming mode by UART reception and complete the baud rate setting.

Remark t_{SUINIT}: The segment shows that it is necessary to finish specifying the initial communication settings within 100 ms from when the resets end.

t_{SU}: How long from when the TOOL0 pin is placed at the low level until an external reset ends.

t_{HD}: How long to keep the TOOL0 pin at the low level from when the external reset ends. (excluding the processing time of the firmware to control the flash memory)